

## WIDEBAND QUAD DIGITAL DOWN-CONVERTER/UP-CONVERTER

### FEATURES

- **Four Independently Configurable Wideband Down-Converter or Up-Converter Channels**
  - Four Channel Down Convert Mode
  - Four Channel Up Convert Mode
  - Two Channels Down and Two Channels Up Mode
- **Down-Conversion Channel Mode**
  - Input Rates to 160-MSPS for Four Channels, 320-MSPS for Two Channels in Double Rate Mode
  - Four Wideband Down-Conversion Channels Support UMTS Standards
  - 115-dB SFDR
  - FIR Filter Block Consists of 16 Cells Providing Up to 256 Taps Per Channel
  - 64 Parallel Input Bits and 64 Parallel Output Bits Provide Flexible I/O Options
  - Many Multiplex Output Options
- **Up-Conversion Channel Mode**
  - Output Rates to 160-MSPS for Four Channels, 320-MSPS for Two Channels
  - Four Up-Conversion Channels Support UMTS Standards
- FIR Filter Block Consists of 16 Cells Providing up to 256 Taps Per Channel
- 64 Parallel Input Bits and 64 Parallel Output Bits Provide Flexible I/O Options
- Multiple Real and Complex Outputs
- Two Channel Double Rate Real Output Mode With Rates to 320 MSPS
- Outputs Can Be Independent, Summed Into Two or One Output(s), and Optionally Merged With Multiple GC5016 Chips
- JTAG Boundary Scan
- 3.3-V I/O, 1.8-V Core
- Power Dissipation: <1 W for Four Channels
- Package: 252-Ball, 17-mm PBGA, 1-mm Pitch

### APPLICATIONS

- Cellular Base Transceiver Station Transmit and Receive Channels
  - WCDMA
  - CDMA2000
- Radar
- General Filtering
- Test and Measurement

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## 1 DESCRIPTION

The GC5016 is a flexible wideband 4-channel digital up-converter and down-converter. The GC5016 is designed for high-speed, high bandwidth digital signal processing applications like 3G cellular base transceiver station transmit and receive channels. The GC5016 is also applicable for general-purpose digital filtering applications. The four identical processing channels can be independently configured for up-conversion, down-conversion, or a combination of two up-conversion and two down-conversion channels.

In up-conversion mode, the channel accepts real or complex signals, interpolates them by programmable amounts ranging from 1 to 4096, and modulates them up to selected center frequencies. The 4 digital up-converter signals can be output individually, summed together on one or two outputs on a single GC5016, or optionally summed between multiple GC5016s. Channels can be used in pairs to increase the output sample rate, to increase filtering capacity, to increase the input bandwidth, or any combination. Each channel contains a user programmable input filter (PFIR), which can be used to shape the transmitted signal's spectrum or as a Nyquist transmit filter for shaping digital data such as QPSK, GMSK, or QAM symbols.

In down-conversion mode, the channel accepts real or complex signals, demodulates them from selected carrier frequencies, decimates them by programmable amounts ranging from 1 to 4096, applies a gain from a user defined automatic gain control, and produces 20-bit outputs. The frequencies and phase offsets of the four sine/cosine sequence generators can be independently specified, as can the decimation and filtering of each circuit. Channels can be synchronized to support beam forming or frequency hopped systems. The output from the down-conversion channel is formatted and output in up to four output ports as either real or complex data.

## 2 ORDERING INFORMATION

PART NAME	TEMPERATURE	PACKAGE	DESCRIPTION
GC5016-PB	-40°C to 85°C	GDJ (S-PBGA-N252)	252 ball PBGA
GC5016-PBZ	-40°C to 85°C	ZDJ (S-PBGA-N252)	252 ball lead free PBGA

## 3 OTHER REFERENCE MATERIALS

The TI Web site has developer toolkit and application notes that provide application specific programming and configuration information. The CMD5016 configuration program, along with a user specified source and tap coefficient file, is used to configure the GC5016 registers. The GC5016 register settings are intended to be configured through the development toolkit software.

**NOTE:**Names in italics refer to parameter inputs to the cmd5016 software configuration program.



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

## 4 ABSOLUTE MAXIMUM RATINGS

over operating free-air temperature range unless otherwise noted<sup>(1)</sup>

		<b>GC5016</b>
Pad ring supply voltage, $V_{PAD}$		-0.3 V to 4 V
Core supply voltage, $V_{CORE}$		-0.3 V to 2.3 V
Input voltage (undershoot and overshoot), $V_{IN}$		-0.5 V to $V_{PAD}+0.5$ V
Storage temperature, $T_{stg}$		-65°C to 150°C
Junction temperature, $T_J$		105°C
Lead soldering temperature (10 seconds)		300°C
ESD classification	Human body model	2 kV
	Machine body model	200 V
	Charged device model	500 V
Moisture sensitivity		Level 3

<sup>(1)</sup> Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

## 5 RECOMMENDED OPERATING CONDITIONS

	<b>MIN</b>	<b>MAX</b>	<b>UNITS</b>
Pad ring supply voltage, $V_{PAD}$	3	3.6	V
Core supply voltage, $V_{CORE}$	1.6	2	V
Temperature ambient, no air flow, $T_A$ <sup>(1)</sup>	-40	85	°C
Junction temperature, $T_J$ <sup>(2)</sup>		105	°C

<sup>(1)</sup> Chips specifications in the *AC CHARACTERISTICS* and *DC CHARACTERISTICS* tables are production tested at 100°C case temperature. QA tests are performed at 85°C case temperature.

<sup>(2)</sup> Thermal management may be required for full rate operation (see the *THERMAL CHARACTERISTICS* table). The circuit is designed for junction temperatures up to 125°C. Sustained operation at elevated temperatures reduces long-term reliability. Lifetime calculations based on maximum junction temperature of 105°C.

## 6 DC CHARACTERISTICS

-40°C to 85°C case temperature unless otherwise noted

PARAMETER		$V_{PAD} = 3$ V to 3.6 V			UNIT
		MIN	TYP	MAX	
$V_{IL}$	Voltage input low <sup>(1)</sup>			0.8	V
$V_{IH}$	Voltage input high <sup>(1)</sup>	2			V
$V_{OL}$	Voltage output low ( $I_{OL} = 2$ mA) <sup>(1)</sup>			0.5	V
$V_{OH}$	Voltage output high ( $I_{OH} = -2$ mA) <sup>(1)</sup>	2.4			V
$ I_{IN} $	Leakage current ( $V_{IN} = 0$ V or $V_{PAD}$ ), inputs or outputs in high-impedance state condition <sup>(1)</sup>			1	μA
$ I_{PU} $	Pullup current ( $V_{IN} = 0$ V) (TDI, TMS, TCK) <sup>(1)</sup>	5		35	μA
$I_{CCQ}$	Quiescent supply current, $I_{CORE}$ or $I_{PAD}(V_{IN}=0$ or $V_{PAD}, \overline{RST} = \overline{TRST} = 0)$ <sup>(1)</sup>			4	mA
$C_{IN}$	Data input capacitance (all inputs except CK) <sup>(2)</sup>		4		pF
$C_{CK}$	Clock input capacitance (CK input) <sup>(2)</sup>		13		pF

<sup>(1)</sup> Each part is tested with a 100°C case temperature for the given specification.

<sup>(2)</sup> Controlled by design and process and not directly tested.

NOTE: General: Voltages are measured at low speed. Output voltages are measured with the indicated current load.

General: Currents are measured at nominal voltages, high temperature (100°C for production test, 85°C for QA).

## 7 AC CHARACTERISTICS

–40°C to 85°C case, supplies across recommended range unless otherwise noted

PARAMETER		MIN	MAX	UNITS
f <sub>CK</sub>	Clock frequency (1)	(3)	160	MHz
t <sub>CKL</sub>	Clock low period (below V <sub>IL</sub> ) (1)	2		ns
t <sub>CKH</sub>	Clock high period (above V <sub>IH</sub> ) (1)	2		ns
t <sub>r</sub> , t <sub>f</sub>	Clock rise and fall times (V <sub>IL</sub> to V <sub>IH</sub> ) (4)		2	ns
t <sub>su</sub>	Input set up before CK goes high (AI, BI, CI, DI, $\overline{\text{SIA}}$ , or $\overline{\text{SIB}}$ ) (1)	2		ns
t <sub>h</sub>	Input hold time after CK goes high (1)	0.5		ns
t <sub>d</sub>	Data output delay from rising edge of CK. (AO, BO, CO, DO, IFLG, [A–D]FS, [A–D]CK, or SO) (1)		4	ns
t <sub>h(o)</sub>	Data output hold from rising edge of CK (1)	1		ns
f <sub>JCK</sub>	JTAG clock frequency (1)		40	MHz
t <sub>JCKL</sub>	JTAG clock low period (below V <sub>IL</sub> ) (1)	10		ns
t <sub>JCKH</sub>	JTAG clock high period (above V <sub>IH</sub> ) (1)	10		ns
t <sub>su(J)</sub>	JTAG input (TDI or TMS) set up before TCK goes high (1)	1		ns
t <sub>h(J)</sub>	JTAG input (TDI or TMS) hold time after TCK goes high (1)	10		ns
t <sub>d(J)</sub>	JTAG output (TDO) delay from falling edge of TCK (1)		10	ns
t <sub>su(C)</sub>	Control setup during reads or writes. (1)(5)	2		ns
t <sub>su(EWC)</sub>	Control data setup during writes (normal mode). (1)(5)	4		ns
t <sub>h(C)</sub>	Control hold during writes. (1)(5)	1		ns
t <sub>CSPW</sub>	Control strobe ( $\overline{\text{CE}}$ and $\overline{\text{WR}}$ low) pulse width (write operation). (1)(5)	20		ns
t <sub>d(C)</sub>	Control output delay $\overline{\text{CE}}$ and $\overline{\text{RD}}$ low and A stable to C (read operation). (1)(5)		12	ns
t <sub>REC</sub>	Control recovery time between reads or writes. (1)(5)	20		ns
t <sub>(CZ)</sub>	End of read to HI-Z (2)(5)		5	ns
I <sub>C(DYN)</sub>	Core dynamic supply current nominal voltages, 100 MHz, four channels active, full length filters, high temperature. (6)		420	mA

(1) Each part is tested with a 100°C case temperature for the given specification. Lots are sample tested at –40°C.

(2) Controlled by design and process and not directly tested.

(3) The minimum clock rate is calculated in the cmd5016 configuration program. It may be estimated by  $(1 + n_{cic} - n_{fir}) \times 200$  kHz.

(4) Recommended practice

(5) See Figure 27 through Figure 32.

(6) Each port is tested with a 100°C case temperature for the given specification.

General: Timing is measured from CK at VPAD/2 to input or output at VPAD/2. Output loading is a 50-Ω transmission line whose delay is calibrated out.

## 8 THERMAL CHARACTERISTICS

THERMAL CONDUCTIVITY	252 BGA	UNITS
	1 W	
Theta junction to ambient, $\theta_{JA}$	22	°C/W
Theta junction to case, $\theta_{JC}$	5	°C/W

NOTE: Air flow reduces  $\theta_{JA}$  and is highly recommended.

## 9 POWER CONSUMPTION

The maximum power consumption depends on the operating mode of the chip. The following equation estimates the typical power supply current for the chip. Chip-to-chip variation is typically  $\pm 5\%$ . The AC Characteristics provides the production test limit for current in a maximum configuration. It is 10% over the typical value.

$$I_{core} = (f_{CK}/100 \text{ MHz}) (V_{core}/1.8 \text{ V}) (\text{Number\_of\_Active\_Channels}/4) (0.75 + \text{FIRDutyCycle}) 220 \text{ mA}$$

The FIRDutyCycle is calculated in the cmd5016 programming software. The '.ANL' extension of the user programming file contains the power analysis value.. It can be estimated by:

Down Converter Mode:

$$\begin{aligned} \text{FIRDutyCycle} &= 1 \text{ for } f_{CK}/F_{out} \leq 16 \\ &16 \times F_{out}/f_{CK} \text{ otherwise} \end{aligned}$$

Up Converter Mode:

$$\begin{aligned} \text{FIRDutyCycle} &= 1 \text{ for } f_{CK}/F_{in} \leq 32 \\ &32 \times F_{in}/f_{CK} \text{ otherwise} \end{aligned}$$

Current consumption on the pad supply is primarily due to the external loads and follows  $C \times V \times F$ . Internal loads are estimated at 2 pF per pin. Data outputs transition from a zero to a one once per four clocks, while clock outputs transition every cycle. The frame strobes consume negligible power due to the low transition frequency. In general:

$$I_{pad} = \Sigma \text{DataPad}/4 \times C \times F \times V + \Sigma \text{ClockPad} \times C \times F \times V$$

Typically loads are 20 pF per pin. A worst case current would be all four output ports operating at 125 MHz and the four output clocks with [A–D]CK active at 125 MHz.

$$I_{pad} = (64/4 + 4) \times (C+2\text{pF}) \times F_{out} \times V_{pad} = 20 \times 22 \text{ pF} \times 125 \text{ MHz} \times 3.3 \text{ V} = 180 \text{ mA}$$

## 10 Functional Block Diagram

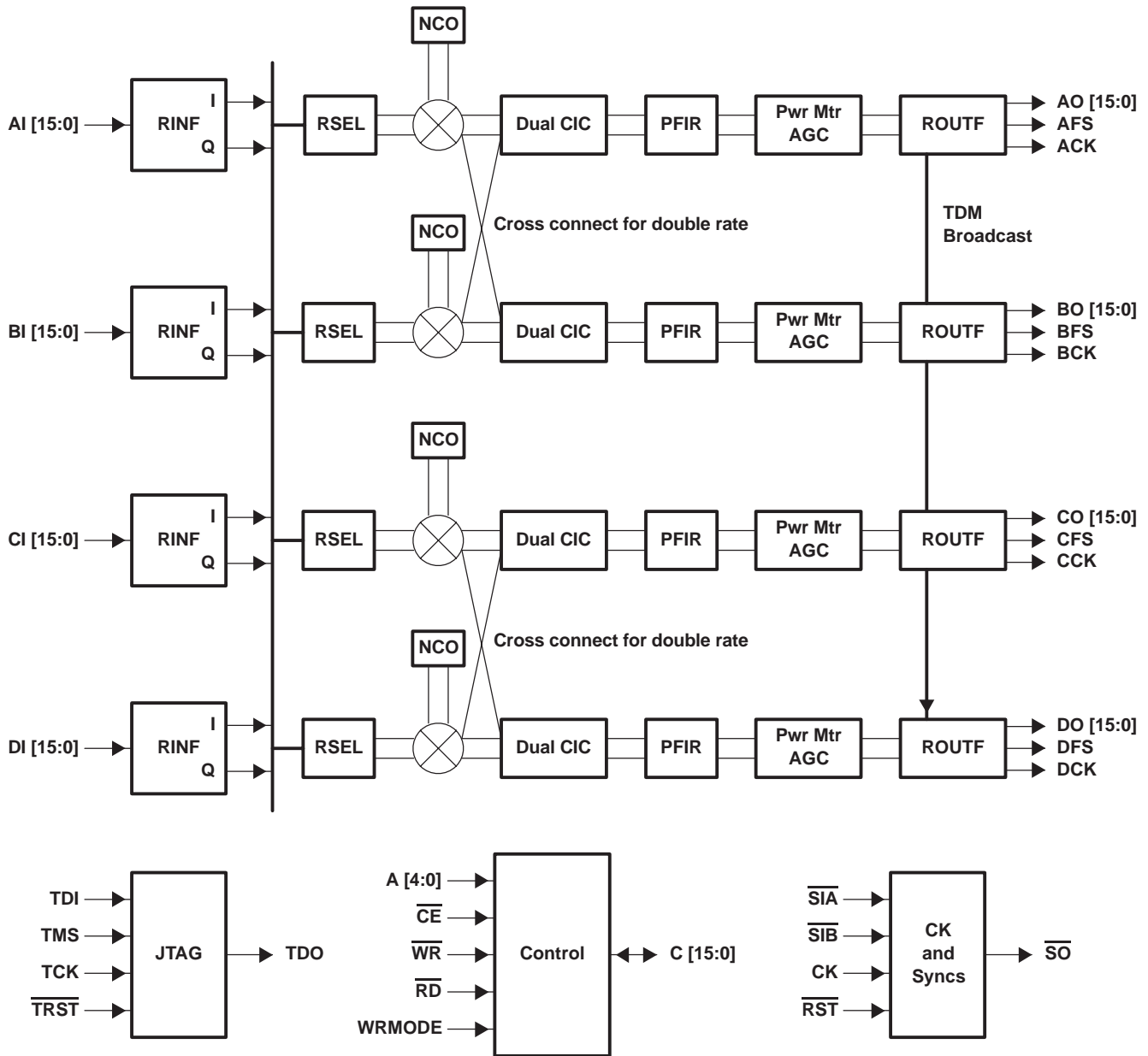
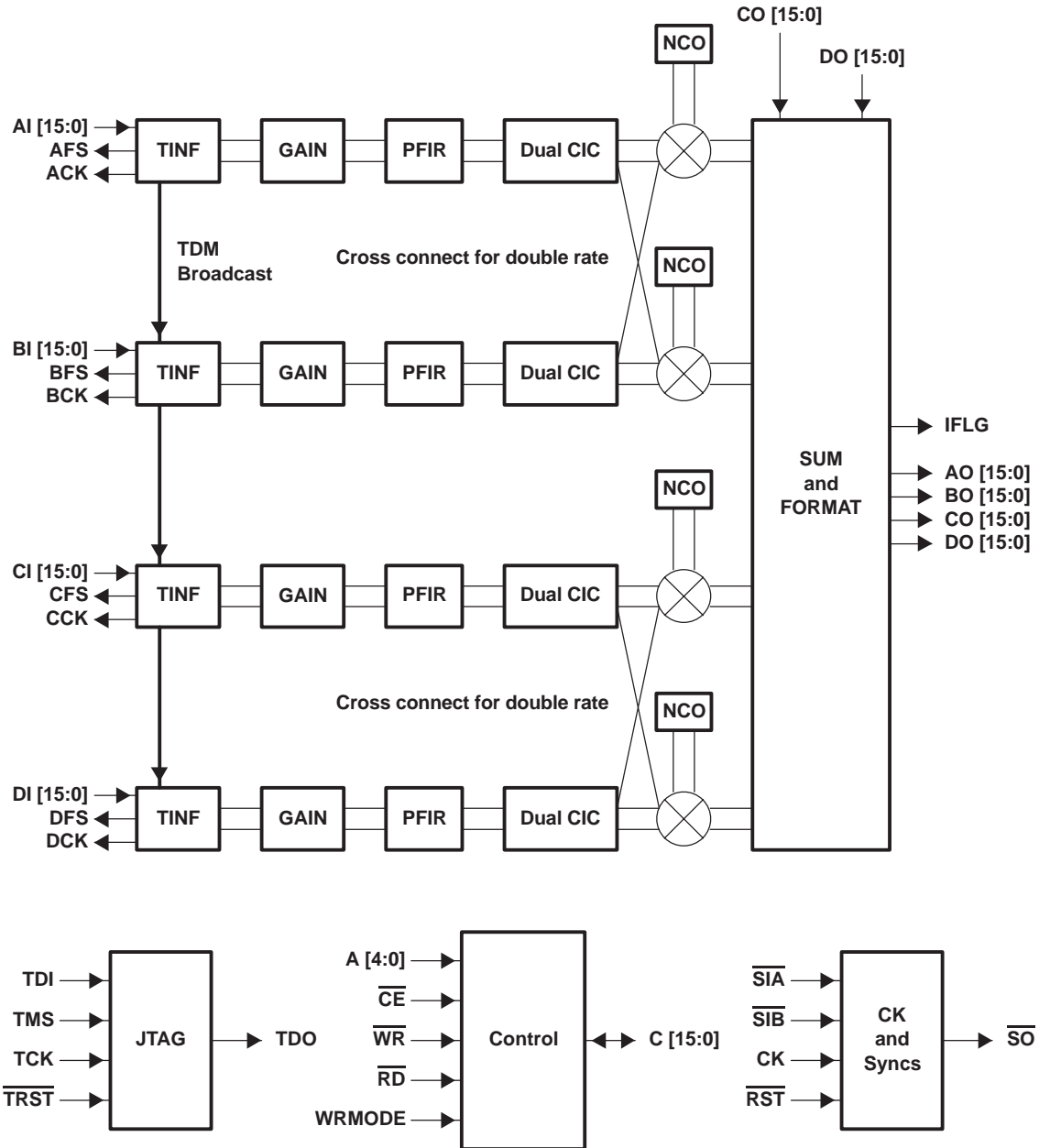


Figure 1. GC5016 in Digital Down-Conversion Mode



**Figure 2. GC5016 in Digital Up-Conversion Mode**

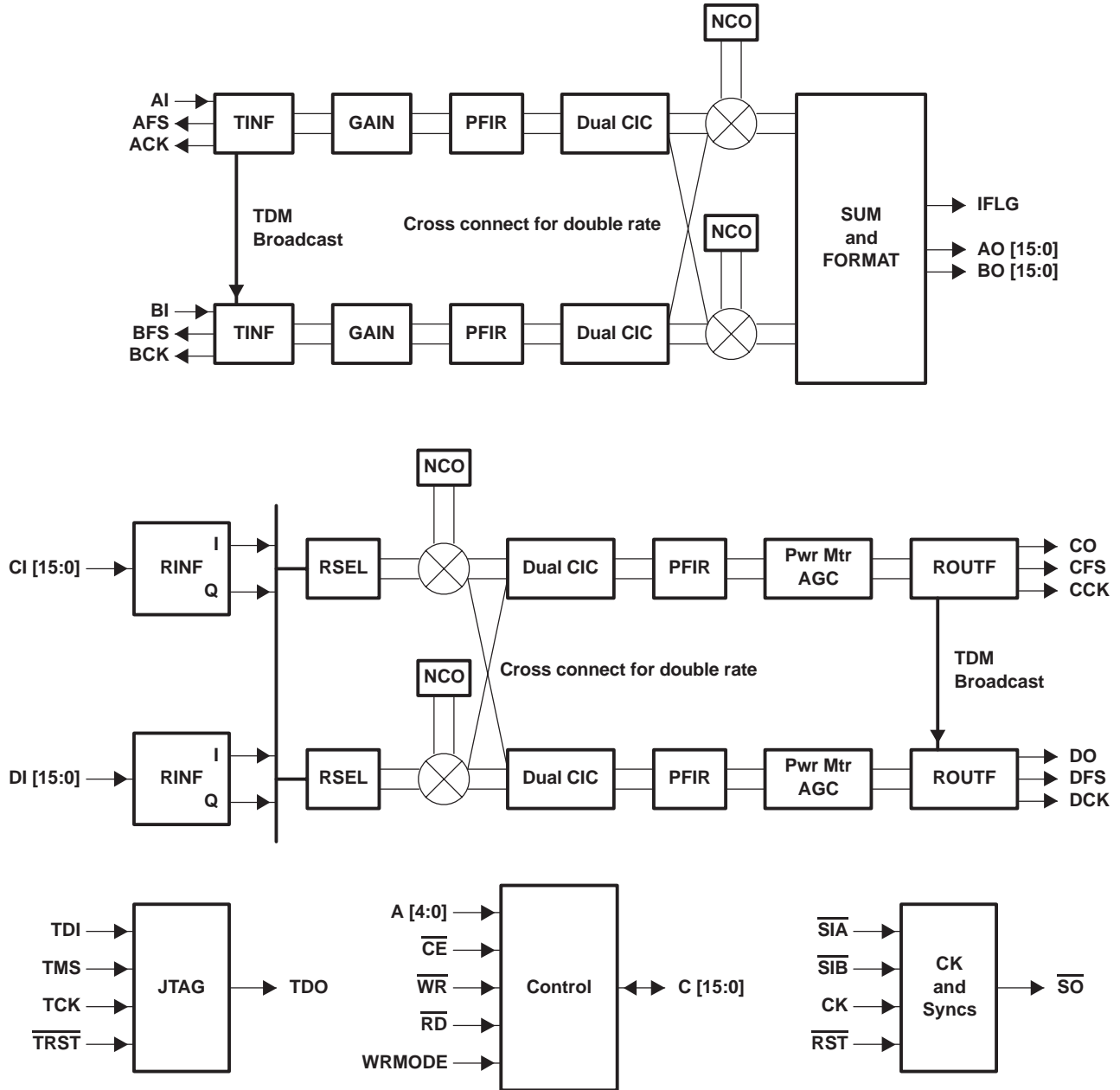


Figure 3. GC5016 in Transceiver Mode



## 11 PIN ASSIGNMENTS

	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16
<b>A</b>	GND	BCK	BO14	BO13	AO11	AO10	BO8	GND	GND	AO6	BO4	BO3	AO1	IFLG	TMS	GND
<b>B</b>	AI1	BI0	AO15	AO14	BO11	BO10	AO9	VPAD	VPAD	BO5	AO4	BO2	BO0	TDI	$\overline{\text{TRST}}$	$\overline{\text{RST}}$
<b>C</b>	BI3	BI2	AI0	AFS	BO15	AO12	BO9	AO7	BO6	AO5	AO3	BO1	$\overline{\text{SO}}$	GND	$\overline{\text{SIB}}$	CI15
<b>D</b>	AI5	AI3	AI2	BFS	ACK	AO13	BO12	BO7	AO8	AO2	AO0	TDO	TCK	DI15	DI14	CI13
<b>E</b>	BI6	AI6	BI5	BI1	GND	VPAD	VPAD	VPAD	VPAD	VPAD	VPAD	GND	$\overline{\text{SIA}}$	DI13	DI12	DI11
<b>F</b>	AI8	BI7	AI7	BI4	VCOR	GND	GND	VPAD	VPAD	GND	GND	VCOR	CI14	CI12	CI11	DI10
<b>G</b>	BI9	AI9	BI8	AI4	VCOR	GND	GND	GND	GND	GND	GND	VCOR	CI10	CI9	DI8	CI8
<b>H</b>	GND	AI10	BI11	BI10	VCOR	VCOR	GND	/	/	GND	VCOR	VCOR	DI9	VPAD	DI7	GND
<b>J</b>	GND	BI12	AI12	AI11	VCOR	VCOR	GND	/	/	GND	VCOR	VCOR	DI5	CI7	DI6	GND
<b>K</b>	AI13	BI13	AI14	BI14	VCOR	GND	GND	GND	GND	GND	GND	VCOR	CI5	DI4	CI4	CI6
<b>L</b>	AI15	BI15	CK	A0	VCOR	GND	GND	VPAD	VPAD	GND	GND	VCOR	CCK	DI2	CI3	DI3
<b>M</b>	A1	A2	A3	A4	GND	VPAD	VPAD	VPAD	VPAD	VPAD	VPAD	GND	DFS	CI1	DI1	CI2
<b>N</b>	$\overline{\text{CE}}$	$\overline{\text{RD}}$	WRMODE	C0	C3	C9	C10	DO1	CO2	CO7	CO12	DO13	CO15	DCK	CI0	DI0
<b>P</b>	$\overline{\text{WR}}$	C1	GND	C5	C8	C14	DO2	CO4	DO4	CO6	DO8	CO11	CO13	GND	DO15	CFS
<b>R</b>	C2	C4	C6	C12	C13	DO0	CO3	VPAD	VPAD	DO5	DO7	CO9	DO10	DO12	CO14	DO14
<b>T</b>	GND	C7	C11	C15	CO0	CO1	DO3	GND	GND	CO5	DO6	CO8	DO9	CO10	DO11	GND

/ = No Ball

## 12 TERMINAL FUNCTIONS

Bit 0 is the least significant bit on all buses. All outputs are able to be put into a high-impedance state. JTAG related inputs have pull-ups if an external pulldown is used, it must be less than 500  $\Omega$ . When I and Q are multiplexed, I comes first. All clocked inputs are registered on the rising edge of CK and all clocked outputs are released on the rising edge of CK, except for Jtag output (TDO). It is recommended that TRST have a user controlled pull-down. This input must be a '1' for JTAG testing, and is recommended to be '0' for normal operation.

SIGNAL	TYPE	DESCRIPTION
<b>CONTROL I/O</b>		
A[4..0]	I	Control address bus – Active high inputs These pins are used to address the control registers within the chip. Each of the control registers within the chip are assigned a unique address. A control register can be written to or read from by having the page register set to the appropriate page and then setting A[4..0] to the register's address.
C[15..0]	I/O	Control data I/O bus – Active high bidirectional I/O pins This is the 16-bit <u>control data I/O</u> bus. Control registers are written to or read from through these pins. The chip drives these pins when $\overline{CE}$ is low, $\overline{RD}$ is low, and $\overline{WR}$ is high.
$\overline{CE}$	I	Chip enable – Active low input pin This control strobe enables the read or write operations.
$\overline{WR}$	I	Write enable – Active low input pin The value on the C[15..0] pins is written into the register selected by the A[4..0] and page register when $\overline{WR}$ and $\overline{CE}$ are low.
$\overline{RD}$	I	Read enable – Active low input pin The register selected by A[4..0] and the page register is output on the C[15..0] pins when $\overline{RD}$ and $\overline{CE}$ are low.
<b>DATA I/O</b>		
AI[15..0]	I	Clocked input port A, data bits 0 through 15 Can be configured for many possible input formats.
BI[15..0]	I	Clocked input port B, data bits 0 through 15 Can be configured for many possible input formats.
CI[15..0]	I	Clocked input port C, data bits 0 through 15 Can be configured for many possible input formats.
DI[15..0]	I	Clocked input port D, data bits 0 through 15 Can be configured for many possible input formats.
AO[15..0]	O	Clocked output port A, data bits 0 through 15 Can be configured for many possible output formats.
BO[15..0]	O	Clocked output port B, data bits 0 through 15 Can be configured for many possible output formats.
CO[15..0]	I/O	Dual function: Clocked output – port C, data bits 0 through 15 Can be configured for many possible output formats. Clocked input – Sum IO input data, data bits 0 through 15 Can be configured for many possible input formats.
DO[15..0]	I/O	Dual function: Clocked output – port D, data bits 0 through 15 Can be configured for many possible output formats. Clocked input – sum IO input data, data bits 0 through 15 Can be configured for many possible input formats.
[A..D]CK	O	Clocked output for ports [A..D] The clock for input ports in up-conversion mode and output ports in down-conversion mode. When configured as a transceiver, channels A and B are in up-conversion and channels C and D are in down-conversion mode.
[A..D]FS	O	Clocked output frame strobes for channels A..D Used to signify the beginning of a data frame for each input port in up-conversion mode and output in down-conversion mode. The frame strobes are set high by the GC5016 with the first word in a frame. The frame strobes can be programmed to be sent early.
CK	I	Main input clock. The clock input to the chip.

SIGNAL	TYPE	DESCRIPTION
<b>DATA I/O (CONTINUED)</b>		
IFLG	O	Clocked output A flag used to indicate which samples are real or imaginary in up-conversion mode when I and Q are time multiplexed.
WRMODE	I	A static control input that changes the timing of control writes. Normally tied low. When low control write data must be stable for a setup time ahead and hold time after the end of the write strobe. When high data must be stable for a setup time ahead of the write strobe going active until a hold time after it goes inactive.
$\overline{\text{RST}}$	I	Chip reset bar. Active low signal. Not clocked. $\overline{\text{RST}}$ requires an external pull-up resistor or connection to VCOR Power Monitor "1" is OK.
$\overline{\text{SIA}}$	I	Sync input A bar. Active low data input signal. $\overline{\text{SIA}}$ requires an external pull-up resistor if not used.
$\overline{\text{SIB}}$	I	Sync input B bar. Active low data input signal. $\overline{\text{SIB}}$ requires an external pull-up resistor if not used.
$\overline{\text{SO}}$	O	Sync output bar. Active low data output signal
<b>JTAG I/O</b>		
TCK	I	JTAG clock – Active high input. Internal pullup
TDI	I	JTAG data in – Active high input clocked on TCK rising. Internal pullup
TDO	O	JTAG data out – High-impedance state output clocked on falling edge of TCK.
TMS	I	JTAG interface – Active high input clocked on TCK rising. Internal pullup
$\overline{\text{TRST}}$	I	Asynchronous JTAG reset bar. Internal pullup
<b>SUPPLIES</b>		
GND		Ground
VCOR <sup>(1)</sup>		Core supply voltage. Used to supply the core logic, nominally set to 1.8 V.
VPAD <sup>(1)</sup>		Interface voltage. Used to set the I/O levels for all pins, nominally set at 3.3 V.

(1) The VCore and VPad must both be powered before programming the GC5016 Control Bus. There is no required power sequence. The recommendation is to power VCore before or simultaneously with VPad.

## 13 GC5016 DOWN-CONVERSION MODE

### 13.1 Overview

Figure 1 shows the functional block diagram for the GC5016 when configured as a 4-channel digital down-converter(DDC). In a common configuration, each down-conversion channel demodulates ADC sampled data down from an IF frequency to 0Hz, low pass filters the signal data, reduces the signal rate (decimation), and outputs I and Q baseband data. The baseband signal is measured by the Power Meter, and a gain or gain + automatic gain are applied to the IQ data. Several output formats are available for transmitting the IQ outputs.

The DDC input can be configured for real or complex inputs. The input data on ports AI[15..0], BI[15..0], CI[15..0], are converted to a complex input format in the Receive Input Formatter (RINF).

The Mixer stage provides the Receive Input channel selection (RSEL), digital oscillator (NCO), and complex mixing logic (mixer) to translate the input down to 0 Hz.

After the Mixer, the 5 stage Cascade Integrator Comb (CIC) provides complex filtering and decimation. The CIC decimation is an integer value from 1 to 256. Special logic is used for double rate processing.

After the CIC complex filter, the Programmable Finite Impulse Response (PFIR) filter provides CIC correction, spectral shaping, and further decimation. The PFIR decimates from 1 to 16.

The PFIR complex output is measured by the Complex Power Meter. The Power Meter integrates the IQ power. The time integrated value can be read through the Microprocessor port.

The PFIR complex output is gain (manual + adaptive) scaled. An automatic gain (adaptive gain) is computed based on the current IQ output level. The gain scaled output is rounded to a desired number of bits resolution, and is formatted for the DDC output.

Channels can be synchronized to support beam forming or frequency hopped systems. Two channels can be operated in tandem to allow double input bandwidth, double output bandwidth, or both.

## 13.2 Receive Input Formatter (RINF)

The GC5016 has four 16-bit input ports AI[15..0], BI[15..0], CI[15..0], and DI[15..0]. The formatter converts the representation of real or complex data at the input pins to a complex format output.

### 13.2.1 Receive Input Data Formats

Five data formats are supported (see Table 1):

- Full Rate, Real Input, one signal per input port
- Double Rate, Real Input, one signal per two input ports (even and odd)
- Half Rate, Complex Input, one signal per input port
- Full Rate, Complex Input, one signal per two input ports (I and Q)
- Double Rate, Complex Input, one signal per four input ports (Ieven, Qeven, Iodd, Qodd)

**NOTE:**Full Rate means the sample input rate is equal to the GC5016 clock rate.

Each input port has a receive input data formatter. The data formatter accepts 2s complement format data 16 bits from its input port and outputs a 16-bit I bus and a 16-bit Q bus (the rinf bus). When there is no data to send, the output bus is held to zero.

For example:

If the input data is real, at full rate, the Q bus is zero.

If the input data is complex, at half rate, every second time sample is zero.

If the input data is complex at full rate, the I data is expected in port A (or C) and A's Q bus is zero. The imaginary data is expected in port B (or D) and B's I bus is zero.

The input format can be specified to the cmd5016 software by setting pseudo-commands rin\_rate and rin\_cmplx.

**NOTE:**Pseudo-commands are user specified variables that the software uses to set the hardware register values.

Table 1 shows the modes, the pseudo-commands, and register variables, programmed through the cmd5016 software.

For example, for the mode with four complex inputs, data from source 1 is entered time multiplexed I, followed by Q onto port AI. Configuration using the software requires that rin\_cmplx be set to 1 and rin\_rate be set to 0 (half rate). Alternatively, if the user wishes to program the hardware register fields directly, rinf\_sel\_A should be set to 3, mix\_rcv\_sel to 0 for channel A, and mix\_rcv\_cmplx to 0 for channel A (etc., for channels B, C, and D).

**Table 1. Receive Input Modes and Controls**

MODE	INPUT PORTS				SOFTWARE CONTROLS	FIELDS FOR CHANNELS A, B, C, AND D					
	AI	BI	CI	DI	<i>rin_cmplx/ rin_rate</i>	<i>rinf_sel/ mix_rcv_sel</i>	<i>mix_rcv_cmplx</i>	A	B	C	D
Four real	1I	2I	3I	4I	0/1	4/0/0	4/1/0	4/2/0	4/3/0		
Four complex	1I/1Q	2I/2Q	3I/3Q	4I/4Q	1/0	3/0/0	3/1/0	3/2/0	3/3/0		
Two complex	1I	1Q	2I	2Q	1/1	4/0/1	1/x/x	4/2/1	1/x/x		
Two double rate real	1I(2k)	1I(2k+1)	2I(2k)	2I(2k+1)	0/2	4/0/0	4/1/0	4/2/0	4/3/0		
One double rate complex	I(2k)	Q(2k)	I(2k+1)	Q(2k+1)	1/2	4/0/1	1/x/1	4/2/x	1/x/x		

### 13.2.2 Synchronization for IQ Multiplexed Mode

When I and Q are time multiplexed, a synchronization signal is used to determine which sample is I and which is Q. The input data is delayed by one cycle to form the I stream and is directly output for the Q stream. Thus far the data stream is (I0,Q0), (Q0, I1), (I1, Q1), — where I0 is the real portion of the sample at time 0. Then every other complex sample is zeroed using receive interpolation as discussed below, so that the stream is now (I0,Q0), (0,0), (I1,Q1), (0,0). — The timing for proper receive interpolation sync is shown in the next section.

### 13.2.3 Receive Interpolation

If the GC5016 CK rate divided by the input sample rate is an integer ratio, receive interpolation can be used (see Figure 4). In this case, the chip can be programmed to insert 0–15 zeros (rinf\_zpad) between input samples. This effectively interpolates the signal up by rinf\_zpad+1. The higher CK rate means the chip is operating faster, so the PFIR has more multiplication operations available per sample. It also allows greater flexibility in selecting the output sample rate since:

$F_{s\_out} = F_{ck} / (cic\_dec \times fir\_dec)$ , where  $F_{ck} = F_{adc} \times (1 + rinf\_zpad)$ .

One sample is registered while the data input on the other rinf\_zpad clocks are zeroed. The user has control over which sample is used through rinf\_zpad\_sync. The zpad selected sync encounters a two CK cycle delay, then loads a counter. When the counter reaches the terminal count, it is reloaded and a data sample is kept. All other data samples are zeroed. The sample occurring two plus (rinf\_zpad + 1) clock cycles after the sync is used, while the other samples are ignored. The sync input may be periodic in any multiple of (rinf\_zpad+1) or may occur just once.

If I and Q are time multiplexed, then the sync should be coincident with the Q sample.,

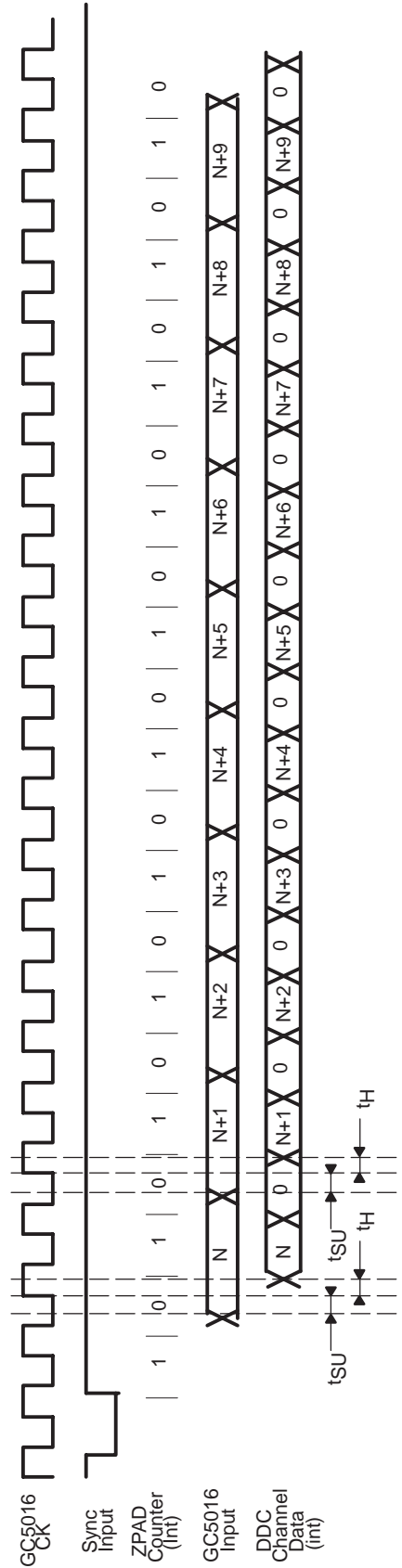


Figure 4. DDC Input Timing Diagram

### 13.2.4 Receiver Desensitizing

In a few circumstances, it is necessary to reduce the receiver sensitivity, which can be done by adding noise to the signal. The GC5016 allows this to be done digitally by adding pseudo random noise to selected bits in the input data stream. The noise power is added by bit wise xoring the input data stream with a Pseudo-random Noise (PN) sequence. The user has control over the noise power by programming which bits get the noise added. The noise power can go from  $-3$  dBFS (0xffff) to  $-99$  dBFS (0x1). This is programmed using `rcv_noise_A` (or B, C, or D). The noise uses the PN generator that is also used for diagnostics. The generator must be enabled for this feature to work by setting `cksum_sync.front` to 0.

### 13.3 Receiver Diagnostic Selection

The Receiver RINF can select the counter (ramp), zero, a constant, or the PN sequence as the DDC channel real input. The 0x4000 constant is used with the NCO setting to generate a known complex tone for output testing. The `rinf_sel` and `rinf_diag` controls are used to select a diagnostic input for a DDC channel. See the Diagnostics section.

### 13.4 Receive Input Selection

In each channel an input selector exists at the input to the mixer. This selects I and Q data from one of four receive input formatters. The field `mix_rcv_sel` allows selection of the `rinf` bus. Full rate real or 1/2 rate complex inputs are selected with the `mix_rcv_sel` value as the input port. Special `mix_rcv_sel` values are needed for full rate complex, and double rate processing. See Table 1.

### 13.5 Mixer

The DDC application of the mixer uses the selected RINF and RSEL with the NCO sine and cosine values. The Mixer equations are:

$$I_{mixout} = I_{in} \times \cos(\text{Phase\_NCO}) - Q_{in} \times \sin(\text{Phase\_NCO})$$

$$Q_{mixout} = Q_{in} \times \cos(\text{Phase\_NCO}) + I_{in} \times \sin(\text{Phase\_NCO})$$

Each of the four multipliers (I x cos, I x sin, Q x cos, Q x sin) can be programmed in one of four modes (off, receive, cross transmit, normal transmit) (see Figure 5). A programmable inversion is provided for each I or Q data source. Programming Q x sin to be inverted corresponds to a mathematical view of down-conversion (mix with negative frequency tone to get a positive spectrum). Programming I x sin to be inverted corresponds to a radio view (tune to a frequency to get the signal at that frequency). The fields involved are `mix_icos`, `mix_isin`, `mix_qcos`, `mix_qsin`, and `mix_inv_icos`, `mix_inv_isin`, `mix_inv_qcos`, and `mix_inv_qsin`. The `cmd5016` software automatically programs these fields assuming a mathematical view.

Selected RINF and RSEL data is accepted into the mixer as 16-bit data, placed into the upper bits of an 18-bit word, and inverted if programmed. The 18bit input is multiplied by a 20-bit NCO word, summed with the output of a second multiplier creating a 21-bit output. The Mixer output in the DDC application is sent to the CIC.

This means there is a 6dB attenuation going through the mixer. In other words, there is a 1-bit growth on top to allow for the extreme case of both real and imaginary inputs at full scale being multiplied by an NCO word that is at 45 degrees. For real inputs, the attenuation is 6 dB, so the CIC can safely be programmed to have 6-dB gain. For complex inputs, the attenuation is 3dB peak. The `cmd5016` software includes this attenuation in its gain calculations when gain is set using the overall-gain keyword.

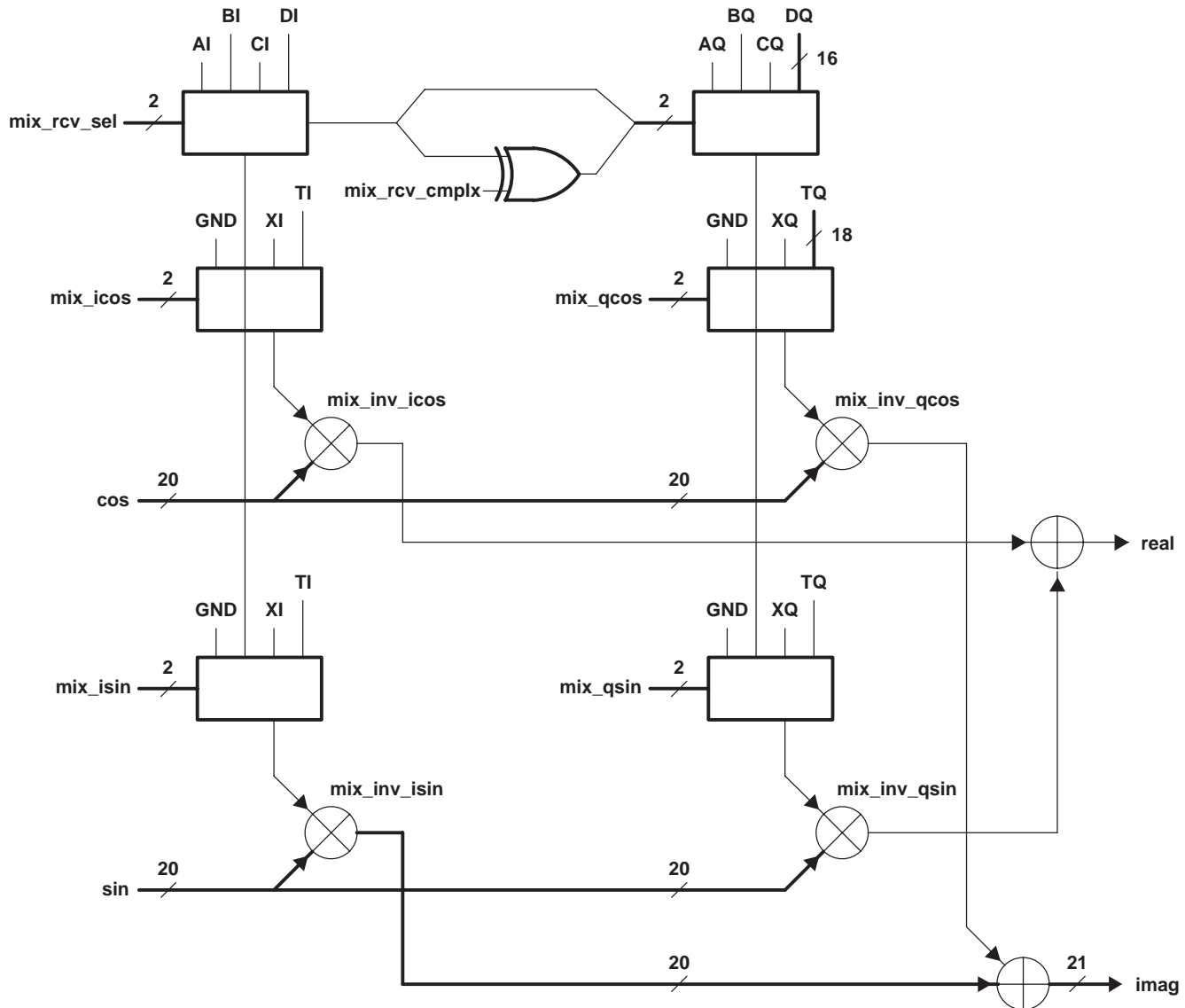


Figure 5. Multiplexing Options in Mixer

### 13.6 Numerically Controlled Oscillator (NCO)

The tuning frequency of each up-converter is specified as a 48-bit word and the phase offset is specified as a 16-bit word. The 48-bit tuning word is calculated based on:

$$\text{Freq words} = \text{FTune}(\text{negative for DDC}) / \text{CK} \times 2^{48}$$

The NCO phase is computed as the integrated frequency word phase + phase\_offset + dither. A block diagram of the NCO circuit is shown in Figure 6. The tuning frequency is set to  $\text{FREQ}$  according to the formula  $\text{FREQ} = (248) \times \text{F}/\text{fCK}$ , where  $\text{F}$  is the desired tuning frequency and  $\text{fCK}$  is the chip's clock rate. The 16-bit phase offset setting is

$$\text{phase} = (2^{16}) \times \text{Ph}/2\pi, \text{ where Ph is the desired phase in radians ranging between } 0 \text{ and } 2\pi.$$

A negative tuning frequency should be used for down-conversion. A positive tuning frequency can be used to flip the spectrum of the desired signal (if the input is real).  $\text{FREQ}$  and phase are set as shown in Table 53 through Table 56 or in software by specifying  $\text{freq\_msb}$ ,  $\text{freq\_mid}$ ,  $\text{freq\_lsb}$ , and phase. The configuration software calculates the appropriate settings for  $\text{freq\_msb}$ ,  $\text{freq\_mid}$ , and  $\text{freq\_lsb}$  given the chip clock frequency ( $\text{fCK}$ ) and  $\text{freq}$ . (If both  $\text{freq}$  and  $\text{freq\_msb}$  are set  $\text{freq\_msb}$  takes priority). The calculation includes the effects of  $\text{zpad}$  and double rate processing. Both  $\text{fck}$  and  $\text{freq}$  are expressed in Mhz.



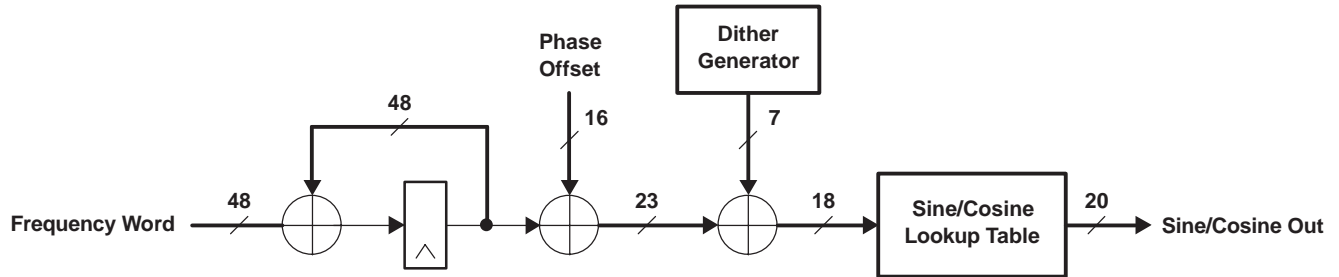


Figure 6. Numerically Control Oscillator (NCO) Circuit

The NCOs can be synchronized with NCOs on other chips. This allows multiple down converter outputs to be coherently combined, each with a unique phase and amplitude. The NCO's frequency, phase and accumulator can be initialized and synchronized with other channels using the `freq_sync`, `phase_sync`, and `nco_sync` controls. The `freq_sync` and `phase_sync` controls determine when new frequency and phase settings become active. Normally, these are set to Always so that they take effect immediately, but can be used to synchronize frequency hopping or beam forming systems. The `nco_sync` control is usually set to Never, but can be used to synchronize the NCOs of multiple channels.

The NCO's spur level is reduced to below  $-113$  dB through the use of phase dithering. The spectrums in Figure 7 show the NCO spurs for a worst case tuning frequency with and without dithering. Dithering decreases the spur level from  $-105$  dB to  $-116$  dB. Dithering is turned on or off using the `dith_sync` controls. Holding `dith_sync` always on freezes the dither value, effectively turning off dither.

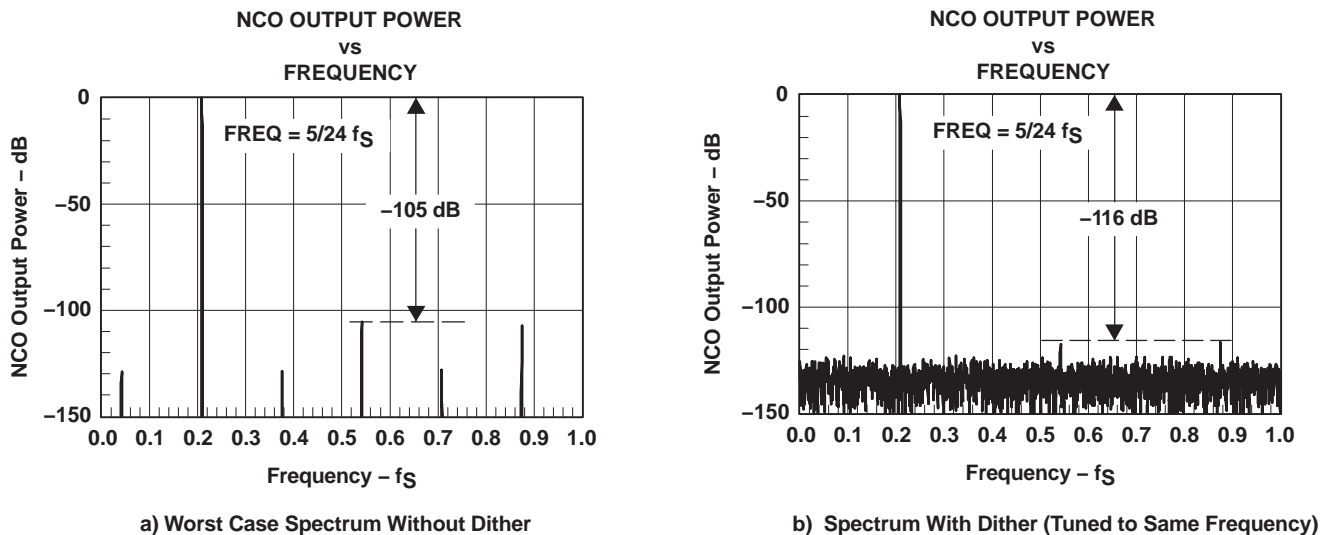
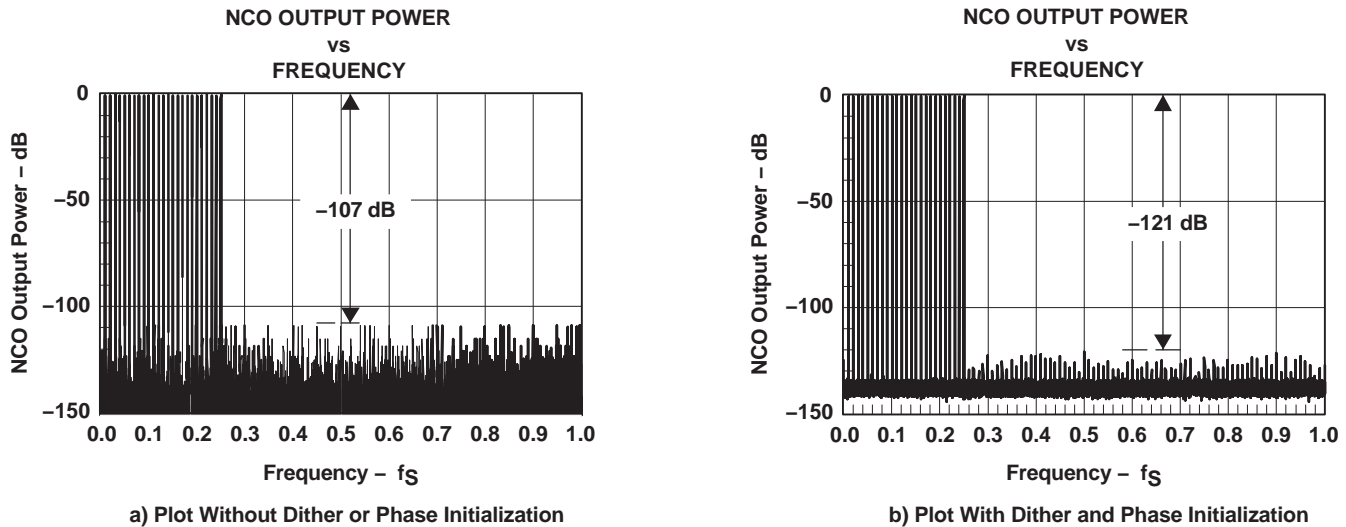


Figure 7. Example NCO Spurs With and Without Dithering



**Figure 8. NCO Peak Spur Plot**

The worst-case NCO spurs at  $-113$  dB to  $-116$  dB, such as the one shown in Figure 7(b), are due to a few frequencies that are related to the sampling frequency by multiples of  $f_{CK}/96$  and  $f_{CK}/124$ . In these cases, the rounding errors in the sine/cosine lookup table repeat in a regular fashion, thereby concentrating the error power into a single frequency, rather than spreading it across the spectrum. These worst-case spurs can be eliminated by selecting an initial phase that minimizes the errors or by changing the tuning frequency by a small amount (50 Hz). Setting the initial phase register value to 4 for multiples of  $f_{CK}/96$  or  $f_{CK}/124$  (and to 0 for other frequencies) results in spurs below  $-115$  for all frequencies.

Figure 8 shows the maximum spur levels as the tuning frequency is scanned over a portion of the frequency range with the peak hold function of the spectrum analyzer turned on. Notice that the peak spur level is  $-107$  dB before dithering and is  $-121$  dB after dithering has been turned on and the phase initialization described above has been used.

Double rate processing is done by sending time samples ( $2k$ ) to mixer A and time samples ( $2k+1$ ) to mixer B. The frequency is tuned to  $freq = (2^{48}) \times F/f_{CK}$ , where  $F$  is the desired tuning frequency and  $f_{CK}$  is the chip's clock rate as before. The 16-bit phase offset for mixer A is set to  $phase = (2^{16}) \times Ph/2\pi$ , where  $Ph$  is the desired phase in radians ranging between 0 and  $2\pi$ . The phase offset for mixer B is set to  $phase = (2^{16}) \times Ph/2\pi + (2^{15}) \times F/f_{CK}$ . Note that the second mixer phase offset is one frequency step at the sample rate of  $2 f_{CK}$  hence  $2^{15}$  rather than  $2^{16}$  scaling. The configuration software automatically calculates these.

### 13.6.1 CIC Decimate Filter

The Cascade Integrator Comb (CIC) filter is a 5 stage decimating filter. The CIC filter is set to decimation mode using the register variable `cic_rcv`. Each CIC channel contains two CIC filters (one for I and one for Q) allowing input rates of  $CK$  complex samples per second. The CIC filter has several sections: scaling, integration, rate change, comb filtering, and output scaling. The two CIC filter sections have special logic used in the double rate mode. The double rate mode is discussed in a later section.

The mixer IQ input is scaled to the 60 bit range using `cic_shift`. The shifted mixer data is then input to the 5 integrator  $M=1$  stages. The 5th integrator is decimated in the rate changer, by `ncic` samples. The `cic` scaling is based on shifting the input data to compensate for the 5 integrator stages' ( $cic\_dec \wedge 5$ ) gain.

$$Ncic = cic\_dec - 1$$

The decimation logic samples the integrator output every `cic_dec` clocks. The `cic_dec` value can be set between 1 and 256. The value of `cic_dec` can actually be programmed up to 4096 but the gain restrictions normally limit the usable range to 256 (up to 1024 in unusual circumstances).

<sup>[1]</sup>Hogenhauer, Eugene V., An Economical Class of Digital Filters for Decimation and Interpolation, IEEE transactions on Acoustics, Speech and Signal Processing, April 1981.

The decimated output is scaled to 24bits and input to the 5 stage comb section M=1. After the 5 comb sections, the 24bit output is scaled to 18 bits. The 18 bit output is saturated to 17 or 18 bits. The 17bit output is used when the PFIR uses symmetry. A block diagram of the decimating CIC filter is shown in Figure 9.

The CIC filter has a gain equal to `cic_dec5` that must be compensated for by the CIC scale circuit. and the scale circuit must limit the peak signal gain from the `rinf_zpad`, mixer, and through the CIC to be 1 or less. The peak gain is:

$$\text{peak gain} = (1/(1+\text{rinf\_zpad})) \times (\text{mixer\_gain}) \times (\text{cic\_dec}^5 \times 2^{(\text{cic\_shift}-39)})$$

The `cmd5016` program will set the gain properly if the overall-gain keyword is used.

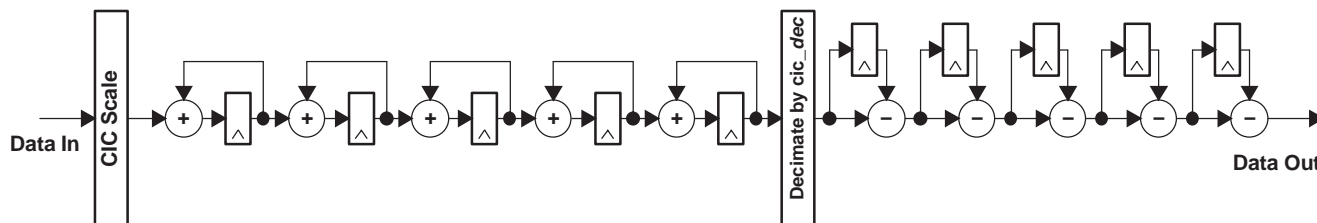
The register field `cic_sync` controls the precise moment of decimation. The sync can be periodic at any multiple of `cic_dec` without disturbing the processing. If sync is held active, the CIC freezes its output.

The output of the CIC can be attenuated in gain by 6 dB by clearing `cic_rshift`. This is appropriate only when `cic_shift` has been set to zero, the signal gain to this point is greater than 0.5, and symmetry is being used in the PFIR filter. In other words, `cic_rshift` should almost always be set to one. The `rshift_gain` is  $2^{\text{cic\_rshift}-1}$ .

The CIC output data feeding the PFIR must be limited to half scale if the PFIR is using symmetry. Control bit field `cic_rcv_full` must be cleared in this case. If the PFIR is not using symmetry, the data is limited to full scale and the bit field `cic_rcv_full` should be set to one. The CIC gain is adjusted by the `cmd5016` configuration software.

When the PFIR filter is in the normal IQ interleaved mode, the CIC filter output rate must not exceed  $CK/2$ .

The `splitiq` pseudo-command is used to determine the PFIR filter interleaved-IQ or non interleaved mode.



**Figure 9. 5-Stage CIC Decimate Filter**

### splitIQ Mode

In some cases, a signal that is input to the chip at  $CK$  rate needs to have more filtering capacity than the chip provides in a single channel. As noted above, twice the filtering capacity is available if each filter only processes I or Q rather than both I and Q. The `splitIQ` mode programs the I data to `firA` or `firC`, and the Q data to `firB` or `firD`. Data is mixed in `mixA/C` (`mixB/D` are idle). This is set automatically by the `cmd5016` software by setting `splitiq` to one.

It can be set manually by setting `cic_rcv_cross` in `cicB`, programming `mixB` to idle, and programming `firA` and `firB` to process real signals.

### CIC in Double Rate Mode

Each channel contains two CIC filters (one for I and one for Q) allowing the input sample rate to equal the clock rate ( $ck$ ). Double rate processing allows input rates of twice this. In this case, the dual CICs in each channel can be configured to perform as a single CIC at double rate. Thus, channel A's CIC can process the I portion of a double rate signal. The time samples ( $2k+1$ ) come from the I portion of mixer B and are routed to CIC A using the cross receive input (`cic_rcv_cross`). Likewise, channel B's CIC processes the Q portion of a double rate signal getting time samples ( $2k$ ) from the Q portion of mixer A using the cross receive input.

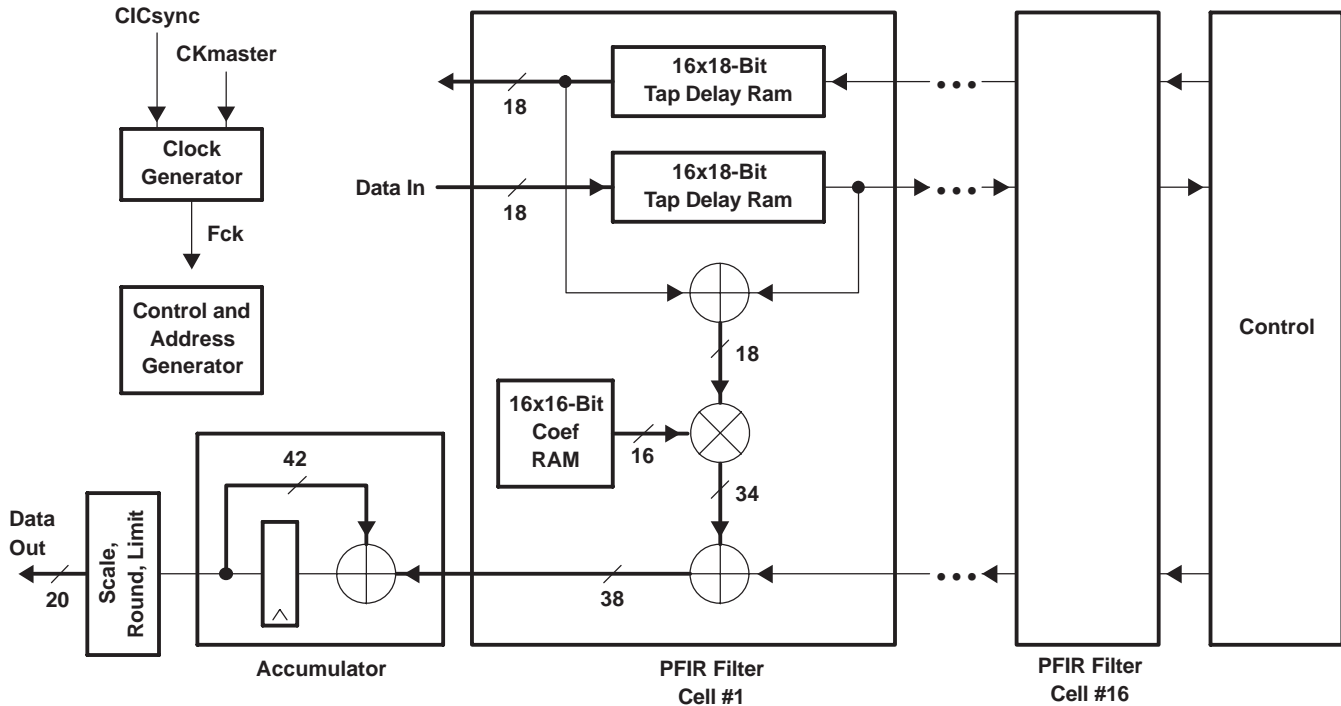
When data is input at  $2x$  rate, the CIC must decimate by at least 2 and by an even number. The `cmd5016` software uses the `rin_rate` pseudo-command to identify this mode. When operating in double rate mode `cicA` outputs I data only to `firA`, while `cicB` outputs Q data to `firB`. Likewise for C and D when they are operating in double rate mode. This means the PFIRs are operating on real data only (`splitiq` mode).

## 13.7 Programmable Finite Impulse Response Filter (PFIR)

The decimating PFIR filter consists of:

- An input swap RAM
- 15 common-programmed FIR filter cells
- A special 16th FIR end cell, and back-end control RAM
- A common control and address generator
- Accumulator logic
- An output gain shift, round, and limit block

Each PFIR can process real or complex data.



**Figure 10. Programmable Filter Block Diagram**

Each FIR cell contains:

- A forward 16x18-bit (16 words with 18-bit width) tap delay RAM
- A backward 16 x 18-bit tap delay RAM (used for symmetric filters)
- A pre-adder with 18-bit output (limits the data to 17-bits when using forward and reverse RAMs with symmetric filters)
- A 16x16-bit filter coefficient RAM
- A 16-bit x 18-bit (delay and coefficient) multiplier
- A 38-bit sum chain\_adder

The output of the sum chain adder in cell # 1 is sent to a 42 bit accumulator. The accumulator output is then shifted 0–7 bits, rounded and limited. The 20-bit accumulator output is sent to the gain section.

The PFIR sections can be programmed independently for each channel.

The filter coefficients can be arranged in banks, allowing the user to change between multiple filter sets rapidly and synchronously. Two sets of coefficients might be used in an adaptive application. While one set of FIR coefficients is being used, the other set is being updated over the control port.

The filter computes 16 taps (32 if symmetric) per clock cycle. The number of clocks available per output sample is

$$\text{Number\_of\_clocks} = \text{cic\_dec} \times \text{fir\_dec}$$

If the data stream is complex, then half the clock cycles are used computing the I output and half are used computing the Q output. The tap delay line limits the filter length to 256 if non-symmetric and 512 if symmetric (half this with complex data streams). The maximum number of taps is determined by the cmd5016 program. It can be estimated by:

$$\text{ntaps} = \text{sym} \times 16 \times \text{fir\_dec} \times \text{int}(\text{min}(\text{cic\_dec}, 16/\text{fir\_dec})/(\text{cmplx}/\text{fir\_nchan})) - \text{odd}$$

Where:

cmplx = 1 for real data (or *splitiq*) and 2 for complex

sym = 1 for nonsymmetric and 2 for symmetric

odd = 1 for odd, symmetric filters

*fir\_nchan* = 1 for up and down conversion

The PFIR coefficients are programmed using the cmd5016 configuration software. The cmd5016 program reports the maximum number of taps available for the configuration. The cmd5016 program uses the mode\_ab(cd), splitiq, cic\_dec, fir\_dec, fir\_diff, fir\_nchan, and pfir\_coef keywords to program the filters.

If there are multiple filter sets, the number of filters stored in memory will limit the number of coefficients per set. The filter supports odd or even symmetry. If the user's filter is significantly shorter than the maximum filter supported, the clock is stopped to the filter block, saving power.

The filter coefficients are zero-appended to the allowable number of taps. The cmd5016 software in the .ANL extension file reports the number of taps in the user-specified filter file, the PFIR filter mode, and the number of PFIR taps in the programmed configuration.

Gain for the FIR is:

$$\text{Gain} = \text{sum}(\text{coefficients}) / 2^{(21 - \text{fir\_shift})}$$

The overall\_gain pseudo-command is normally used to set the PFIR gain.

There is an application note on DDC gain, and using cmd5016 has examples for specific applications of the PFIR for DDC usage.

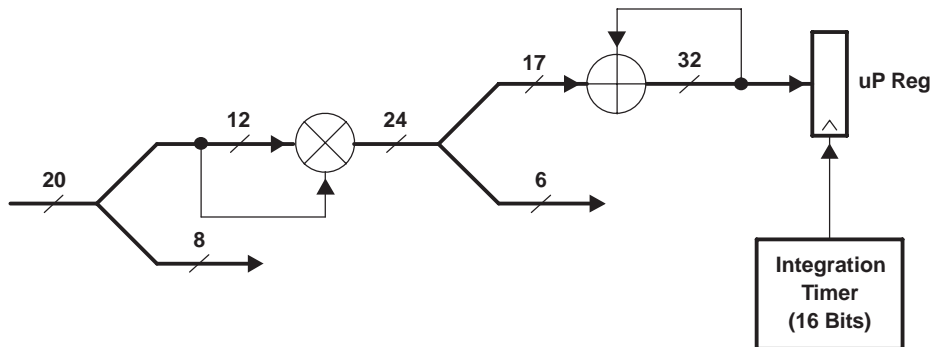
## 13.8 Power Meter

The PFIR output data is input to the power meter. The power meter integrates the  $I^2+Q^2$  power over a number of PFIR output samples. The power meter output is read as a 32bit result over the Microprocessor port.

The power meter squares the I or Q top 12 bits of the data, keeps the top 17 bits of the result, and integrates it for up to  $2^{16}$  words. The number of words is I or Q samples. Handshaking is provided to let the user know when data is ready. Note that the integration is over a number of words so if the data is complex the number of samples integrated is one half the number of words. If the filters are configured in a splitiq mode then the power meters of the real and imaginary channels need to be combined by reading both the I and Q channel power meters and adding the results..

A sync is available to start the power measurement period. The power meter automatically starts a new measurement at the conclusion of the last one. The contents of the power meter registers should be considered unstable from eight clocks after input sync to eight clocks plus an output sample time. (The actual unstable time is around 0.5 ns, so even reading during this window provides correct answers most of the time.) Reading during data transfer results in an erroneous output (some bits being updated, while others are not) but does no other harm.

The customer software can read the power meter several times, to obtain a valid reading, or can use the handshake signals to ensure reliable power measurements. If the processor is not sufficiently aware of time and the user wishes to avoid using the handshake, it is possible to read the power meter several times in rapid succession, checking that the value is consistent. Figure 11 shows the hardware.



**Figure 11. Power Meter Hardware**

A "done" control bit is set in the power meter status register when the integration counter is synchronized (`pwr_mtr_sync`) and again when it reaches terminal count (`pwr_mtr_integ`). The "done" signal that comes from syncing the integration counter should be discarded. Using the periodic sync counter to sync the integration counter is not recommended. On done, the accumulator value is strobed into the registers (page 0x13 address 0x1a and 0x1b), the ready bit (page 0x13 address 0x1c bit 15) is set, and the accumulator is cleared. Note that there are four independent power meters. The addresses here are for channel A. Channels B, C, and D are at the same address but on page offsets of 0x20, 0x40, and 0x60 respectively.

The control bus and system clock are at different rates. In most cases, the system clock is faster. To get the control bus to the system clock domain, a one shot is used. Firing the one shot clears the ready bit and lets the chip know the power was read. There are two ways to fire the one shot. It may be done automatically, when the msb of the power is read page 0x13 address 0x1c bit 10 = 1, or manually, by writing a 0 (arming) and then a 1 (firing) to page 0x13 address 0x1c bit 11, (page 0x13 address 0x12 bit10 must be 0). There should be two system clocks between writing the 0 and writing the 1, and two clocks after writing the 1, before rearming.

There are two status bits, `too_soon` bit13 and `missed` bit14. If the one shot is fired when the ready bit 15 is low, then `too_soon` is set. The user must reset it. If done happens when the ready bit is set, the `missed` bit is set. Again, it is reset by the user.

Example using a read of the msb to fire one shot:

1. Sync integration counter
2. Wait for ready bit to be 1 (8 clocks or less depending on sync source)
3. Read MSB of power (also fires one shot to clear ready bit) and ignore it.
4. Wait for ready bit to be 1
5. Read power LSB
6. Read power MSB
7. Check to be sure missed bit is not set
8. Go to step 4

**NOTE:** The `too_soon` bit is never set if ready is active when MSB is read.

Example using manual one shot firing:

1. Sync integration counter
2. Wait for ready bit to be 1 (eight clocks or less depending on sync source)
3. Arm and fire one shot to clear ready
4. Wait for ready bit to be 1
5. Read power LSB
6. Read power MSB
7. Arm and fire one shot to clear ready
8. Check to be sure missed bit is not set
9. Go to step 4

**NOTE:** The *too\_soon* bit is never set if ready is active when one shot fires.

### 13.9 Gain, Rounding, and IQ/AGC Multiplexing

The 20-bit PFIR output is multiplied by the (manual + AGC) 19bit gain value (see Figure 12). The gain adjusted output data is saturated to full scale and then rounded to between 4 and 20 bits in steps of one bit. The round circuit provides a round-to-even and shift of the data into the specified upper bits of the 20 bit DDC output. If selected, a special output multiplexing occurs to output the gain, I, and Q data. See Table 2. In the splitIQ mode, the I or Q is rounded and output. The DDC Output formatter converts the I, Q interleaved and AGC gain into the selected output format.

### 13.10 Automatic Gain Control (AGC)

The GC5016 automatic gain control circuit is shown in Figure 12. The basic operation of the circuit is to multiply the 20-bit input data from the PFIR by a 19-bit gain word that represents a gain or attenuation in the range of 0 to 128. The gain format is mixed integer and fraction. The 7-bit integer allows the gain to be boosted by up to a factor of 128 (42 dB) in .33db steps. The 12-bit fractional part allows the gain to be adjusted up or down in steps of one part in 4096 or approximately 0.002 dB. If the gain integer and fractional value is less than 4096, this is attenuation. The gain equation is:

$$\text{gainAv} = ( \text{gain\_msb} \times 65536 + \text{gain\_lsb} ) / 4096$$

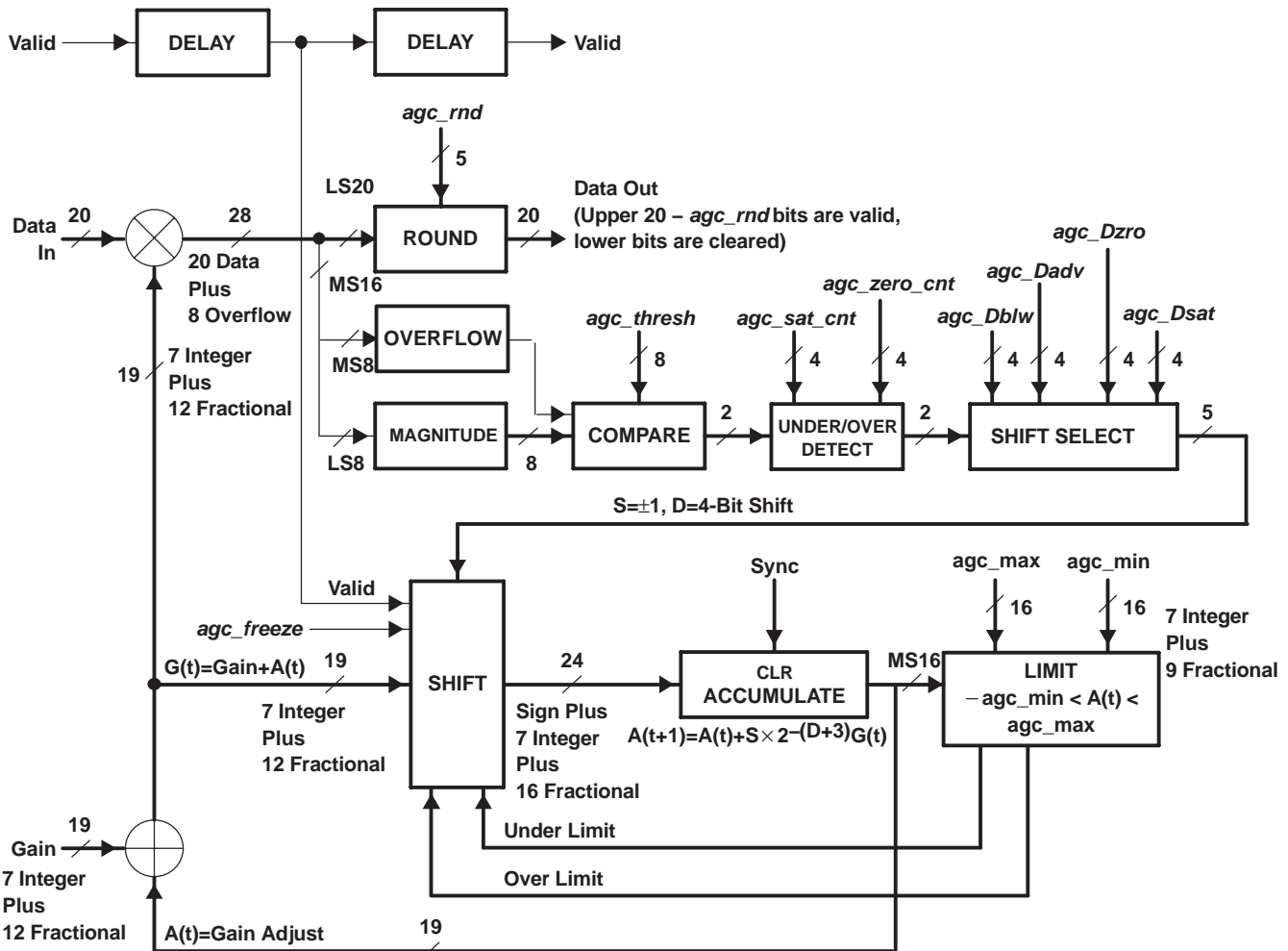


Figure 12. GC5016 AGC Circuit

The AGC portion of the circuit is used to change the adaptive gain so that the median magnitude of the output data matches a target value. The magnitude of the gain-adjusted (manual + adaptive) output data is compared to a target threshold. If the magnitude is greater than the threshold, the gain is decreased. If not, it is increased. The gain is adjusted as:

$$G(t) = G + A(t)$$

$$A(t) = A(t) + G(t) \times S \times 2^{-(D+3)}$$

where G is the default, user supplied gain value, and A(t) is the time varying adjustment, where S=1 if the magnitude is less than the threshold and is -1 if the magnitude exceeds the threshold, and where D sets the adjustment step size. Note that the adjustment is a fraction of the current gain. This is designed to set the AGC noise level to a known and acceptable level, while keeping the AGC convergence and tracking rate constant, independent of the gain level. Because the adjustment is a fraction of the current gain, one can show that the AGC noise is an amplitude jitter in the data output equal to  $\pm(\text{data output}) \times 2^{-(D+3)}$ . This means that the AGC noise is always 6 x (D+3) dB below the output signal's power level. The AGC attack and decay rate is exponential with a time constant equal to  $2^{(D+1.75)}$  complex samples. This means the AGC covers to within 63% of the required gain change in one time constant and to within 98% of the change in the four time constants.

If one assumes the data is random with a Gaussian distribution, which is valid for UMTS if more than 12 users with different codes have been overlaid, then the relationship between the RMS level and the median is  $MEDIAN = 0.6745 \times RMS$ .

Hence the threshold should be set to 0.6745 times the desired RMS level.



The step size can be set using four values of D. The user can specify separate values of D for when the magnitude is:

- below threshold (agc\_Dblw),
- above threshold (agc\_Dabv),
- consistently equal to zero (agc\_Dzro),
- or consistently equal to maximum (agc\_Dsat).

This allows the user to set different attack and decay time constants.

The agc\_Dzro and agc\_Dsat can have shorter time constants for when the signal falls too low (nearly zero) or goes too high (saturates).

The magnitude is considered to be consistently nearly zero by using a 4-bit counter that counts up every time the 8-bit magnitude value is nearly zero and counts down otherwise. Nearly zero is defined by and'ing the magnitude with a zero mask before checking to see if it is zero. If the counter's value exceeds a user specified threshold, then agc\_Dzro is used.

The magnitude is considered too high by counting the number of cycles where the count is greater than a maximum magnitude. If the counter value exceeds a user specified threshold, then the agc\_Dsat is used.

The AGC is also subject to user specified upper and lower adjustment limits. The AGC stops incrementing the gain if the adjustment exceeds agc\_max. It stops decrementing the gain if the adjustment is less than -agc\_min. The agc\_max and agc\_min bits are 16-bit values that line up with the most significant 16 bits of gain\_msb and gain\_lsb.

The input data is validated by a signal. For complex data, the I and Q samples are processed as if they were two real samples. An adjustment is made for the magnitude of the I sample, and then another adjustment is made for the Q sample.

The cmd5016 software will automatically program the agc circuit using the keywords overall\_gain, agc\_mode, agc\_tc, and agc\_cf. See the GC5016 automatic gain control application note for details.

### 13.11 Fixed Gain Control

The AGC can be turned off by setting the agc\_freeze control bit. The AGC adjustment loop is cleared using the gain\_sync control bit field. A static gain is set by setting G0 using the gain\_lsb and gain\_msb bit fields, by setting agc\_freeze, and by setting gain\_sync to be always active. The gain\_sync control can also be used to synchronize gain changes across multiple channels or across multiple chips. The cmd5016 software will put the chip into the fixedgain mode and will automatically calculate the correct values for gain\_lsb and gain\_msb based upon the overall-gain keyword.

### 13.12 Receiver Output Interface (ROUTF)

This section describes the output interface of the GC5016 as a DDC. The receiver output has several different modes, and different numbers of output pins and bit configurations. The receiver Output has several formats:

- Parallel IQ or real output – in this mode, there is one output per Frame Strobe and each channel is output on its own pins.
- Interleaved IQ – in this mode, the Frame Strobe identifies the start of I of the interleaved IQ output. In this format, I is output first, followed by Q. Each channel is output on its own pins.
- Time Division Multiplexed IQ – in this mode, all of the DDC channels are output from the D output port. The Frame Strobe identifies the start of each TDM frame. The output order in 4 channel mode is: ID, QD, IC, QC, IB, QB, IA, QA. The output order in 2 channel split IQ mode is: QD, IC, QB, IA.

The output interface also allows AGC gain data to be output with the data.

The GC5016 has four 16-bit output ports. Each output port consists of 16 parallel output pins, a programmable divided clock, and a frame strobe. The parallel output data pins for the GC5016 are AO[15..0], BO[15..0], CO[15..0], and DO[15..0]. The letters A..D refer to the four separate channels A..D.

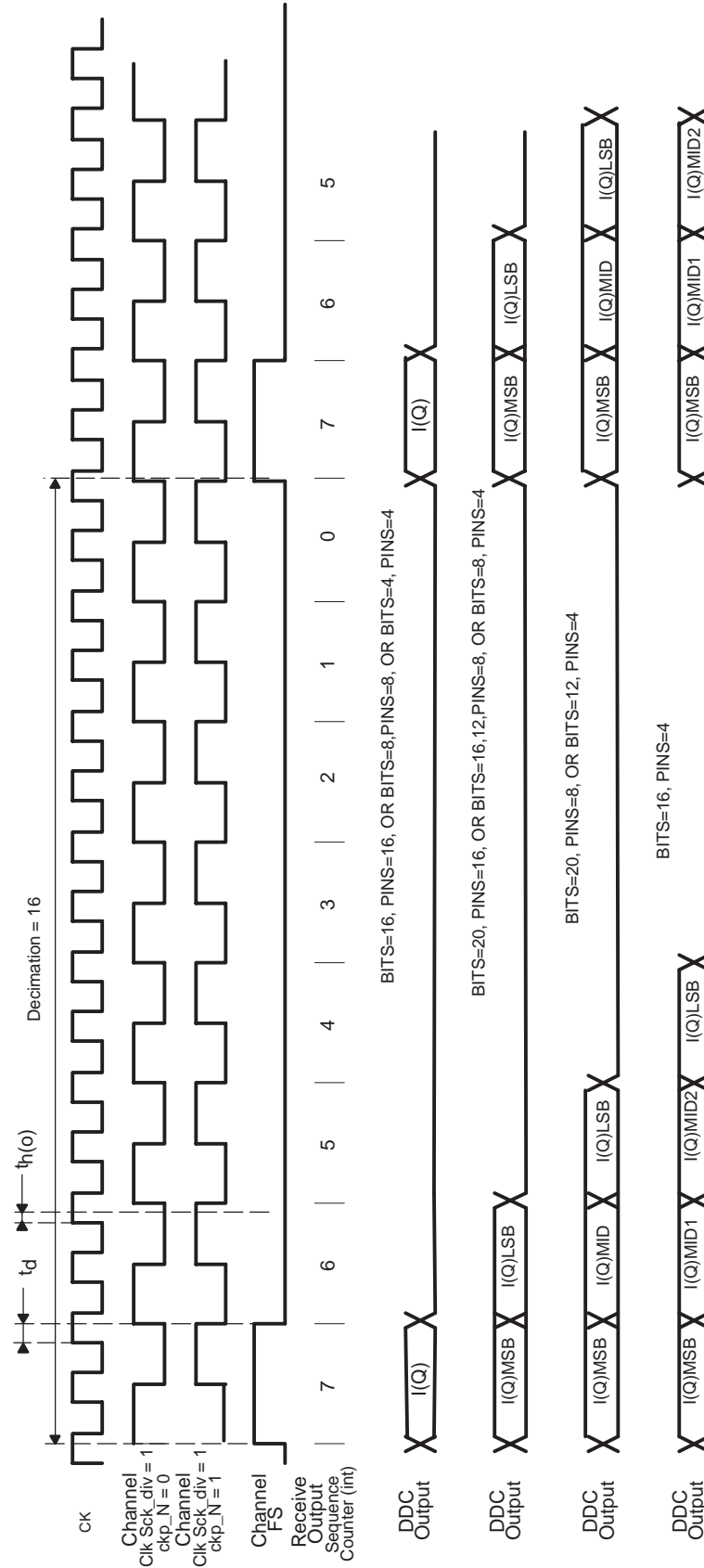
The clocks [A..D]CK for each port are generated by dividing the GC5016's main clock CK by a programmable divider for each port. Programming the divided port clock establishes the output rate for this port. The clock dividers can be synchronized by the methods described in the Synchronization section. The polarity of each divided port clock [A..D]CK is user programmable. The clock, data and Frame Strobe outputs are output after the rising edge of the CK clock. Figure 13 shows the  $t_d$  and  $t_{h(o)}$  timing between the CK and the Output (Out[ ]) Bus.

The divided port clocks [A..D]CK are output by the GC5016 as data signals, and therefore change nearly simultaneously with the frame strobes and the output data pins. The divided clocks typically transition 0.5ns after the frame strobe and the output data due to the xor gate for clock polarity. When `ck_pol` is 0 data transitions just before the rising edge of [A..D]CK, the falling edge of [A..D]CK should be used. If `ck_pol` is 1, then the rising edge should be used. The serial clock output is valid starting six clocks after the incoming sync selected by `sck_sync` (see Figure 14).

The frame strobe is one `sck` period in width. The divided port clock (`sck_div + 1`) should be a submultiple of the decimation ratio (`cic_dec × fir_dec`). Otherwise the frame period varies between X `sck` periods and X+1 `sck` periods. The output port data can be sampled on the rising edge of CK after the Frame Strobe is asserted. The Time Division Multiplexed Output, and Interleaved IQ output require multiple samples to capture the output data. The customer logic must generate the multiple cycles after the Frame Strobe is received.

The divided port clock can be used to hold the output data across several CK cycles. It is easier to design the logic interfacing with the GC5016 receiver output if there is an integer number of channel divided clocks in the output frame. A combination of the CK and channel clock can be used to register the GC5016 output data.

**NOTE:** The `cmd5016` programming tool calculates the DDC output format settings. If the DDC output uses multiplexed data, and the output frame has no idle time, an error may occur. The `cmd5016` programming tool may issue a warning for this configuration. The output mode needs to have at least one idle clock cycle, or needs timing verification with the actual configuration.



**Figure 13. DDC Output Real or SplitIQ Timing Diagram**

The frame strobes [A..D]FS are used to signify the beginning of a data frame for each port. The frame strobes are set high by the GC5016 with the first word in a frame.

The GC5016 output can be a single data, interleaved complex data, or time division multiplexed data. The GC5016 may be configured to have one port for each channel. The GC5016 can be configured in time division multiplex data mode to have all 4 channels' data output on the D output port.

The number of pins used for a port is user programmable as 4, 8, or 16 . The number of bits in a word is user programmable as 4, 8, 12, 16, or 20 . When the number of word bits is larger than the number of pins, the data is sent time domain multiplexed at the divided port clock rate [A..D]CK. The most significant bits (MSBs) are sent first. For complex data, I is followed by Q. The frame strobe is set high with the MSB of the first I word as shown in Figure 14.

For example, in interleaved IQ mode, with 16 bits (bits=16) and four pins (pins=4) selected, there are eight transfers requiring at least 8 divided clocks, so  $(cic\_int \times fir\_int / (sck\_div + 1))$  must be eight or greater. The keywords bits, pins, sck\_div, and routf\_tdm are used to setup the output interface.

The GC5016 can round the output to any size from 4-bits to 20-bits and supplies zeros for the extra LSBs. The number of bits after rounding can be smaller than the number of bits in a word.

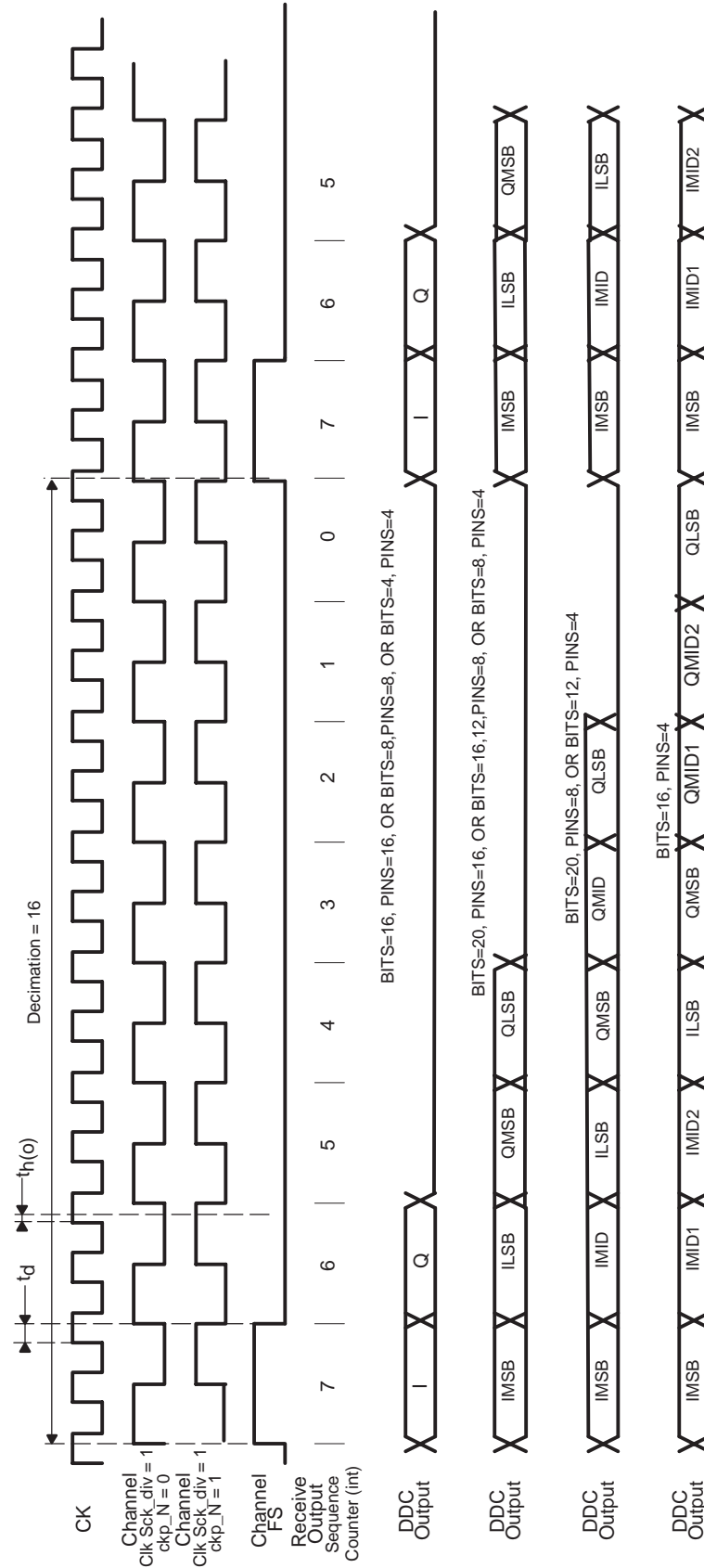


Figure 14. DDC Output Interleaved IQ Timing Diagram

### 13.12.1 Multichannel Time Division Multiplex

Two or four channels can share one output port, with the data for each channel time multiplexed. In this case, the frame strobe is set high with the MSB in the first I word in the frame as shown in Figure 15. The number of pins used for a port is user programmable as 4, 8, or 16, and the number of bits in a word is user programmable as 4, 8, 12, 16, or 20.

### 13.12.2 splitIQ Mode

Where a complex signal is split, so that the I and Q are processed in different channels, the outputs should be configured to output real data, with the I portion output from one port and the Q from another. The splitIQ mode can use the TDM IQ or real output mode.

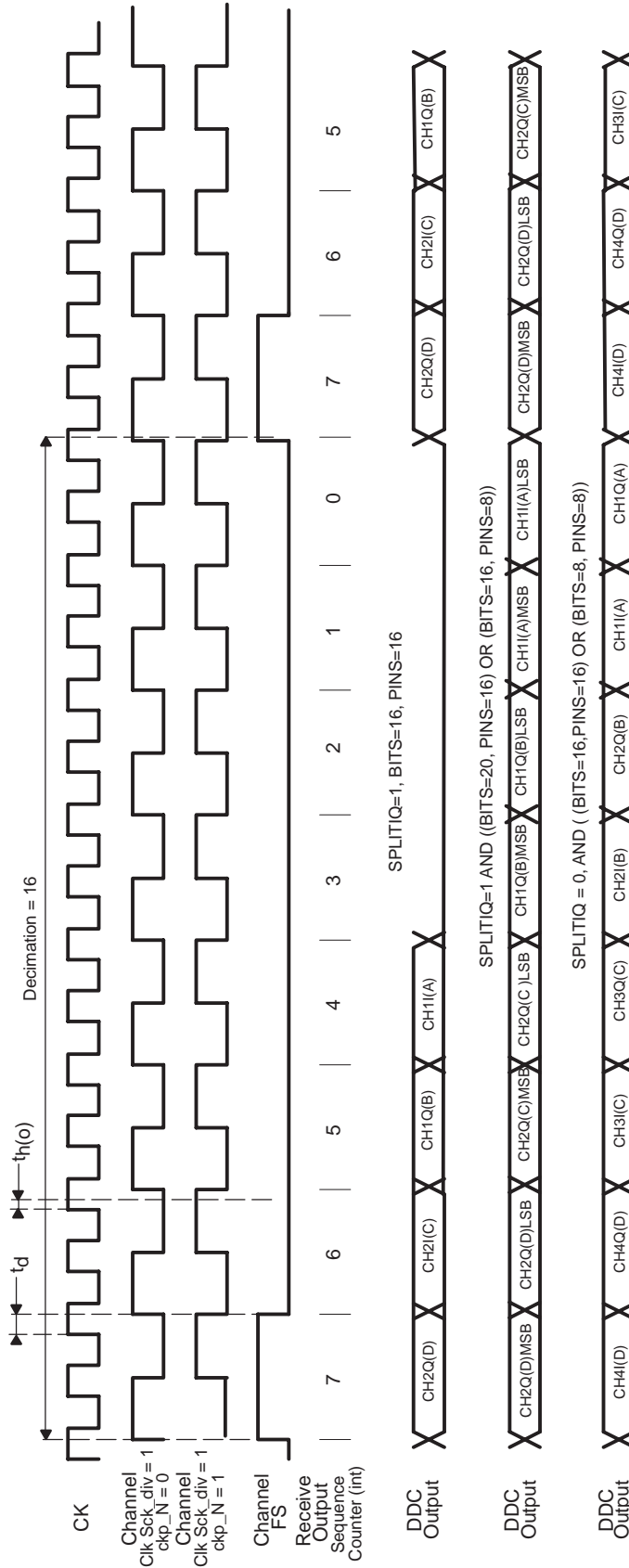
### 13.12.3 Embedded AGC

The output formatter can be set up to output AGC information together with the data. This is appropriate for systems with AGC enabled that need to know the current gain value with the 8 bit I and Q data. This is done by configuring the round to 8 bits or less, while configuring the port to support 16 bits. The lower 8 bits of the I and Q word are then replaced by the AGC information as shown in Table 2. The most significant 14 bits of gain are output together with 2 bits of state information. The state information shows whether the AGC is in a zero or max state that uses the faster gain adaptive constants.

The embedded AGC only works for total decimation rates ( $cic\_dec \times fir\_dec$ ) of 5, 6, and 10 or more. The cmd5016 program issues a warning if this mode is enabled for total decimations of 1, 2, 3, 4, 7, 8, or 9.

**Table 2. Bit Placement for Gain Output With Data**

PINS	TIME	CONTENT
AO 15..8	0	I 7..0
AO 7..0	0	Gain 18..11
AO 15..8	1	Q 7..0
AO 7..2	1	Gain 10..5
AO 1	1	Zero signal state
AO 0	1	Saturated signal state



**Figure 15. DDC Output TDM Timing Diagram**

### 13.13 Overall Gain in Receive Mode

The overall gain in the receive mode is a function of zero padding (*rinf\_zpad*), the CIC decimation (*cic\_dec*), the cic shift settings (*cic\_shift* and *cic\_rshift*), the sum of the programmable filter taps (PFIR\_SUM), the filter output shift (*fir\_shift*) and the final gain in the agc circuit (G). The *cmd5016* program, described later in the data sheet, sets the *cic\_shift*, *cic\_rshift*, *fir\_shift*, and G to their optimum levels for a targeted overall gain using the *overall\_gain* keyword. The calculated gain is done to limit the gain between stages, as well as provide an overall gain.

The overall gain is:

$$\text{DDC\_gain} = \text{zpad\_gain} \times \text{mix\_gain} \times \text{cic\_gain} \times \text{rshift\_gain} \times \text{fir\_gain} \times \text{agc\_gain}$$

Where the individual gains are:

$$\text{zpad\_gain} = 1 / (\text{rinf\_zpad} + 1)$$

$$\text{mix\_gain} = 1/2$$

$$\text{cic\_gain} = \text{cic\_dec}^5 \times 2^{(\text{cic\_shift} - 39)}$$

$$\text{rshift\_gain} = 2^{(\text{cic\_rshift} - 1)}$$

$$\text{fir\_gain} = \text{PFIR\_SUM} \times 2^{(\text{fir\_shift} - 21)}$$

$$\text{agc\_gain} = G / 4096$$

The restrictions on the gain settings are:

1. To prevent overflow in the CIC, *cic\_shift* must be set such that:

$$\text{zpad\_gain} \times \text{mix\_gain} \times \text{cic\_gain} \leq 1$$

2. If *rinf\_zpad* is greater than *cic\_dec*, then *cic\_shift* must be set such that:

$$(1/\text{cic\_dec}) \times \text{mix\_gain} \times \text{cic\_gain} \leq 1$$

3. For symmetric filters the maximum amplitude allowed into the fir is one-half, so *cic\_shift* must be set such that:

$$\text{zpad\_gain} \times \text{mix\_gain} \times \text{cic\_gain} \times \text{rshift\_gain} \leq 1/2$$

4. The *cic\_rshift* control is set to 1 (this control is only used to extend the allowable *cic\_dec* range, and must be used with care).

The *fir\_gain* and *agc\_gain* are used to adjust the overall gain to match the user's desired gain (*overall\_gain*). The *fir\_shift* control should be set such that:

$$\text{zpad\_gain} \times \text{mix\_gain} \times \text{cic\_gain} \times \text{rshift\_gain} \times \text{fir\_gain} \leq \text{overall\_gain}$$

and the final *agc\_gain* is set to give the desired *overall\_gain*.

This equation gives unity gain for dc or complex data inputs. For real inputs, such as from an ADC, the *DDC\_gain* is typically set to 2 (6 dB). The gain of 2 compensates for the loss of 6 dB when tuning a signal to dc and filtering out the negative image. Mathematically this is illustrated by using an example input signal *s(t)* modulated up to a frequency of " $\omega$ ". The input is defined as:

$$d(t) = s(t) \times \cos(\omega t) = s(t) \times (e^{j\omega t} + e^{-j\omega t}) / 2$$



## 14 GC5016 DIGITAL UP CONVERSION (DUC) MODE

The GC5016 can be configured as a digital up converter (DUC). The DUC interpolates, filters, mixes, and sums the customer inputs into one or several output ports. The GC5016 DUC (See Figures 2 and 16) has several blocks:

Transmit Input Interface

Gain

PFIR

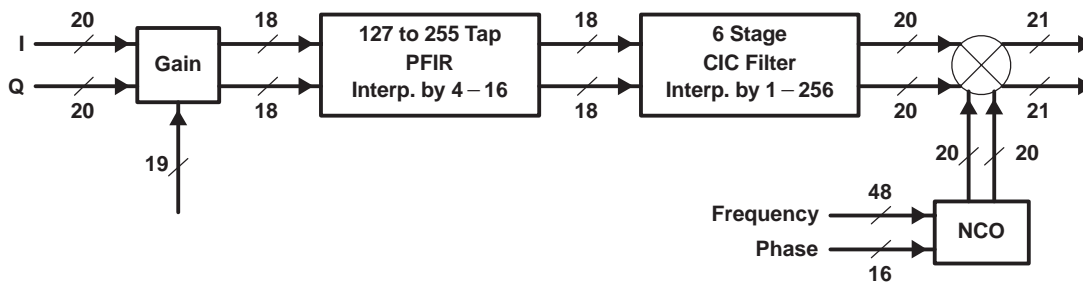
CIC

Mixer

Sum, SumIn, and Transmit Output Formatter

The GC5016 has either four independent DUC channels, or two Wideband (split IQ) DUC channels. The DUC accepts real or complex inputs, with complex being the more common. The GC5016 can have one, two, or four real or complex DUC outputs.

The up-conversion channel details are reproduced in Figure 16.



**Figure 16. Up-Conversion Channel Detail**

The Transmit input formatter generates the Frame Strobe and channel divided clock, and is used to receive the customer IQ data. The data input can be parallel IQ, interleaved IQ, or Time Division Multiplexed (TDM) IQ. The Frame Strobe signal is generated to indicate to customer logic that another input sample is required.

The gain block provides fine gain adjustment for the channel's IQ data.

The PFIR provides the first stage of interpolation. The typical PFIR interpolation is 3, 4, or 5. The number of PFIR taps is dependent on the number of data streams and number of clocks available to compute the FIR taps. The PFIR can interpolate from 1 to 16.

The Cascade Integrator Comb (CIC) filter provides the second stage of interpolation. The 6 stage CIC M=1 filter can interpolate from 1 to 256.

The interpolated IQ data and the NCO's frequency output sinusoid are mixed together in the mixer to generate the channel digital IF output. The mixer output can be real or complex.

The Sum block within the GC5016 can be used to combine other GC5016 outputs (using the SumIn path) with this GC5016's channels.

The Transmit Output Format logic converts the Sum or fixed scale data to the Real, Interleaved Complex, Parallel Complex, Double Rate Real, or Double Rate Complex output modes. An IFLG signal is output.

### 14.1 Special Modes– Split IQ, and Double Rate DUC Output

There are two special DUC modes: SplitIQ, and double rate.

The splitIQ Mode combines two channels to provide for more PFIR filtering. The A and B, or C and D channels can be used in the splitIQ mode. The A and C channels process the I data, and the B and D channels process the Q data. The parallel IQ and TDM modes may be used with the splitiq mode. In the splitIQ mode, the channel A and C mixers are used. The cmd5016 software keywords splitIQ, splitIQ\_AB, and splitIQ\_CD are used to control this function.

The double rate DUC mode utilizes the splitIQ mode with special CIC filter special mixer, and special output port programming. The double rate mode has two output ports versus one, as there are even and odd DUC outputs. The CIC filters produce even and odd sample outputs at the CK rate. The cmd5016 software keyword 'toutf\_rate 2' controls the double rate mode,

## 14.2 Transmit Input Interface

The Transmit Input Interface connects the customer input with the Gain Block. The Transmit Input has several formats, and programming modes:

Real Data – The channel input is real data.

8bit parallel IQ Data – The channel input is complex. Each 16 bit port accepts 8 bits of I and 8 bits of Q.

Parallel IQ Data – Two input ports are used for a complex input. I is input on one port, Q on the other. This mode limits the chip to only two input ports.

Interleaved IQ Data – One input port is used to transfer each complex input. Several channel clocks are needed to transfer the IQ input data.

Time Division Multiplexed (TDM) IQ Data – The A input port is used to input the channel IQ input data for all four channels. Several channels clocks are needed to transfer in the IQ data.

Several cmd5016 software keywords are used to specify the Transmit Input Delay and Transmit Input Formatter modes. The cmd5016 keywords are:

- fir\_int, cic\_int – interpolation ratio
- fir\_coef – the filter symmetry and number of coefficients
- sck\_div –sets the Frame Strobe width and the input data clock rate (period in CK clocks)
- tinf\_fs\_dly – term used to adjust the delay between the Frame Strobe output and the first IQ data sample in the frame
- splitiq, splitiq\_AB, splitiq\_CD – sets the split IQ mode
- tinf\_cmplx – identifies the input data as complex
- tinf\_tdm – identifies that all channels are Time Multiplexed on port A inputs
- tinf\_pariq –identifies the 8bit parallel IQ input mode
- tinf\_iqmux –identifies the interleaved IQ mode

MODE NAME	splitiq	tinf_cmplx	tinf_tdm	tinf_pariq
Real	1	0	0	0
8bit parallel IQ	0	1	0	1
Parallel IQ	1	0	0	0
Interleaved IQ	0	1	0	0
TDM IQ	0	1	1	0
TDM IQ(splitIQ)	1	0	1	0
TDM IQ(parIQ)	0	1	1	1

### 14.2.1 Frame Strobe

Each channel has its own Frame Strobe generator that outputs a Frame Strobe when it needs a new input sample. The period between each Frame Strobe is determined by the interpolation ratio.

The divided clock determines the width of the Frame Strobe and data signals. The Frame Strobe, 1→0 transition is used to identify the start of the input frame. See Figures 17 through 19.

The DUC channel outputs the Frame Strobe when it needs a new sample. The user can program the delay in divided clocks between the frame strobe output and when the first value for the frame is clocked into the chip. This delay is set in the cmd5016 software using the tinf\_fs\_dly keyword.

### 14.2.2 Input Clocking

The incoming data is clocked by the rising edge of the GC5016 clock CK.

The `sck_div` can be used to program the GC5016 receive data every second, third, etc., clock edge, allowing the data source to supply data at a lower speed. The user controls the clock division using `sck_div`. A value of 0 means that every clock edge is used; a value of 1 means that every other clock edge is used, etc. The clock division phasing is controlled by a general sync (`sck_sync`).

The time (in CK clocks) between data frames is the product of PFIR interpolation (`fir_int`) and CIC interpolation (`cic_int`). The divided clock must divide this evenly, so  $(cic\_int \times fir\_int) \text{ modulo } (sck\_div+1)$  must be 0 for the framing to be fixed length. Otherwise, the length varies between two values.

There need to be enough divided clocks per frame to receive the entire frame of data. This means that  $(cic\_int \times fir\_int) / (sck\_div + 1)$  must be greater than or equal to  $(bits/pins) \times (2 \text{ if complex}) \times (nchannels \text{ if TDM})$ . The CMD5016 software checks these constraints.

The divided clock outputs [A..D]CK are used primarily in the GC5016's DDC receive mode, but may be of use in some transmit applications – either as a data bit to indicate when data should be valid or in low frequency applications as a clock. They are generated by dividing the GC5016's main clock CK by programmable dividers `sck_div+1` for each channel. The input data transfer clock rate is then  $CK / (sck\_div+1)$ . The clock dividers can be synchronized by the methods described in the Synchronization section. The polarity of each divided port clock [A..D]CK is user programmable. For many applications, the input data transfer clock rate is the same as the main clock CK. In this case, the output [A–D]CK should be ignored.

The divided clocks [A..D]CK are clocked out of the chip on the rising edge CK . The input data is clocked into the chip on the rising edge of CK just before the rising edge of the divided clock (see Figure 19).

### 14.2.3 Bits and Pins

The user can select the number of data bits input to the GC5016 per divided clock cycle. The `bits` keyword in the `cmd5016` software selects the total number of data bits per input word. The allowable values are 4,8,12, 16, and 20 bits. The `pins` keyword selects the number of input port pins to use. The allowable values for the pins are 4,8, or 16. This means that there will be "pins" bits transferred for every divided clock cycle.

Transmit Input Mode	Bits	Pins	Port Pins Used	Number of Divided Clocks for I and Q, or I
Real, or Parallel IQ	20	16	15..0	2
	16,12	16	15..0	1
	20	8	15..8	3
	16,12	8	15..8	2
	8	8	15..8	1
	20	4	15..12	5
	16	4	15..12	4
	12	4	15..12	3
8bit I and Q	8	4	15..12	2
	8	16	15..0	1
Interleaved IQ Data	20	16	15..0	4
	16,12	16	15..0	2
	20	8	15..8	6
	16,12	8	15..8	4
	8	8	15..8	2
	20	4	15..12	10
	16	4	15..12	8
	12	4	15..12	6
	8	4	15..12	4

Transmit Input Mode	Bits	Pins	Port Pins Used	Number of Divided Clocks for I and Q, or I
TDM(not splitIQ) IQ Data	20	16	15..0	8
	16,12	16	15..0	4
	20	8	15..8	24
	16,12	8	15..8	16
	8	8	15..8	8
	20	4	15..12	40
	16	4	15..12	32
	12	4	15..12	24
	8	4	15..12	16
TDM(splitIQ) IQ Data	20	16	15..0	8
	16,12	16	15..0	4
	20	8	15..8	12
	16,12	8	15..8	8
	8	8	15..8	4
	20	4	15..12	20
	16	4	15..12	16
TDM(parIQ, splitIQ)	8	16	15..0	4

#### 14.2.4 Real or IQ Multiplexed

The GC5016 may be configured to have one input port for each channel. For complex data, I is followed by Q. The Frame Strobe is set high and low, marking the start of the transmit input frame. The 1→0 transitions of Frame Strobe and clock transition mark time 0 ( $t_{inf\_fs\_dly} = 0$ ) of the input data sequence. The Real mode starts out the same as IQ multiplexed but only the I data sample times are used.

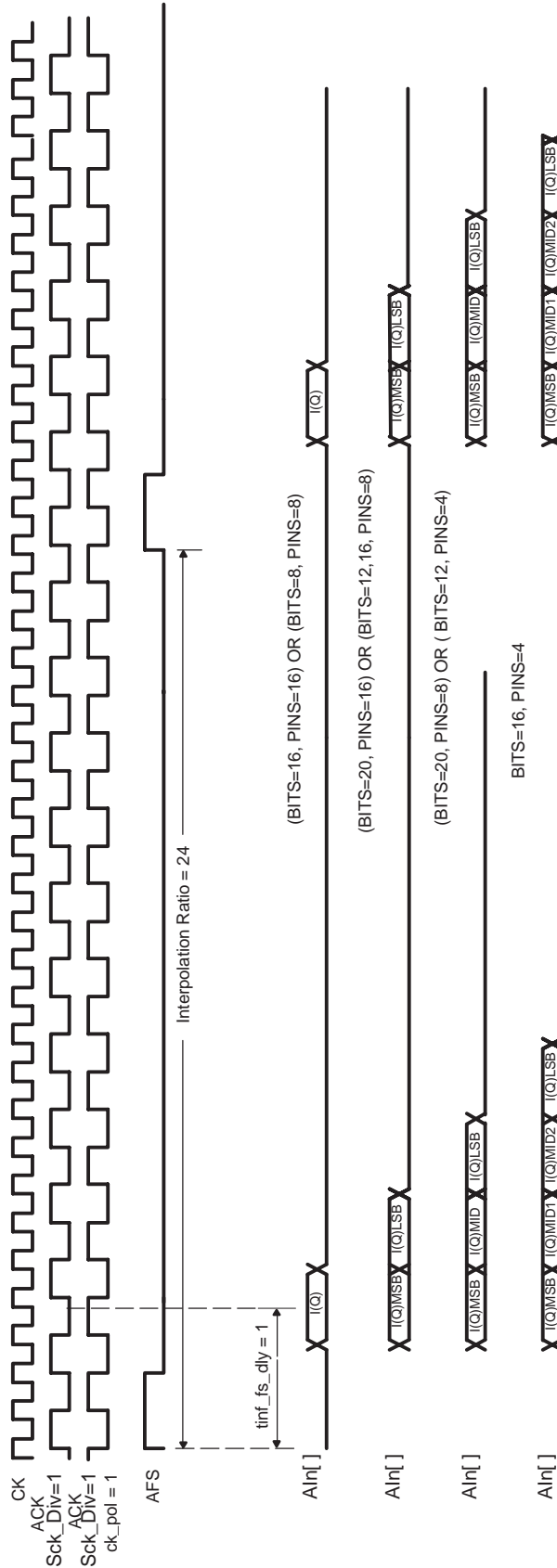


Figure 17. DUC Real or SplitIQ Input Timing Diagram, sck\_div = 1, tinf\_fs\_dly 1

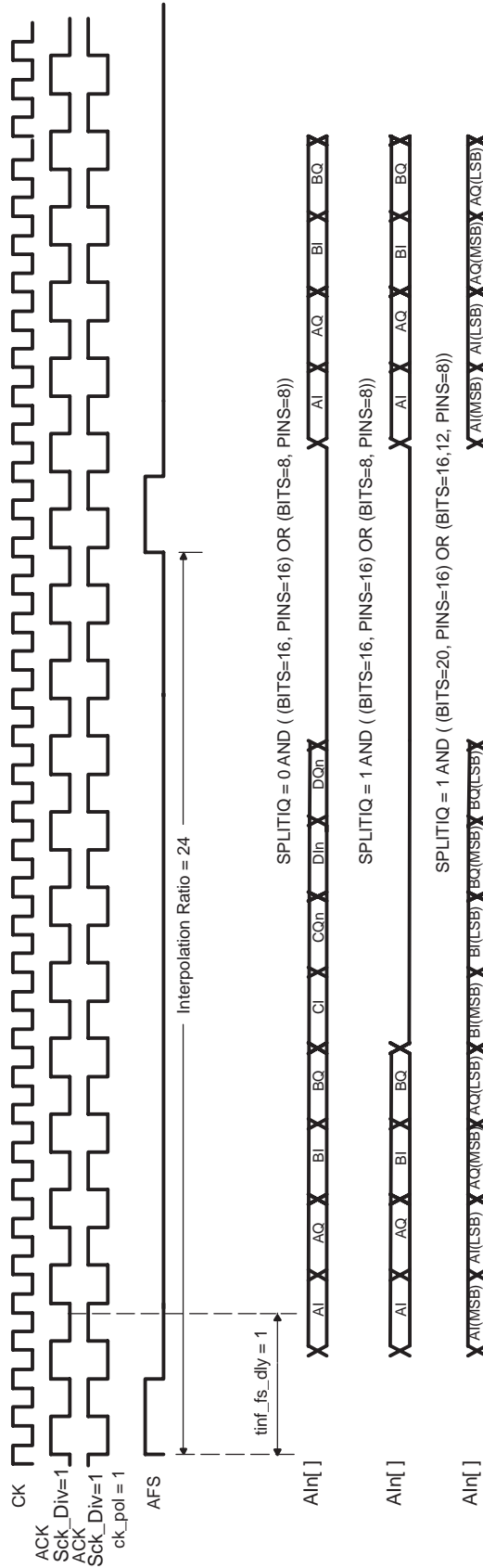
### 14.2.5 8bit IQ Parallel

The GC5016 may also be configured to accept input data with 8 bits of I and 8 bits of Q in parallel. I MSB should be placed at AI[15] and Q MSB at AI[7] (or BI, CI, or DI). This mode is valid only for 8-bit I and 8-bit Q using 16 pins. Applications with fewer bits usually connect the unused bits to GND.

### 14.2.6 Multichannel Time Division Multiplex

The A port may also be used as the source for all channels configured to accept input data. In TDM mode, the channel order is A, B, C, D. The Frame Strobe is set high and low marking the start of the transmit input frame. The 1→0 transition of Frame Strobe and clock transition mark time 0 ( $t_{inf\_fs\_dly} = 0$ ) of the input data sequence. There are three possible TDM sequences, depending on the desired number of bits, splitiq mode, and number of channels:

- 4 channel TDM, 12 or 16 bits for I or Q → IA, QA, IB, QB, IC, QC, ID, and QD
- 4 channel TDM, 8bit IQ parallel mode → IQA, IQB, IQC, IQD
- 2 channel TDM, split IQ, 12 or 16 bits → IA, QA, IB, QB



**Figure 18. DUC TDM Input Timing Diagram, sck\_div = 1, tinf\_fs\_dly 1**

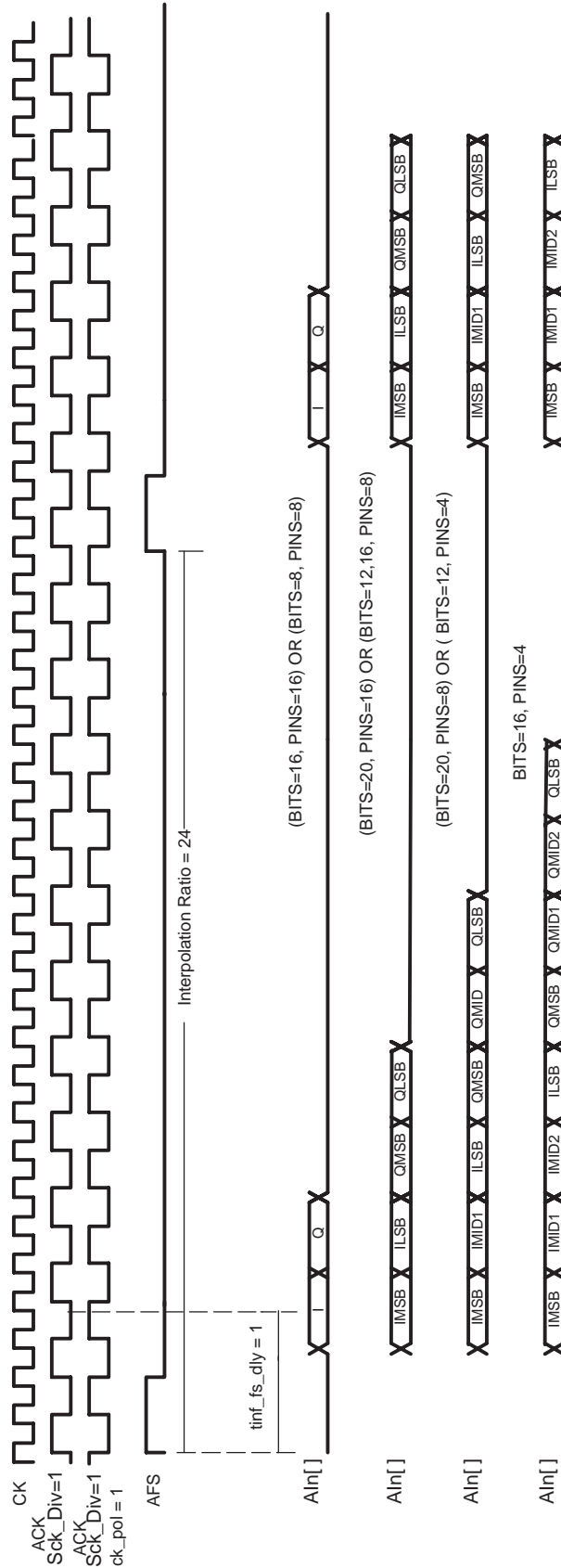


Figure 19. DUC IntIQ Input Timing Diagram, sck\_div = 1, tinf\_fs\_dly 1



### 14.3 Gain

Each 20-bit input sample is multiplied by a 19-bit gain word. The 16 gain LSB's are stored in one register, gain\_lsb and three MSB's in another, gain\_msb. The gain adjustment is  $GAIN/212$ , where the gain word (gain) ranges from 0 to  $(+219 - 1)$ . Negative gains are not allowed. This gives a 0.002-dB gain adjustment resolution. Setting gain\_msb and gain\_lsb to zero clears the channel input. A different gain can be specified for each channel. The gain values are usually set using the overall\_gain keyword in the cmd5016 software.

The gain values are double buffered and are transferred to the active register at the first I sample after sync (gain\_sync). The gain block for each up-conversion channel contains a dedicated 20x20 multiplier to apply fine gain control. The result is rounded to 18 bits, limited to one for non-symmetric filters or one-half for symmetric filters, and sent to a programmable filter. This is controlled manually using gain\_half or the software calculates it automatically.

### 14.4 Programmable Finite Impulse Response Filter (PFIR)

The interpolating PFIR filter consists of an input swap RAM, 15 common-programmed FIR filter cells, a special 16 FIR end cell, a control and address generator block, a final accumulator, and an output gain shift, round, and limit block (see Figure 20). The PFIR can process real or complex data.

The DDC and DUC share the same PFIR. The configuration of the PFIR and surrounding blocks, changes some of the functions( ie DDC decimation, DUC interpolation). The sections in the PFIR filter cells are:

- 16x18-bit (16 words with 18-bit width) forward tap delay RAM,
- backward 16 x 18-bit tap delay RAM (used for symmetric filters),
- pre-adder with 18-bit output (the reverse input is 0 for non-symmetric filters),
- 16x16-bit filter coefficient RAM,
- 16-bit x 18-bit multiplier,
- 38-bit sum chain.

The output of the sum chain is sent to an accumulator with 42-bit output and is then shifted up 0–7 bits, round and/or limited with a 20-bit output that is sent to the AGC.

The PFIR sections are programmed independently for each channel. The filter coefficients can be arranged in banks allowing the user to change between multiple filter sets rapidly and synchronously. Two sets of coefficients might be used in an adaptive application, where one set is being used while the other set is being updated. On each clock cycle the filter computes 16 taps (31 if symmetric). The number of clocks between PFIR outputs is cic\_int.

If the data stream is complex then half the clock cycles are used computing the I output and half are used computing the Q output. The tap delay line limits the filter length to 256 if non-symmetric and 511 if symmetric (half this with complex data streams). The maximum number of taps is determined by the cmd5016 program. It can be estimated by:

$$ntaps = sym \times \min(256, (16 \times fir\_int \times int(cic\_int/(cmplx*fir\_nchan) - odd)))$$

where:

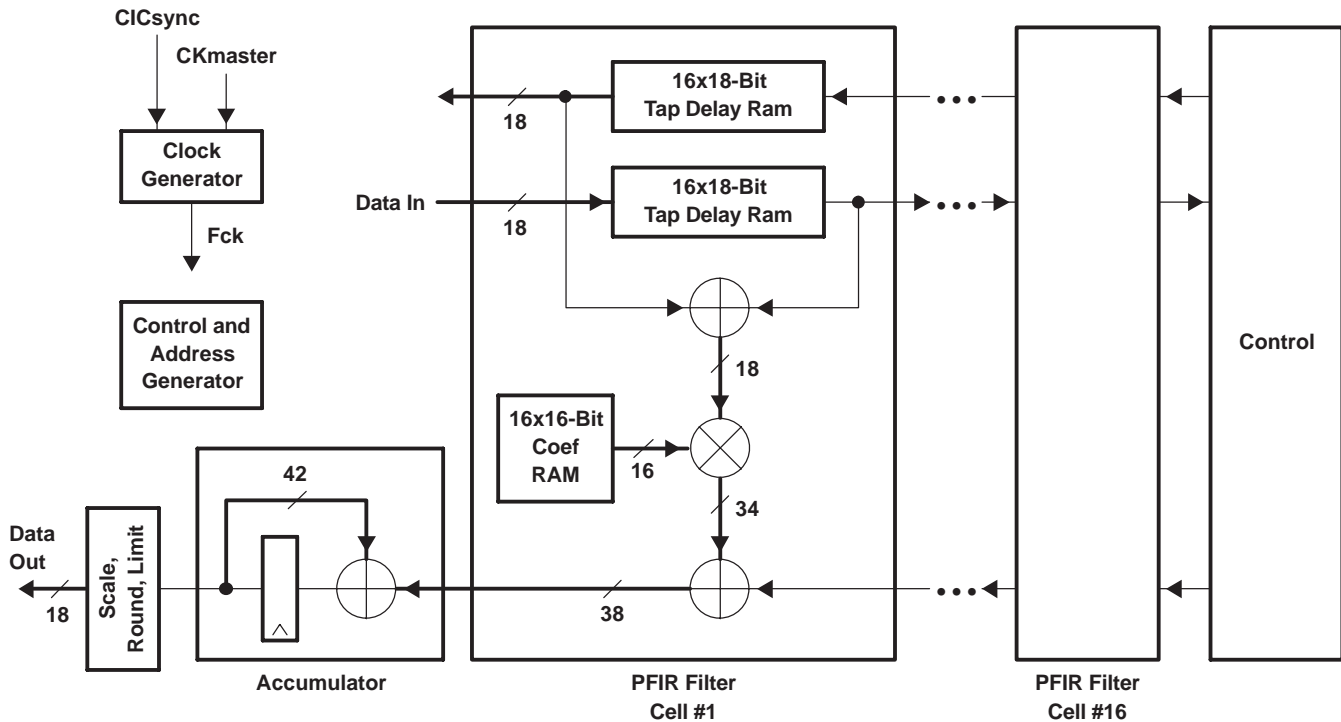
cmplx = 1 for real data (or splitiq) and 2 for complex

sym = 1 for nonsymmetric and 2 for symmetric

odd = 1 for symmetric filters

fir\_nchan = 1 for up and down conversion.

The PFIR coefficients are programmed through the cmd5016 configuration software, based on the number of filter taps computed per clock cycle, the number of clock cycles per output, the number of data streams in the PFIR channel, the symmetry of the filter taps, and the number of filter taps. The mode\_ab(cd), splitiq, cic\_int, fir\_int, fir\_diff, fir\_nchan, and pfir\_coef tap filename are the cmd5016 inputs.



**Figure 20. Programmable Filter Block Diagram**

Multiple PFIR coefficient sets will limit the PFIR length of a specific filter. In interpolation mode, the PFIR supports symmetry for interpolation of 1 or 2. If the user's filter is significantly shorter than the maximum filter supported, the clock is stopped to the filter block, saving power. The user can append zeros after the PFIR taps, to use the longest possible filter tap-size to reduce the PFIR latency.

Gain for the FIR is:

$$\text{Gain} = \text{sum}(\text{coefficients}) / (\text{fir\_int} \times 2^{(21 - \text{fir\_shift})})$$

The overall\_gain pseudo-command is used to set the PFIR gain, as part of the channel gain calculation.

The DUC gain application note and the cmd5016 software usage note have specific applications of the PFIR and gain settings for DUC usage.

## 14.5 Dual CIC Filter

The 18-bit output from the PFIR is interpolated by a factor of cic\_int in the 5 or 6-stage CIC filter, where cic\_int is any integer between 1 and 4096. The 6-stage CIC has a usable range from 1 to 294. The 5-stage CIC has a usable interpolation range from 1 to 1217. The value of cic\_int is programmed independently for each channel. A block diagram of the CIC filter is shown in Figure 21.

The output rate of the CIC interpolation filter is equal to the mixer clock rate CK. The CIC filter has a gain equal to  $\text{cic\_int}(\text{numCICstages}-1)$  that must be removed by the scale and round circuit. This circuit has a gain equal to  $2^{-41+\text{cic\_shift}}$ , where cic\_shift ranges from 0 to 39. Overall CIC gain is  $2^{-41+\text{cic\_shift}} \times \text{cic\_int}(\text{numCICstages}-1)$  and should normally be set to be 1 or less.

The cmd5016 configuration software uses ncic overall\_gain and cic\_int to calculate the appropriate control settings for cic\_shift, cic\_xmt\_5stg, cic\_xmt\_d6stg, cic\_2x, and ncic. ncic is  $\text{cic\_int}-1$  for normal cases and  $\text{cic\_int}/2-1$  for double rate.

**NOTE:** If overall-gain is not used, and if the gain is set too high, then the signal can overflow internally, which causes CIC instability. A momentary high power noise spike is seen on the output before the autoflush forces the CIC to zero. If the gain is set so high that the signal rapidly overflows internally, the output appears as a pulsing signal as the CIC periodically overflows.

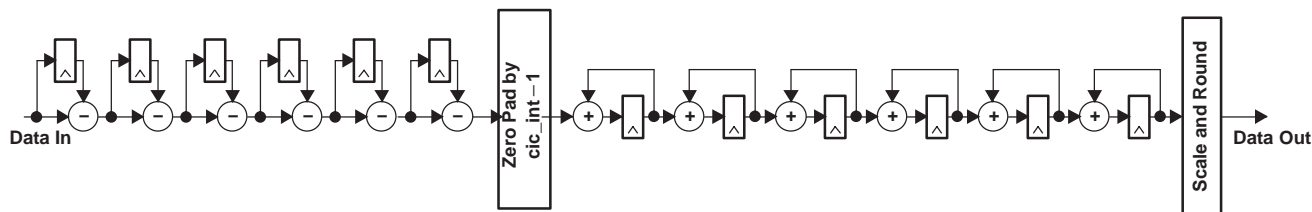
The CIC may be bypassed by setting `bypass_cic` or by setting `cic_bypass` bit, and setting `cic_int = 1`. This is appropriate for small overall interpolation (< 6) where the CIC filter requirement for wide transition bandwidth would be a problem, or when using the chip only for filtering operations. The CIC can be bypassed only in splitIQ mode.

### 14.5.1 CIC in SplitIQ Mode

In the standard configuration, a dual CIC is used in each channel, one for I and one for Q. In the splitIQ, non-double rate configuration, the I portion of each channel's dual CIC is used. The CIC outputs from channels A and B go to channel A's mixer, and the CIC outputs from channels C and D go to channel C's mixer.

### 14.5.2 CIC in Double Rate Mode

In the double rate mode, each CIC channel outputs even and odd time samples rather than I and Q samples. The CIC interpolators are configured to calculate two results with each clock cycle. In this configuration, the CIC interpolation must be even value and the filters are in the split IQ mode. The software configures this mode if the variable `toutf_rate` is set to 2.



**Figure 21. 6-Stage CIC Interpolate Filter**

## 14.6 Numerically Controlled Oscillator (NCO) and Mixer

The DUC NCO is identical to the DDC NCO (see Figure 5). The `mix_rev_sel`, `mixer_rcv_cmplx`, `mix_icos`, `mix_isin`, `mix_qcos`, and `mix_qsin` are selected by the `cmd5016` software to get the proper IQ data into the DUC Mixer:

Mode	Channel (Mixer)	I Source	Q Source
4 Channel	A,B,C,D	TI	TQ
SplitIQ	A,C	TI	XQ
SplitIQ	B,D	not used	not used
DoubleRate	A,C	TI	XQ
DoubleRate	B,D	XI	TQ

The mixer equations are identical to the DDC mode, in that the `inv_q_sin` control is a '1' for subtraction:

$$IMixOut = selected(I) * \cos(NCOphase) - selected(Q) * \sin(NCOphase)$$

$$QMixOut = selected(I) * \sin(NCOphase) + selected(Q) * \cos(NCOphase)$$

The mixer can be configured in normal mode, splitiq mode, or double rate mode. Figure 22 shows the normal mode where each FIR processes a complex data stream and feeds it to a dual CIC block. The dual CIC block is configured to process two streams (I and Q) at the clock rate. The interpolated output is sent to the mixer.

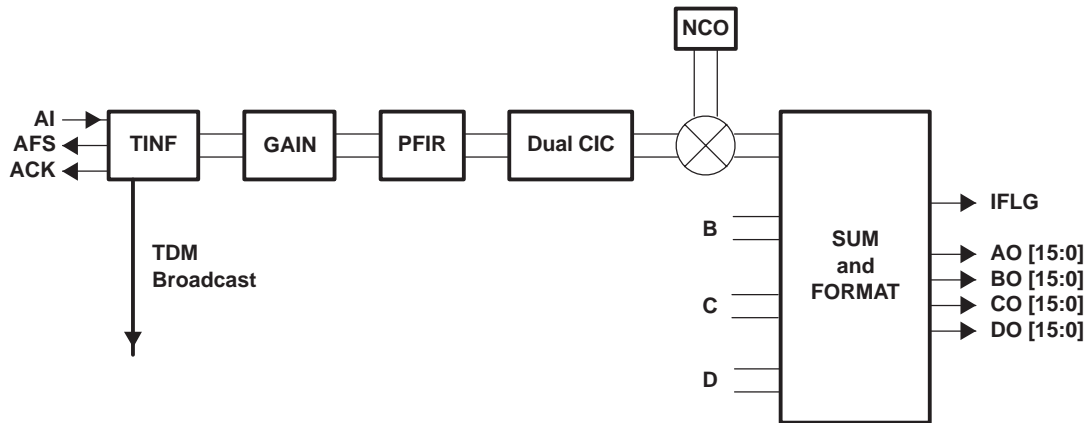


Figure 22. Normal Mode Transmit Channel

### 14.6.1 splitIQ Mode

The SplitIQ mode uses channels A,B and C,D in pairs. The PFIR and CIC are used with real data into channel A or C, and imaginary data into channels B or D. Figure 22 shows the standard configuration. The difference is that PFIR, CIC A/C processes the I channels, and PFIR, CIC B/D processes only the Q channels. Channels B and D are programmed as if real data is processed. The I and Q combination is done in the Channel A and C Mixer.

The SplitIQ mode can use the TDM IQ, and parallel I Q (16bit 2 ports) input modes. Each CIC is configured for the I input data. The CIC channel A,C I, and B,D Q are modulated using mixers A and C. For the complex mixer, the XQ input connects the B and D CIC I outputs.

The A and C Mixers are programmed with the freq differential phase, and phase, phase offset value. There are pseudo-commands splitiq\_AB and splitiq\_CD for setting only one pair of channels in splitiq mode. The PFIR in this configuration has twice the number of taps versus the standard configuration. This mode has the added benefit of allowing the CIC filter to be bypassed.

### 14.7 Double Rate Mode

Figure 23 shows the double rate data flows from input to mixer output. The double rate mode input configuration follows the splitIQ mode for the Transmit Input and PFIR configuration. The real portion of the data must be entered to channel A, and the imaginary to channel B. TDM input may be used if desired. The filters A and B are configured to process real data. Each dual CIC is configured to accept real input and interpolate (by an even ratio), and outputs two samples per clock. The output of CICA is then  $I(2k)$  and  $I(2k+1)$ , while the output of CICB is  $Q(2k)$  and  $Q(2k+1)$ . Mixer A is configured to accept cross-strapped input for the qcos and qsin multipliers, so that mixer A input is  $I(2k)$  and  $Q(2k)$ . Similarly, mixer B is configured to accept cross-strapped input for the icos and isin multipliers, so that mixer B input is  $I(2k+1)$  and  $Q(2k+1)$ . The output sample rate ( $f_{sample}$ ) is twice the chip clock rate (CK).

The cmd5016 configuration software controls this mode when the pseudo-command tout\_rate is set to 2. The cmd5016 configuration software sets the proper CIC and mixer settings. The user must provide the tuning frequency (freq). In double-rate mode, the accumulated value in the NCO should be increased by  $2 \times (ftune / f_{sample}) \times 2^{32}$  or  $(ftune / CK) \times 2^{32}$ . This is set directly in freq\_msb, freq\_mid, and freq\_lsb or by setting freq and fck in the software. The phase setting for NCO B should be offset from A by one frequency step, so  $phase(NCO\_B) = phase(NCO\_A) + (ftune / f_{sample}) \times 2^{16}$ . NCO B gets a phase offset of  $(ftune / f_{sample}) \times 2^{16}$ .

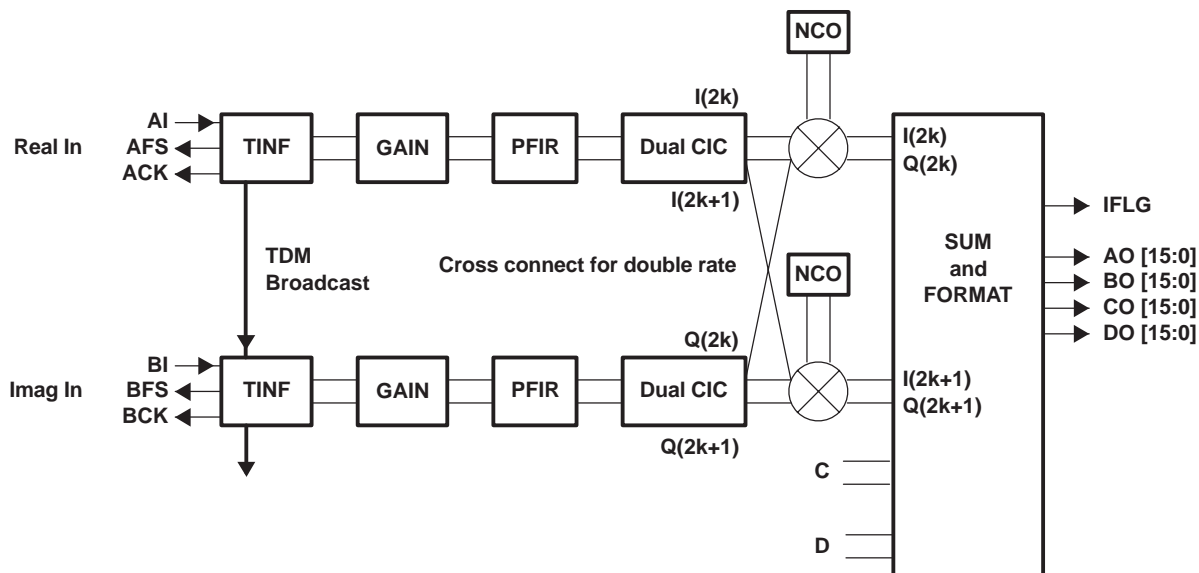


Figure 23. Double Rate Mode Transmit Channel

## 14.8 Transmit Output Interface

The complex mixer outputs are rounded to 21 bits and sent to the sum tree and transmit output formatter. The sum tree optionally adds together DUC channel outputs, and the transmit output formatter rounds the results and formats them for output on the 16 bit output ports: AO, BO, CO, and DO. The data pins for the output ports are AO[15..0], BO[15..0], CO[15..0], and DO[15..0].

The rounded 21-bit mixer outputs can either be sent to separate output ports or summed into one or two output signals in a sum tree. The summed signal can also be added to data from an external source such as other GC5016 chips. In this case, ports CO and DO function as sum input ports and are not available for signal output. The sum input path and sum output path are expected to be configured the same in all GC5016 chips in a summing chain except for possible rounding in the final chip.

The possible output formats and the cmd5016 keyword settings that are used to select them are shown in Table 3. The possible output modes are identified by the "Rate", "Real or IQ", and "Sum" columns.

The "Rate" can be either full, half or double. Full is the most common mode and indicates that a new sample is output every clock cycle (CK). Half means that complex samples are output at half the clock rate in an interleaved I followed by Q format. The IFLAG output signal identifies the I sample. Double means that the sample rate is twice the clock rate so that two time samples are output every clock cycle: Even time samples on one port, odd on another.

The "Real or IQ" mode identifies if the output is real or complex. If the output is complex, then the I and Q halves can either come out on separate ports or interleaved onto a single output port as specified by the "Rate" mode.

The "Sum" mode can either be none, pairs or all. The "none" mode means that each DUC channel is output on its own port and is not added to the other DUC outputs. The "pairs" mode means that the outputs from DUC channels A and B are added together and the outputs from DUC channels C and D are added together. The "all" mode means that all of the DUC channels are added together.

Table 3 is divided into sections that show settings for:

- Using standard resolution output word size (tout\_res=0 for 16 bits or less)
- Using wide resolution word size (tout\_res=1 for up to 22 bits). Output ports AO and BO are merged and output ports CO and DO are merged to give 22 bit outputs in the wide resolution mode.
- Using external sum IO paths (tout\_sumio=0 for no sumio, tout\_sumio=1 for sumio turned on). Ports CO and DO become input ports when the sumio path is turned on.

- Using the split IQ mode that merges channels A and B together to give more taps (split\_IQ=1).
- Using the double rate output mode (tout\_rate=2).

The output from the transmit output format block can be rounded to 12, 14, 16 or 22 bits using the toutf\_rnd\_AB control for the AO and BO ports, and toutf\_rnd\_CD control for the CO and DO ports. The settings are "3" for 12 bits, "2" for 14 bits, "1" for 16 bits and "0" for 22 bits. The output values are rounded into the MSBs of the final output word and the unused LSBs are cleared. The tout\_res control must also be set to 1 for the 22 bit output rounding option to be used.

The MSB of the final output words can be inverted (toutf\_offsetbin=1) to generate the offset binary output format required by many DACs.

**NOTE:**The MSB of the GC5016 output port must be connected to the MSB of the receiving device's input port.

**Table 3. DUC Output Formats**

Modes			Output Ports				CMD5016 Keyword Values		
Rate	Real or IQ	Sum	AO	BO	CO	DO	<i>tout_rate</i>	<i>tout_cmplx</i>	<i>tout_nsig</i>
The following modes assume no external sum IO with standard 16 bit resolution ( <i>tout_sumio</i> =0 and <i>tout_res</i> =0)									
full	real	none	AI	BI	CI	DI	1	0	4
full	real	pairs	(AI+BI)	(CI+DI)	off	off	1	0	2
full	real	all	(AI+BI+CI+DI)	off	off	off	1	0	1
full	IQ	pairs	(AI+BI)	(AQ+BQ)	(CI+DI)	(CQ+DQ)	1	1	2
full	IQ	all	(AI+BI+CI+DI)	(AQ+BQ+CQ+DQ)	off	off	1	1	1
half	IQ	none	AI, AQ	BI, BQ	CI, CQ	DI, DQ	0	1	4
half	IQ	pairs	(AI+BI), (AQ+BQ)	(CI+DI), (CQ+DQ)	off	off	0	1	2
half	IQ	all	(AI+BI+CI+DI), (AQ+BQ+CQ+DQ)	off	off	off			
The following modes assume external sum IO is used with standard 16 bit resolution ( <i>tout_sumio</i> =1 and <i>tout_res</i> =0)									
full	real	all	extl+(AI+BI+CI+DI)	off	extl (input port)	off	1	0	1
full	IQ	all	extl+ (AI+BI+CI+DI)	extQ+(AQ+BQ+CQ+DQ)	extl (input port)	extQ (input port)	1	1	1
half	IQ	all	extl+ (AI+BI+CI+DI), extQ+(AQ+BQ+CQ+DQ)	off	extl, extQ (input port)	off	0	1	1
The following modes assume external sum IO is used with wide 22 bit resolution ( <i>tout_sumio</i> =1 and <i>tout_res</i> =1)									
full	real	all	16 MSBs of extl+(AI+BI+CI+DI)	6 LSBs of extl+(AI+BI+CI+DI)	16 MSBs of extl (input port)	6 LSBs of extl (input port)	1	0	1
half	IQ	all	16 MSBs of extl+ (AI+BI+CI+DI), extQ+(AQ+BQ+CQ+DQ)	6 LSBs of extl+ (AI+BI+CI+DI), extQ+(AQ+BQ+CQ+DQ)	16 MSBs of extl, extQ (input port)	6 LSBs of extl, extQ (input port)	0	1	1
The following modes are for splitIQ, no external sum IO, and standard resolution ( <i>split_IQ</i> =1, <i>tout_sumio</i> =0, <i>tout_res</i> =1)									
full	real	none	ABI	CDI	off	off	1	0	2
full	real	all	(ABI+CDI)	off	off	off	1	0	1
full	IQ	none	ABI	ABQ	CDI	CDQ	1	1	2
full	IQ	all	(ABI+CDI)	ABQ+CDQ	off	off	1	1	1
half	IQ	none	(ABI, ABQ)	CDI, CDQ	off	off	0	1	2
half	IQ	all	ABI+ABQ, CDI+CDQ	off	off	off	0	1	1
The following modes are for splitIQ, using external sum IO, and standard resolution ( <i>split_IQ</i> =1, <i>tout_sumio</i> =1, <i>tout_res</i> =0)									
full	real	all	extl+(ABI+CDI)	off	extl (input port)	off	1	0	1
full	IQ	all	extl+(ABI+CDI)	extQ+(ABQ+CDQ)	extQ (input port)	off	1	1	1
half	IQ	all	extl+(ABI+ABQ), extQ+(CDI+CDQ)	off	extl, extQ (input port)	off	0	1	1
The following modes are for splitIQ, using external sum IO, and wide resolution ( <i>split_IQ</i> =1, <i>tout_sumio</i> =1, <i>tout_res</i> =1)									
full	real	all	16 MSBs of extl+(ABI+CDI)	16 MSBs of extl+(ABI+CDI)	16 MSBs of extl (input port)	16 MSBs of extl (input port)	1	0	1
half	IQ	all	16 MSBs of extl+(ABI+ABQ), extQ+(CDI+CDQ)	6 LSBs of extl+(ABI+ABQ), extQ+(CDI+CDQ)	16 MSBs of extl, extQ (input port)	6 LSBs of extl, extQ (input port)	0	1	1
The following modes are for double rate output, no external sum IO, standard resolution ( <i>split_IQ</i> =1, <i>tout_rate</i> =2, <i>tout_sumio</i> =0, <i>tout_res</i> =0)									
double	real	none	ABleven	ABlodd	CDleven	CDlodd	2	0	2
double	real	all	ABleven+CDleven	ABlodd+CDlodd	off	off	2	0	1
double	IQ	all	ABleven+CDleven	ABQeven+CDQeven	ABlodd+CDlodd	ABQodd+CDQodd	2	1	1
The following mode is for double rate output, with external sum IO, and standard resolution ( <i>split_IQ</i> =1, <i>tout_rate</i> =2, <i>tout_sumio</i> =1, <i>tout_res</i> =0)									
double	real	all	extleven +ABleven+CDleven	extlodd+ABlodd+CDlodd	extleven (input port)	extlodd (input port)	2	0	1

## 14.9 The Sum Tree

Figures 24 and 25 show the sum tree and transmit output format blocks when all four channels are added together, including the sum IO path. Figure 24 shows the data paths for the standard 16-bit resolution mode ( $tout\_res=0$ ). Figure 25 shows the wide resolution mode ( $tout\_res=1$ ).

The mixer outputs are rounded to 21-bits. This includes a 1-bit growth as the partial products of the complex multiply are added together (effectively a gain relative to the msb of 0.5). The sum tree adds up to four up-conversion channels together producing a 23-bit output (and a gain for any channel of 1/4). The 23-bit sum tree output is shifted down by four bits and rounded to 19 bits before being added into the LSBs of the external 22-bit sum input. The gain through the mixer, sumtree, and sumIO is equal to  $2^{-7}$ . When sumIO is bypassed (no sum-in) or is in the 16-bit mode, there is no shift down by the four bits, so the gain through the mixer, sumtree, and sumio are equal to  $2^{-3}$ .

The final 22-bit sum is scaled up by 0 to 7 bits ( $sum\_shift$ ), checked for overflow, and then sent on to the transmit output formatter. After scaling, the output data is rounded. Overflows in the sum tree are saturated to plus or minus full scale. Hard limiting occurs after shifting and rounding. In normal applications, the data would be rounded to the size of the digital to analog converter (DAC). The data is rounded into the uppermost bits and the unused lower bits are cleared. For applications using sum inputs from other GC5016 chips, rounding should be to 22 bits for all chips except the GC5016 just prior to the DAC.

The latency from the sum input port CO and DO to the output ports AO and BO is 14 clock cycles.

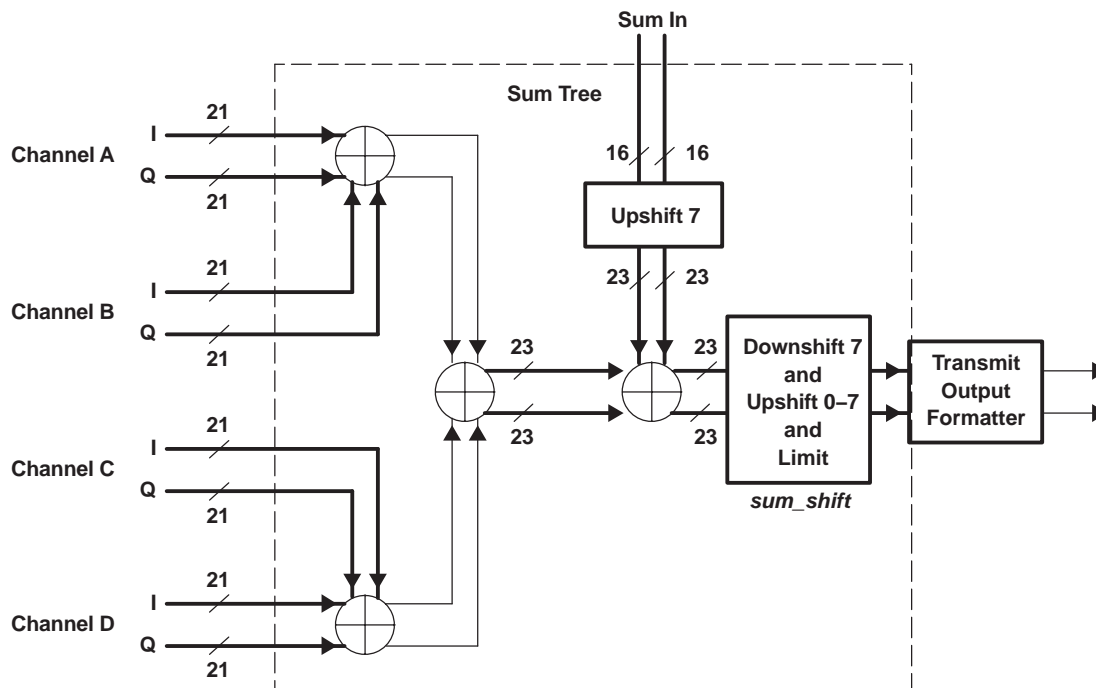
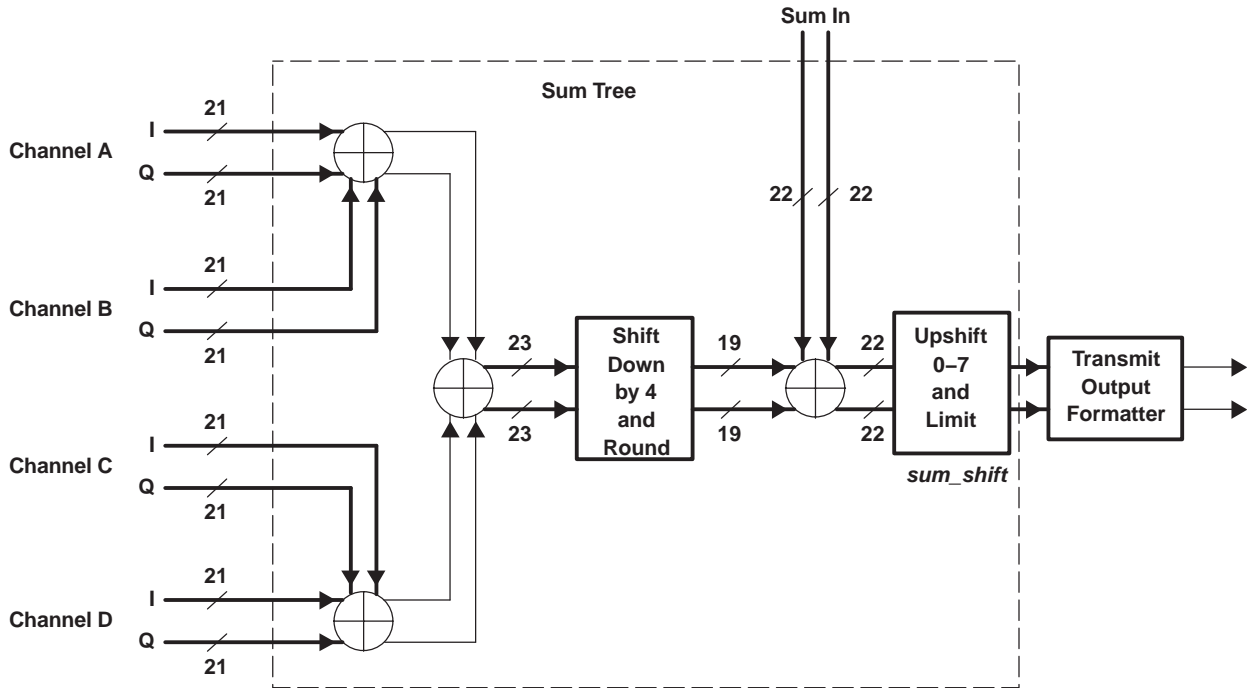


Figure 24. Sum Tree and Transmit Output Formatter – 16-Bit SumIO Mode





**Figure 25. Sum Tree and Transmit Output Formatter – 22-Bit SumIO Mode**

## 14.10 Sum and Format Details

Figure 26 shows the sum and format blocks in more detail. Normally the configuration software is used to set all these parameters (see Table 4 and Figure 26).

Figure 26 shows the sum and format blocks in more detail. Normally the cmd5016 configuration software uses just `tout_res`, `tout_sumio`, `tout_cmplx`, `tout_nsig`, `overall_gain` and `split_IQ` to set all the parameters shown in Figure 26. Details of the implementation are provided in the following sections for special applications where the parameters may want to be set manually. Using manual settings is discouraged and should not be necessary.

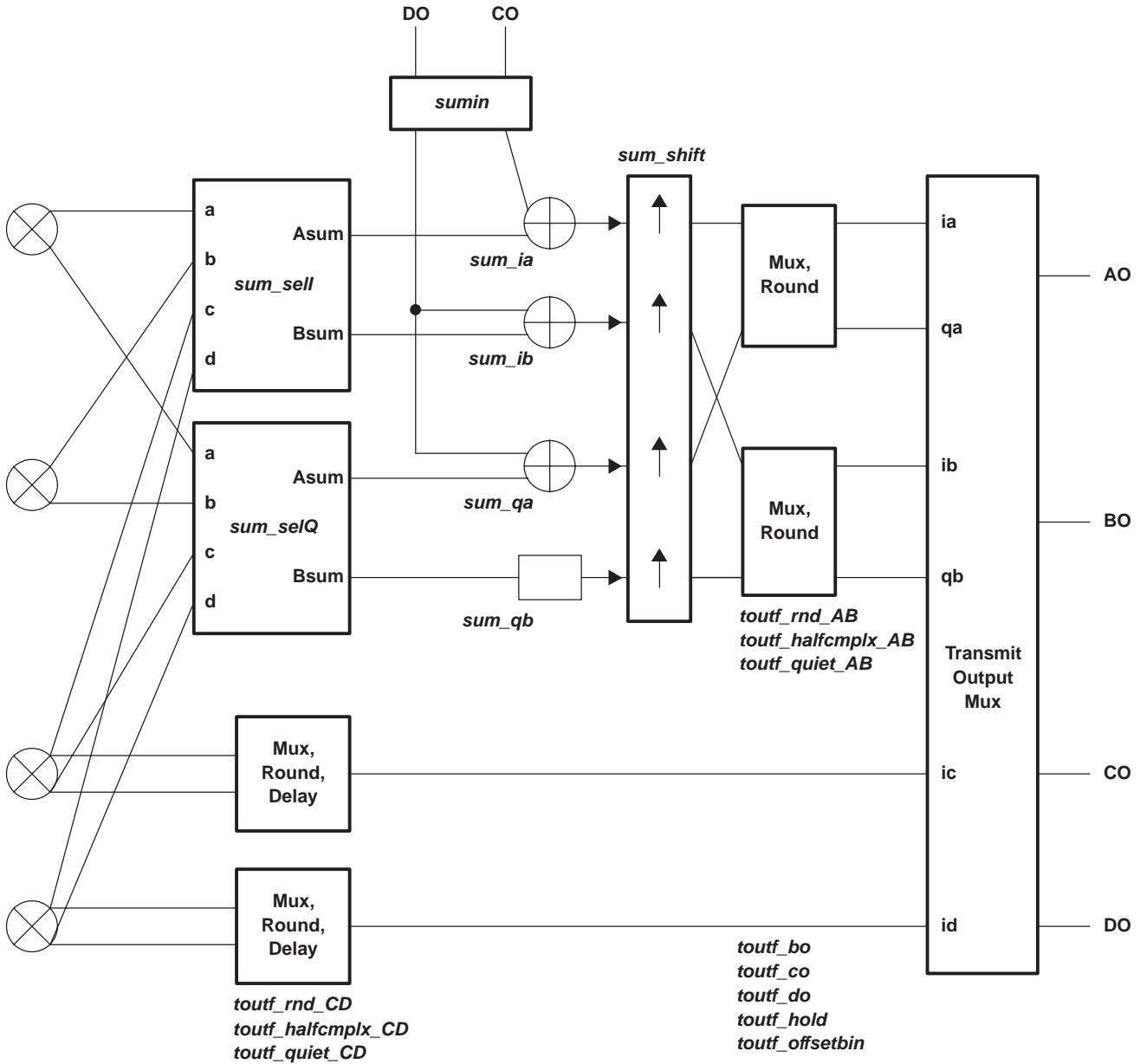


Figure 26. Transmit Sum and Output Format Details

### 14.10.1 Sum Selection

Data from the four complex mixers (mixA–D) is sent to sum and selection blocks. The I data from the four mixers is combined (controlled by *sum\_sel*) into two outputs, *Asum* and *Bsum*. Likewise, Q data is combined (controlled by *sum\_selQ*). The *sum\_sel* and *sum\_selQ* controls are 8-bit values with bits (s7..0). The *Asum* output is:

Sum Select setting:

$$Asum = s0 \times (s1 \times a + s2 \times b + s3 \times c) + s4 \times (s5 \times d + s6 \times b + s7 \times c)$$

The *Bsum* output is:

$$Bsum = s5 \times d + s6 \times b + s7 \times c.$$

Table 4 shows four common configurations. There is a constraint that *s2* and *s3* may not both be one. Likewise for *s6* and *s7*.

**Table 4. Sum Selection Settings**

Sum_sel setting	Asum	Bsum
0x0	0	0
0x43	a	b
0xA7	a+b	c+d
0xB7	a+b+c+d	c+d

### 14.10.2 Sumin Port for Cascading Chips

If `sumin` is active, the ports `CO` and `DO` are used as inputs (reducing the number of outputs available). The control `sumin` determines the format of the sum in port data. Both outputs are forced to zero when `sumin=0`.

When `sumin = 1`, a 22-bit half-rate complex `sumin` path is formed. The 22 bits are mapped to `CO` and `DO` as `sumin[21..6] ≥ CO[15..0]` and `sumin[5..0] ≥ DO[15..10]`. The `I` word is identified by the `cic` sync. `Iflag` is high when the `I` word is expected as an input. The `sumin-to-sumout` delay is 14 clocks, so when `Iflag` is high the `I` word is being output. Summers `ib` and `qb` would be programmed off since only one path is available.

When `sumin=2`, `CO[15..0]` is passed as a 16-bit value to the sum node controlled by `sum_ia`. `DO[15..0]` is passed to both `sum_ib` and `sum_qa`. This format is useful for using a `sumin` path with double rate real, full-rate complex, or two full rate real channels. Due to the limitations of the 16-bit `sumpath`, gain and SNR need to be carefully analyzed to see if they satisfy the system requirements. In the case of double rate, real summers `qa` and `qb` would be programmed off, `CO` would add to `ia`, and `DO` would add to `ib`. `CO` should contain  $I(2k)$ , while `DO` contains  $I(2k+1)$ . For full-rate complex summers, `ib` and `qb` would be programmed off, `CO` would add to `ia`, and `DO` would add to `qa`. Finally, for two channels of full-rate real summers, `qa` and `qb` would be programmed off, while `CO` would add to `ia` and `DO` would add to `ib`.

Finally, when `sumin = 3`, a 22-bit full rate `sumin` path is formed (most common application using `sumin`). In this case summers `ib`, `qa`, and `qb` are all off. Gain is identical to the 22-bit half-rate complex case discussed above.

If an application calls for both a `sumin` port and transmit output hold, then the output hold should only be applied to the last chip in a chain.

When cascading chips, `sum_shift` should be set only on the last chip in the chain, it should be 0 in the others. When using a 22-bit sum chain, rounding should be set to 22 bits in all chips except the final one, where the rounding is set appropriate to the next stage in processing (typically a DAC). Likewise, when using a 16-bit sum chain, rounding should be set to 16 bits in all chips except the final one.

### 14.10.3 Sum Shift

The four paths (`ia`, `qa`, `ib`, and `qb`) are then upshifted by 0–7 (`sum_shift`). For most applications, different channels added together are independent and their powers should be added in a root-sum-square manner. For optimal performance, gains should be optimized into the D/A, since that is the dominant source of noise. Once the desired level into the DAC is found, gains for the rest of the signal processing chain can be derived. The hardwired gains through the mixer, `sumtree`, and `sumio` are set to allow maximal signal growth. The sum shifter allows adjustment in gain for other situations. The mixer allows 1 bit of growth (when one adds  $\text{real} \times \sin + \text{imag} \times \cos$ ). The 2-bit growth in the sum tree allows for four channels to be added together inside the chip. The 3-bit growth in the `sumio` (22-bit mode) allows up to 8 GC5016 chips to be cascaded without any clipping prior to the final output shift and round.

With a 16-bit `sumio` path we can not afford to be so generous with bit growth. Hence, gains with a 16-bit data path are 1 bit in the mixer and 2 bits in the sum tree. This allows a total growth of 3 bits (maximum of four channels for absolutely no clipping or 64 users using RMS) – the user is still limited by signal power per channel in the DAC.

Note that there is no shifter on paths `ic` and `id`. These paths are used only when there is no summing, no `sum_in`, and four channels are output (or two channels at double rate). The gain on paths `ia` and `ib` can be forced to match `ic` and `id` by setting `sum_shift` to 3.

### 14.10.4 Output Rounding and I/Q Multiplexing

The data on paths A and B next enter mux and round. Multiplexing allows I and Q to be time multiplexed onto the same set of pins. Effectively, this decimates the signal by two and the sync source for this decimation is the `cic_sync`. Finally, `toutf_rndAB` controls rounding of bits from the bottom, so the resulting word is 12 (3), 14 (2), 16 (1), or 22 (0) bits. Bits below the round point are forced to zero. After rounding, the data is hard limited. Paths `ia`, `qa`, `ib`, and `qb` are 22 bits.

Processing on paths C and D is similar. If channels are added together, channels C and D are routed up and added into paths A and B. If all four channels are output separately then the mux, round, and delay blocks on paths C and D are used. The C and D data is delayed to match hardware pipelining delay on paths A and B. Since there is no summing gain, a fixed upshift of one bit is provided to compensate for the one bit of headroom in the mixer output. The blocks can either output the real data or IQ multiplexed (`toutf_halfcmplx_CD=1`). Paths `ic` and `id` out of these blocks are limited to 16 bits, since that matches the size of the output ports. Control `toutf_rndCD` determines the round. Since the path is limited to 16 bits, both `toutf_rndCD=0` and `toutf_rndCD=1` round to 16 bits. If paths C and D are unused here (for example when adding paths C and D into paths A and B), then setting `toutf_quiet_CD` forces an overflow condition, thus holding the bus constant (and quiet).

### 14.10.5 Transmit Output Multiplexing

The final block can invert the msb (`toutf_offsetbin`) for systems that prefer offset binary output to two's complement. Port AO always outputs `ia`.

Port BO can output zeros (`toutf_bo=0`), `ib` (`toutf_bo=1`), `qa` (`toutf_bo=2`), the lsb's of `ia` (`toutf_bo=4`), or the complement of AO (`toutf_bo=8`). Setting 4 is used to support output word sizes greater than 16 bits. If 22 bits are output, then AO gets bits 21..6, while BO[15..10] gets bits 5..0. The remainder of BO is zero. Finally, setting 8 sets BO to be the complement of AO. This can be used together with external resistor packs to create LVDS outputs. Other settings for `toutf_bo` are undefined.

Port CO can output zeros (`toutf_co =0`), `ic` (`toutf_co =1`), `ib` (`toutf_co =2`), or `qa` (`toutf_co =4`). Other settings for `toutf_co` are undefined.

Port DO gets zeros (`toutf_do =0`), `id` (`toutf_do =1`), `qb` (`toutf_do =2`), `ib` lsb's (`toutf_do =4`), `qa` lsb's (`toutf_do =8`), or CO complement (`toutf_do =16`). Other settings for `toutf_do` are undefined.

## 14.11 Overall Gain in Transmit Mode

The overall gain in the transmit mode is defined below. The gain is normally set using the `overall_gain` keyword in the `cmd5016` configuration software. The overall gain is set relative to the MSB of the input data to the MSB of the output data. For example, if `overall_gain` is set to 1.0, then a full scale input sample will result in a full scale output sample. This allows the user to set the gain based upon the desired input and output crest factors. Note that the gain is for each channel, if multiple DUC channels are added together then the `overall_gain` should be decreased to compensate for the increased crest factor. See the "DUC Mode GAIN" application note for complete details.

The gain of the chip is a function of the input gain setting (`G`), the sum of the programmable filter coefficients, the filter gain (`fir_shift`), the amount of interpolation in the CIC filters (`cic_int`), the scale circuit settings in the CIC filter (`cic_shift`), and the sum tree scale factor (`sum_shift`). The overall gain (22-bit sumio mode) is:

$$\text{GAIN} = \left\{ \left( \frac{G}{4096} \right) \left( \frac{\text{PFIR\_SUM}}{\text{fir\_int} \times 2^{21-\text{fir\_shift}}} \right) \text{cic\_int}^{(5-\text{cic\_xmt\_5stg})} 2^{\text{cic\_shift}-41} \right\} 2^{\text{sum\_shift}-6}$$

where `cic_int`, `G`, `PFIR_SUM`, and `fir_shift` can be different for each channel, but `sum_shift` is common to all channels. The term inside { } should be less than or equal to one. For no sumio or 16 bit sumio modes, the gain is:

$$\text{GAIN} = \left\{ \left( \frac{G}{4096} \right) \left( \frac{\text{PFIR\_SUM}}{\text{fir\_int} \times 2^{21-\text{fir\_shift}}} \right) \text{cic\_int}^{(5-\text{cic\_xmt\_5stg})} 2^{\text{cic\_shift}-41} \right\} 2^{\text{sum\_shift}-3}$$

$$\text{GAIN} = \left\{ \left( \frac{G}{4096} \right) \left( \frac{\text{PFIR\_SUM}}{\text{fir\_int} \times 2^{21-\text{fir\_shift}}} \right) \text{cic\_int}^{(5-\text{cic\_xmt\_5stg})} 2^{\text{cic\_shift}-41} \right\}$$

## 15 GC5016 IN TRANSCEIVER MODE

The GC5016 can also be configured in a transceiver mode as shown in Figure 3, where channels A and B function in up-conversion mode and channels C and D function in down-conversion mode. The channel details for A and B are identical to those described above for the up-conversion mode. The channel details for C and D are identical to those above for down-conversion mode. Two input ports and two output ports are available each for the up-conversion channels and down-conversion channels.

The down-conversion interfaces are described in the Receive (DDC) section. The up-conversion interfaces are described in the Transmit (DUC) section. The Sumin port function is not available in transceiver mode.

The splitiq\_AB, and splitiq\_CD cmd5016 variables are used for special Transceiver conditions. In this example, the Channel A and B are configured as a splitQ DUC section, and Channels C and D are configured as individual DDC channels.

## 16 GENERAL GC5016 FEATURES

### 16.1 Control Interface

Writing control information into control registers configures the GC5016. The control registers are grouped into eight global registers and 88 pages of registers, each page containing up to 16 registers. The global registers are accessed as addresses 0 through 0xF.

The non-global pages of registers are accessed as addresses x10 through x1f. The control register at global address 0x2 is the page register. The value written to the page register selects which page is accessed for addresses 16(x10) through 31(x1f).

The contents of the control registers and how to use them are described in tables 8 through 67 later in the data sheet.

The registers are written to or read from using the C[15..0], A[4..0],  $\overline{CE}$ ,  $\overline{RD}$ , and  $\overline{WR}$  pins. Each control register has been assigned a unique address within the chip. This interface is designed to allow the GC5016 chip to appear to an external processor as a memory mapped peripheral (the pin  $\overline{RD}$  is equivalent to a memory chip's OE pin).

The dual strobe and single strobe cycles are selected based on the  $\overline{RD}$  pin:

1. If the  $\overline{RD}$  and  $\overline{WR}$  pins are used as separate strobes, this is the dual strobe mode.  $\overline{CE}$  and  $\overline{RD}$  are required for the read cycle.  $\overline{CE}$  and  $\overline{WR}$  are required for the write cycle.
2. If the  $\overline{RD}$  pin is grounded, this is considered the single strobe mode. The level of the  $\overline{WR}$  pin while the  $\overline{CE}$  pin is active, determines the read or write cycle.

Write timing is controlled by the WRMODE pin:

1. If the WRMODE pin is '0', the write timing is edge based. The data bus must be stable for a setup time before and a hold time after ( $\overline{CE}$  or  $\overline{WR}$ ) goes high
2. If the WRMODE pin is '1', the write timing is latch based. The data bus must be stable for a setup time before ( $\overline{CE}$  and  $\overline{WR}$ ) goes low and a hold time after ( $\overline{CE}$  or  $\overline{WR}$ ) goes high.

**NOTE:**The suggested external processor interface is dual strobe and edge-WRMODE, where the WRMODE pin is connected to GND.

## 16.2 Dual Strobe, Edge Mode ( $\overline{\text{WRMODE}} = 0$ ), Control Bus Timing (See Figures 27 and 28)

In this mode, an external processor (a microprocessor, computer, or DSP chip) can write into a register by setting  $\text{A}[4..0]$  to the desired register address, setting  $\overline{\text{RD}}$  high, selecting the chip by setting  $\overline{\text{CE}}$  low, then strobing  $\overline{\text{WR}}$  low. The write cycle is active while both  $\overline{\text{CE}}$  and  $\overline{\text{WR}}$  are low. Data on the  $\text{C}[15..0]$  is registered into the chip on the rising edge of  $\overline{\text{WR}}$ . (see Figure 28)

The external processor reads from a control register by setting  $\text{A}[0:4]$  to the desired address, select the chip with the  $\overline{\text{CE}}$  pin, and then set  $\overline{\text{RD}}$  low. The chip then drives  $\text{C}[0:15]$  with the contents of the selected register. After the processor has read the value from  $\text{C}[0:15]$  it should set  $\overline{\text{RD}}$  and  $\overline{\text{CE}}$  high (see Figure 27).

The  $\text{C}[0:15]$  pins are turned off (high impedance) whenever  $\overline{\text{CE}}$  or  $\overline{\text{RD}}$  are high or when  $\overline{\text{WR}}$  is low.

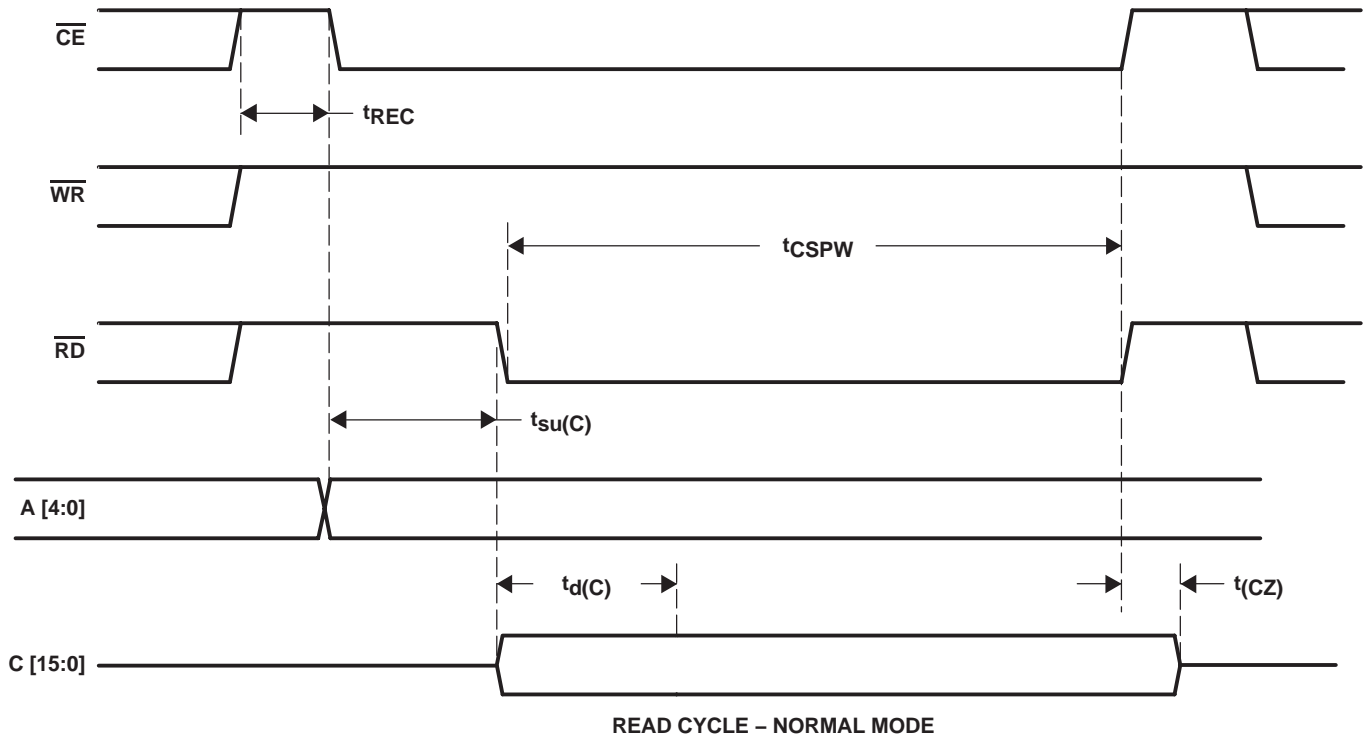


Figure 27. Dual Strobe Read Timing

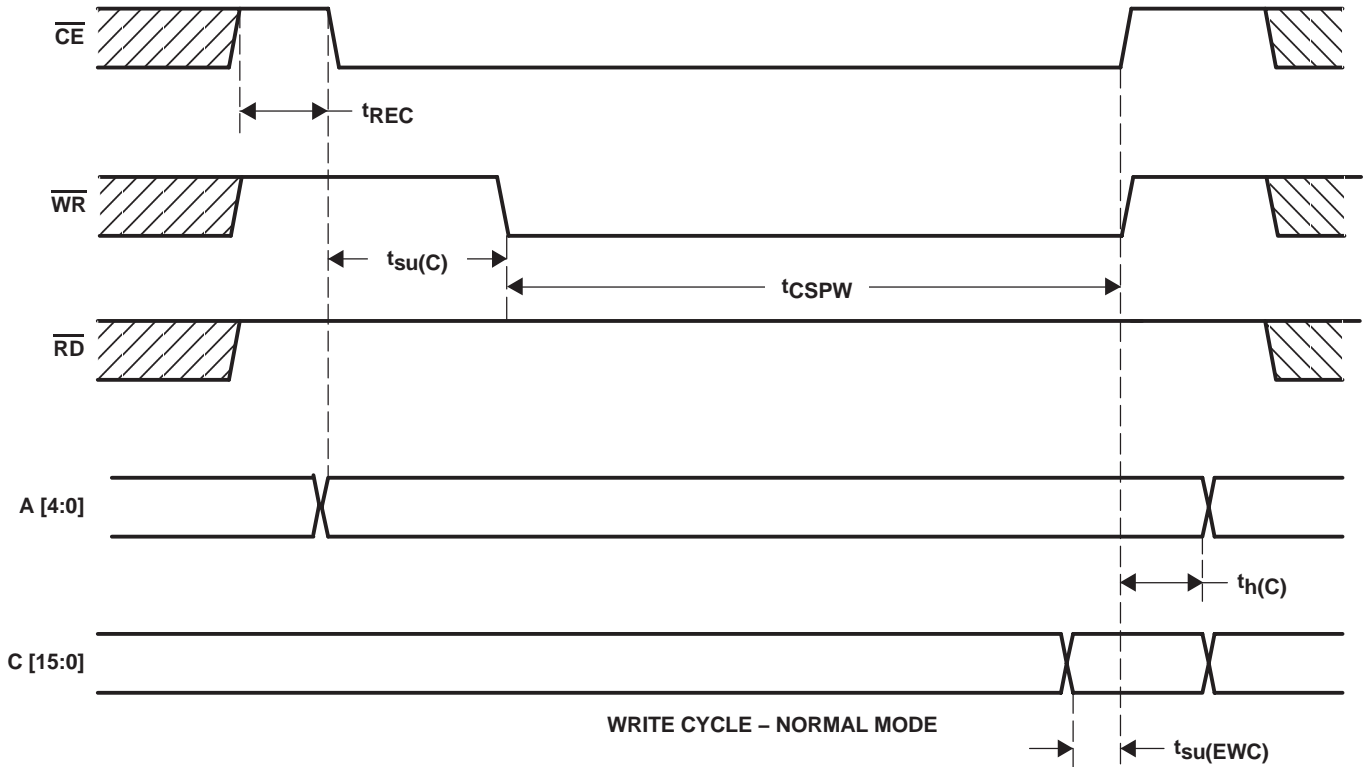


Figure 28. Dual Strobe Edge Mode Write Timing

### 16.3 Single Strobe, Edge Mode ( $WRMODE = 0$ ), Control Bus Timing (See Figures 29 and 30)

Some processors provide a single control  $\overline{RD}/\overline{WR}$  together with a chip strobe that controls timing. In this case, the  $\overline{RD}$  pin can be grounded. The control processor must set  $A[4..0]$  to the desired register address, set  $\overline{WR}$  low for a write or high for a read, and select the chip by setting  $\overline{CE}$  low. The write cycle is active while both  $\overline{CE}$  and  $\overline{WR}$  are low. Data on the  $C[15..0]$  is registered into the chip on the rising edge of  $\overline{CE}$ .

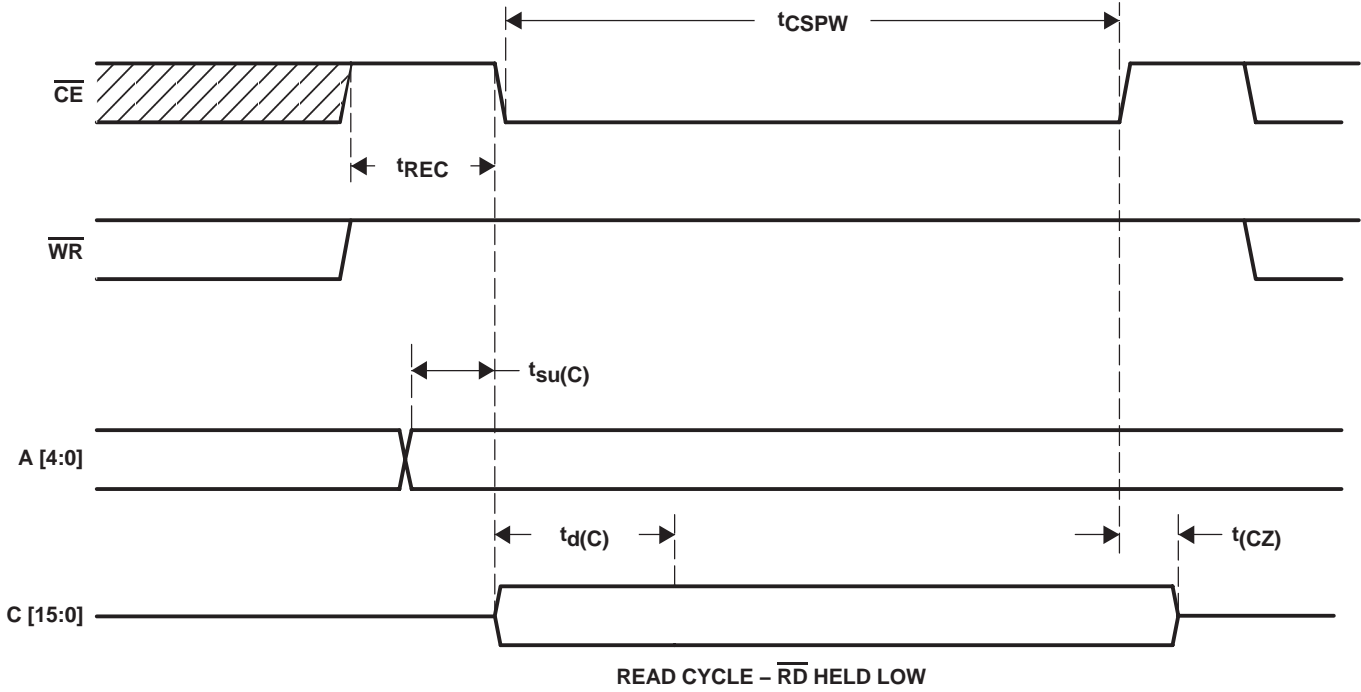


Figure 29. Single Strobe Read Timing

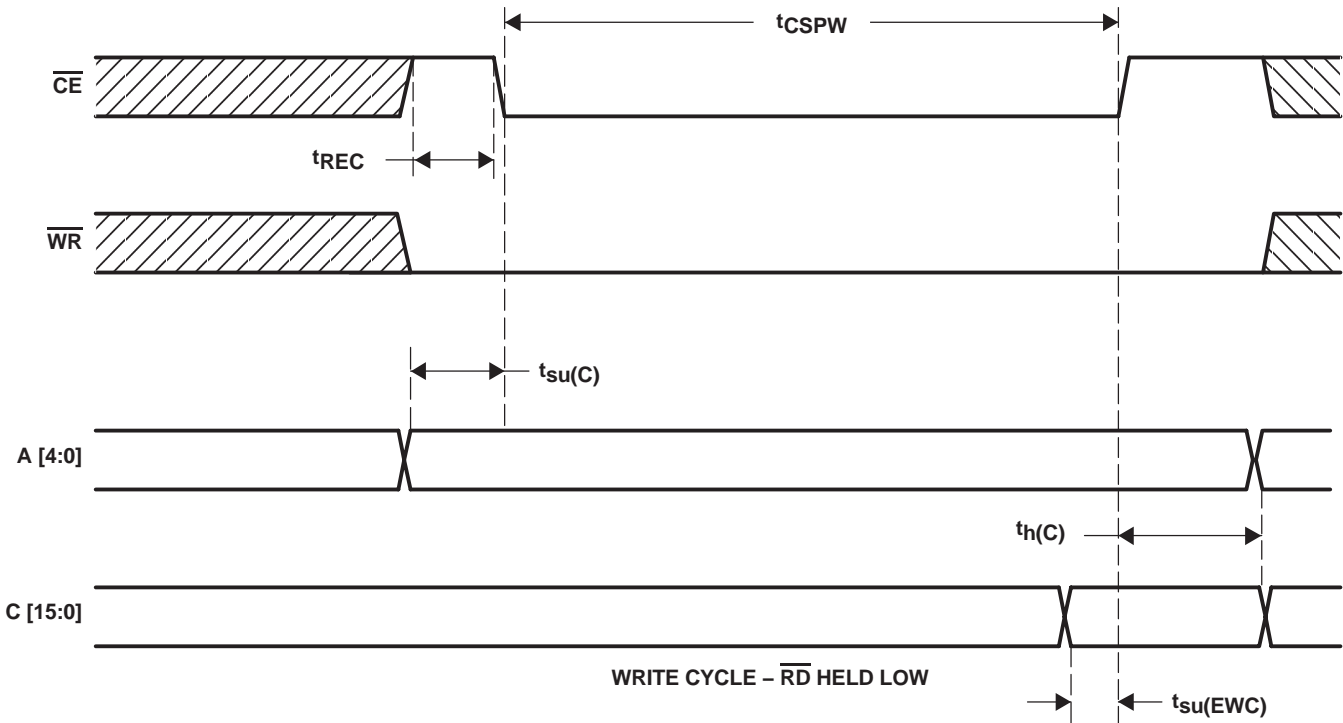


Figure 30. Single Strobe, Edge Mode Write Timing



### 16.4 Dual Strobe, Latch Mode(WRMODE = 1), Control Bus Timing (See Figure 31)

Latch mode (WRMODE=1) is used if the data is stable over the entire time period the write strobe is active. The data on C[15..0] is transferred to the control registers during the entire time both  $\overline{\text{WR}}$  and  $\overline{\text{CE}}$  are low. Since some control registers (such as most sync registers) are sensitive to transient values on the C[0:15] data bus, the data must be stable during the entire write pulse in this mode.

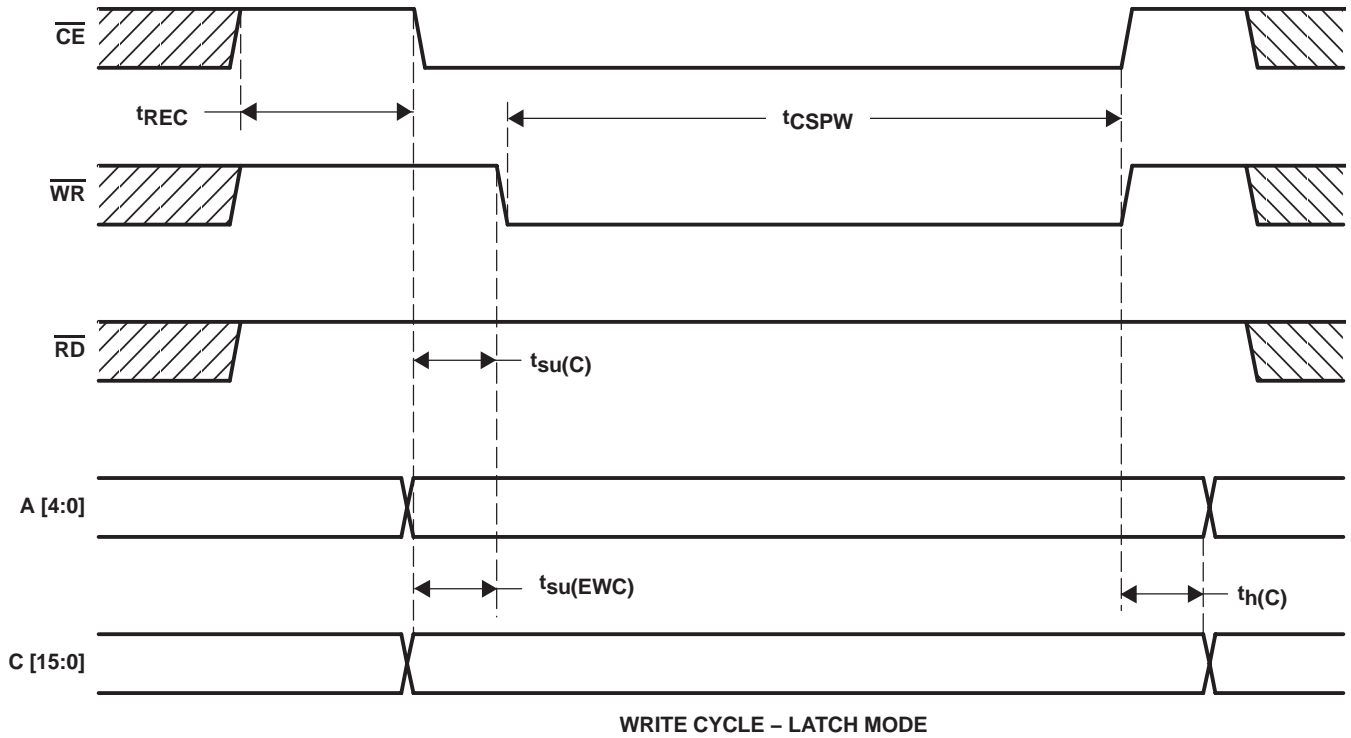


Figure 31. Dual Strobe Latch Mode Write Timing

## 16.5 Single Strobe, Latch Mode(WRMODE = 1), Control Bus Timing (See Figure 32)

The user can also use the latch mode with a single strobe, as shown in Figure 32.

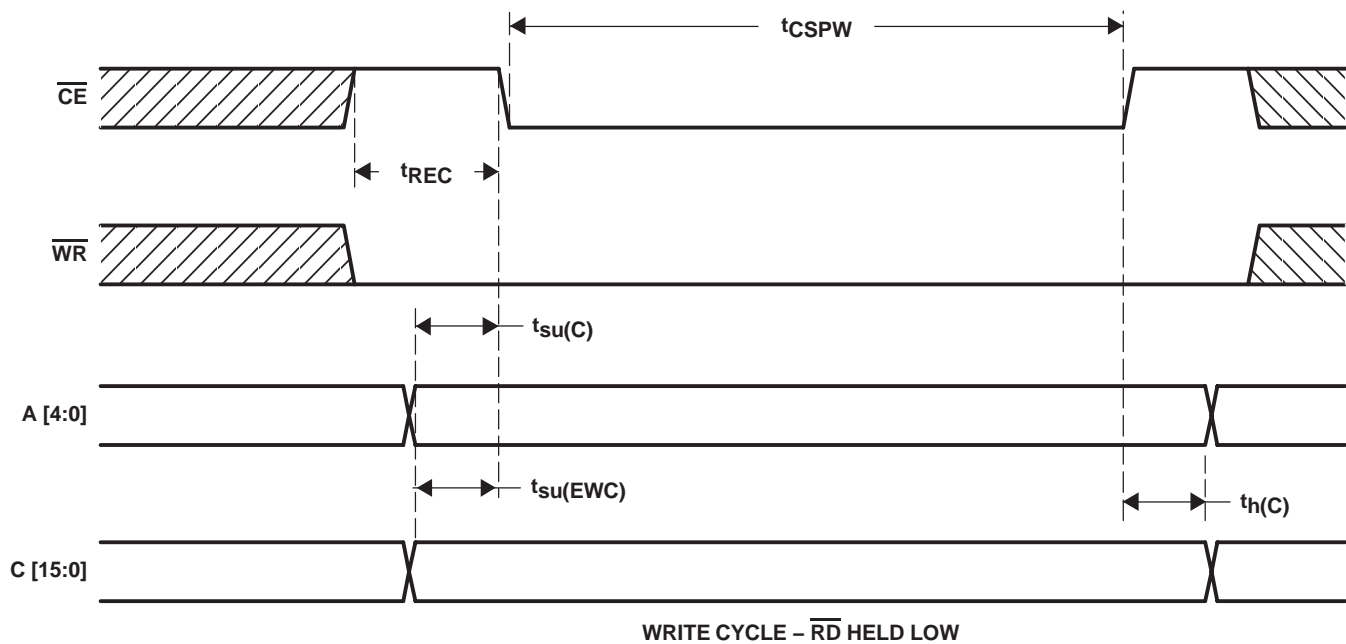


Figure 32. Single Strobe Latch Mode Write Timing

## 16.6 Clocking

The GC5016 uses a single clock, CK to sample, process, and output data. The same clock is used throughout the chip (gated in some areas to save power). Note that `rinf_zpad` can be used to allow the input sample rate (in receive) to be a fraction of the chip clock rate. The `toutf_hold` can be used to allow the output sample rate (in transmit) to be a fraction of the chip clock rate. All channels use the same clock.

## 16.7 Power-Down Modes

The GC5016 allows software control to power down each of the four channel filters and each of the two `cic/mix` blocks. When a block is powered down, control registers are not altered. The state machines and data paths are put into a reset state. This is used to reduce the core GC5016 power, for unused channels. Channels that have been placed in power down mode, must be resynchronized after power-on, before use.

## 16.8 Synchronization

Each GC5016 chip can be synchronized through the use of internal or external signals. There are two sync input signals, an internal one shot sync generator, or a sync counter. The sync to each circuit can also be set to be always on (active) or always off (never asserted). The 3-bit sync mode control for each sync circuit is defined in Table 5. A `cmd5016` software command, `sync_mode`, can be used to setup the channel and start-up synchronization. The value determined for synchronization, are shown in the TBL file.

In the Down Conversion process, the `rinf_zpad_sync`, `cic` filter, `pfir` filter, and `sck_sync` will typically require synchronization. The `rinf_zpad_sync` is only used if the DDC input uses the receive interpolation or the IQ multiplexed input modes. The `cic_sync` is used to select the synchronization of the `cic` filter decimation. The `fir_sync` and `cic_sync` need to be selected to a common sync signal. The `fir_sync` selects the synchronization signal for the filter's decimation, address generators, and state machines. The `coef_sync` is used if multiple coefficient banks are desired, and a sync is used for selection. The `sck_sync` is used to synchronize the divided clock (if used) for the Receive Output interface.

In the Up Conversion process, the *sck\_sync*, *pfir* filter, *cic* filter, and *toutf\_hold\_sync* will typically require synchronization. The *sck\_sync* is used to synchronize the divided clock. The *fir\_sync* is used to synchronize the PFIR. The *coef\_sync* is used to synchronize switching between two banks of coefficients. The *cic\_sync* and *fir\_sync* need to be selected to a common sync signal. The *toutf\_hold\_sync* is used to synchronize the decimation of the real or parallel IQ data DUC output.

**Table 5. Sync Modes**

MODE	SYNC SOURCE
0, 1	Off (never asserted)
2	$\overline{SIA}$
3	$\overline{SIB}$
4	<i>one_shot</i>
5	TC (terminal count (general timer))
6, 7	On (always active)

NOTE: The internal syncs are active high. The  $\overline{SIA}$  and  $\overline{SIB}$  inputs have been inverted to be the active high syncs  $\overline{SIA}$  and  $\overline{SIB}$  internally.

The *one\_shot* can either be a level or a pulse as described in Table 15. The level mode is used to initialize the chip; the pulse mode is used to synchronously switch frequency, phase, or gain values.

The  $\overline{SIA}$  input can then be used to initialize and flush the channels and the  $\overline{SIB}$  sync input can be used, if desired, to synchronize the phases of the NCOs.

The recommended sync mode settings are summarized in Table 6.

The  $\overline{SIA}$  and  $\overline{SIB}$  sync inputs are either connected to a user defined sync generator, for example, an FPGA, or are tied to a GC5016 chip's sync output pin (SO). If there are multiple GC5016 chips in the system, then the SO pin of one chip can be used to drive the  $\overline{SIA}$  input of all chips, and the SO pin of another chip can drive the  $\overline{SIB}$  inputs of all chips. This arrangement allows the user to use the SO sync output to synchronously drive the  $\overline{SIA}$  or  $\overline{SIB}$  sync inputs of other GC5016s. The sync source for SO is selected using the *soB\_sync* control bits in address 1.

**Table 6. Recommended Sync Settings**

Global Syncs (Address 1)			Channel Syncs (Pages 0x14, 0x34, 0x54, and 0x74 Address 0x15)		
Sync	Value	Description	Sync	Value	Description
<i>soB_sync</i>	4 (OS)	The SO output is used during initialization	<i>fir_sync</i>	2 ( $\overline{SIA}$ )	Sync FIR during initialization
<b>CIC and Mixer Syncs (Page 0x80 and 0xa0, Addresses 0x16 and 0x1E)</b>			<i>coef_sync</i>	7 (always)	For use with multiple coefficient sets
<i>gain_sync</i>	4 (OS)	Sync gain when changing base value. Manual Gain set to 6,7, for DDC AGC set to initial sync source. In DUC mode set to always.	<i>freq_sync</i>	7 (always)	Use frequency settings as they are loaded
<i>phase_sync</i>	7 (always)	Use phase settings as they are loaded	<i>pwr_mtr_sync</i>	2 ( $\overline{SIA}$ )	Synchronization starts a new $I^2+Q^2$ accumulation cycle
<i>dith_sync</i>	0 (never)	Can free run. Set to 7 (always) to disable	<i>sck_sync</i>	2 ( $\overline{SIA}$ )	Sync the serial clock during initialization
<i>nco_sync</i>	3 ( $\overline{SIB}$ )	For NCO updates. Disrupts signal processing when sync occurs.			
<i>flush_sync</i>	0 (never)	Set CIC integrator to 0, set to 0 for DDC, and sync source for DUC (shouldn't be repetitive sync)			
<i>cic_sync</i>	2 ( $\overline{SIA}$ )	Sync CIC during initialization			

It is important that the synchronization source has an active SYNC signal when the Reset signal is released during the initial GC5016 programming.

Repetitive synchronization, if used, requires a logic low Sync input that is one CK period wide.

The cmd5016 programming software has a pseudo-command 'sync\_mode'. The sync\_mode is used to set up common synchronization modes for all of the sync registers. It has the added benefit of adding the assert-sync, remove-reset, and remove-sync. See the Programming GC5016 application note for more information on this command and its use.

The sync\_mode keyword can accept the following values:

- 0,  $\overline{SIA}$  selected for sync source
- 1,  $\overline{SIB}$  selected for sync source
- 4, One Shot Sync Out, (external SOB to  $\overline{SIA}$ ) connected to  $\overline{SIA}$ , level
- 5, One Shot Sync Out, (external SOB to  $\overline{SIA}$ ) connected to  $\overline{SIA}$ , pulse
- 6, One Shot Sync Out, (external SOB to  $\overline{SIB}$ ) connected to  $\overline{SIB}$ , level
- 7, One Shot Sync Out, (external SOB to  $\overline{SIB}$ ) connected to  $\overline{SIB}$ , pulse
- 8, internal one shot, level triggered
- 9, internal one shot, pulse triggered

## 16.9 Initialization

Three initialization procedures are recommended. The first is for standalone GC5016 chips, the second is for a multi-GC5016 chip configuration synchronized by a master GC5016 chip, and the third is for a configuration where the GC5016s are to be synchronized by to an external source.

### 16.9.1 Standalone GC5016 Chips

This procedure works if the GC5016 can free run and its timing doesn't need to be synchronized with other chips (FPGAs, other GC5016s, etc.).

1. Reset the chip by writing 0xFF00 to address 0.
2. Disable all outputs by writing 0 to address 3.
3. Force the one-shot to be a pulse by writing 0x04 to address 1.
4. Load the configuration generated by the cmd5016 program.

**NOTE:**All sync controls that need to select a sync source should be set to 4, (one shot).

This can be done by adding these lines to the cmd5016 input file:

```
soB_sync 4
fir_sync 4
sck_sync 4
nco_sync 4
cic_sync 4
```

5. Clear the reset by writing 0x100 to address 0.
6. Pulse the syncs by writing 0x04 to address 1

**NOTE:**The above procedure is selected by setting pseudo-command sync\_mode to '9'.

### 16.9.2 Multiple GC5016 Chips Using $\overline{SO}$ From a Master GC5016 Chip

This procedure works if multiple GC5016 chips need to be synchronized. This assumes that the sync output pin ( $\overline{SO}$ ) from the master GC5016 chip is connected to the  $\overline{SIA}$  input pin on all GC5016 chips including the master chip.

1. Reset the chip by writing 0xFF00 to address 0 of all chips.
2. Disable all outputs except  $\overline{SO}$ , by writing 0x100 to address 3 of all chips.
3. Force the one-shot to be a pulse and use the one shot to drive SO by writing 0x04 to address 1 in all chips.
4. Load the configuration generated by the cdm5016 program to all chips.

**NOTE:**All sync controls except for  $\overline{SO}$ , should be set to 2 so that they are controlled by the  $\overline{SIA}$  input sync.

This can be done by adding these lines to the cmd5016 input file:

```
soB_sync 4
fir_sync 2
sck_sync 2
nco_sync 2
cic_sync 2
```

5. Clear the reset by writing 0x100 to address 0 of all chips.
6. Pulse the syncs by writing 0x14 to address 1 of the master chip.

**NOTE:**The above procedure is selected by setting pseudo-command sync\_mode to '5'.

### 16.9.3 Multiple GC5016 Chips Using an External Sync

Same as above, except the  $\overline{SIA}$  input is tied to an FPGA or other sync source.

1. Reset the chip by writing 0xFF00 to address 0 of all chips.
2. Disable all outputs except  $\overline{SO}$ , by writing 0x100 to address 3 of all chips.
3. Drive the  $\overline{SIA}$  inputs low (active) using the external sync source.
4. Load the configuration generated by the cdm5016 program to all chips.

**NOTE:**All sync controls should be set to 2, so that they are controlled by the  $\overline{SIA}$  input sync.

This can be done by adding these lines to the cmd5016 input file:

```
soB_sync 2
fir_sync 2
sck_sync 2
nco_sync 2
cic_sync 2
```

5. Clear the reset by writing 0x100 to address 0 of all chips.
6. Release the syncs by setting  $\overline{SIA}$  high (inactive).

**NOTE:**  $\overline{SIA}$  is clocked into the GC5016 chips by CK and the signal must meet the specified setup and hold times for all of the GC5016 chips.

**NOTE:**The above procedure is selected by setting pseudo-command sync\_mode to '5'. Only the master GC5016 has the Sync Output tied back to the FPGA. The other GC5016s have their  $\overline{SIA}$ s tied to the FPGA outputs.

## 16.10 Diagnostics

The GC5016 provides self-test capability by providing a pattern generator at the inputs, a specific signal processing setup condition, a linear feedback shift register LFSR to develop an output results, and a checksum register read by the local bus. A general timer is used to sequence the load, run for n cycles, and capture the test results.

The diagnostic tests are provided in the gc5016 developer's toolkit. There are 5 different tests, a local bus interface test, and 4 separate checksum tests. More details on these tests are given in the application notes at the end of this document.

The LFSR generator for the DDC inputs has specific register variable settings. The rinf\_diag register variable selects the diagnostic source, which can generate a linear feedback sequence, a constant, or a ramp. The rinf\_sel\_[portA,B,C,D] selects the receiver input-bus, or a diagnostic input for each DDC input bus. The cksum\_sync\_front register value selects the synchronization source for the pattern generator.

Once the local bus registers have been programmed, the general timer starts, which releases the GC5016 to perform the test. The LFSR inputs are processed in the DDC channel, and after the gain output, the IQ data is input to the receive checksum logic. The receive checksum computes another LFSR sequence, and when the general timer has counted the number of test cycles to be performed, the LFSR output is registered in the checksum register. Each general timer cycle, the checksum generator is recycled to start the test.

There is a separate pattern generator at the transmit inputs, which can generate a linear feedback sequence or a constant. The register variable tx\_pat\_gen controls the Transmit diagnostic source. The register variable tinf\_src selects the TINF data port input or the diagnostic input.

The same type of test cycle can be performed from the Transmit input LFSR generator, through the Transmit DUC logic, to the Transmit output LFSR sequence, to the local bus register. At the start of the checksum test, the general timer sync clears the cksum\_sync\_back selection synchronizes the rcv\_checksum register feedback. The general timer interval IQ events are processed in the checksum logic. At the completion of the general timer, the last LFSR calculation is latched in the checksum register.

The cksum\_sync\_front selection synchronizes the transmit\_cksum register feedback. The number of internal IQ events are processed in the checksum logic, based on the general timer value. When the general timer completes, the last LFSR calculation is latched in the checksum register.

The NCO must be sync'd with the data pattern (so the accumulated phase always starts at zero). The dither sync must either be set to always on (thus freezing the dither) or sync'd to the sync source. The user should wait for at least four sync periods to allow the checksum to stabilize before reading the checksum.

The checksum and console diagnostic tests are further described in the application section.

## 16.11 JTAG

The GC5016 supports JTAG with a 5-pin interface. The JTAG implementation supports the standard boundary scan (used for board test), and chip identification. A BSDL file is available on the web. The GC5016 identification string is a 1 followed by an 11-bit manufacturer number (0x8C), a 16-bit chip number (5016 = 0x1398), and a 4-bit revision number (currently a 1).

The TRST inverted pin is not used on 4 wire JTAG testers. This pin should have at least a 1-k $\Omega$  pull-up resistor to 3.3 V during JTAG operation.

**NOTE:**The TRST pin must be connected to GND during normal operation.

## 16.12 Mask Revision Register

The mask revision register contains a simple 8-bit code that changes with any mask changes which may impact software, so that users can deploy software that tests for which revision and changes the behavior accordingly. The current revision value is 1.

## 17 CMD5016 – CONFIGURATION SOFTWARE

The cmd5016 is a configuration software program used to calculate the register variable values and the initialization sequence required for the GC5016. The TI Developer toolkit has the cmd5016.exe program, and a cmd5016 user's guide for programming the GC5016 through the cmd5016 software.

**NOTE:**The GC5016 is intended to be programmed through the supplied cmd5016 interface.

The configuration software accepts a user supplied configuration file. The configuration file contains general commands and register variable values. The general commands are called pseudo-commands. The pseudo-commands (listed in table 7) specify receive, transmit, io modes, 4 channel or splitiq modes. The register commands (tables 8 through 66) provide more detailed control, and are normally not required. Example configuration files are provided in the cmd5016 user's guide.

The user specifies the configuration file, and the PFIR coefficient tap file to the cmd5016 software. The software performs analysis to determine if the configuration is feasible, and converts the pseudo commands, and register variables into the register values to program the GC5016.

**NOTE:**In the configuration file, a line beginning with '#' is considered a comment field.

The cmd5016 generates output files based on print directives in the configuration file:

print table – An output file is generated with a .TBL extension that lists all of the register settings generated for the specified configuration.

print analysis – An output file is generated with a .ANL extension that provides information on configuration warnings, configuration errors, the PFIR filter mode used, and a VCore power consumption estimate.

print gc101 – An output file is generated with a .GC101 extension that contains address and data programming for the GC101 evaluation platform. This file is formatted as a list of write commands.

print debug – An output file is generated with a .DBG extension that contains more information on specific filter modes, and GC5016 state information.

print hfile – An output file is generated with a .h extension that is formatted as a "C" language structure which can be used with embedded systems for programming the GC5016.

**NOTE:**Errors identified in the analysis file must be fixed before the gc101 or the outputs can be used. Warnings are sent to the analysis file and indicate unusual but possibly legal conditions.

**NOTE:**The PFIR coefficient filename and local path are referenced in the configuration file. An error will occur if the proper local path or filename are incorrect.

Each pair of-channels has two modes of operation transmit and receive. The chip may operate with all four channels in transmit, all four in receive, or two in transmit (AB) and two in receive (CD). The mode settings must be declared first.. The mode is specified using a mode command:

```
mode [AB | CD] [transmit | receive]
```

### 17.1 cmd5016 Keywords

The user sets variables in the configuration input file using keywords that are either pseudo-fields or variable fields. In most cases, the table 7 pseudo\_field settings will be used to configure the GC5016. The variables fields are bit fields of the hardware control registers. The pseudo\_fields are variables that exist in software only and have no directly corresponding element in hardware. The keywords can be one of six types:

mandatory (M) – requires user selection,

defaulted (D), – variable set with an initial value

computed (C), – software controlled variable

unused (X), not-applicable (–).

expert(E) – Normally a calculated variable, that should not be set manually.

Variables can have different types in transmit and receive mode. For example, the CIC interpolation (*cic\_int*) is mandatory in transmit and unused in receive. Any variable may be directly set by the user and that value is used both to program the chip and in some cases to compute other fields.

A user should first let the software generate values for computed and expert fields before attempting to modify them. Setting *expert\_only* fields gives a warning and generally should not be attempted. Computed fields (such as *gain\_lsb* and *gain\_msb*) can reasonably be changed by a user – but most commonly should not need be changed.

Defaulted values should be reviewed to see if they fit the user's application. Mandatory values must be set – the software does not generate a configuration without them. Unused variables are programmed to zero – though it does not matter. Any user set variables are normally used to compute other fields.

The *override* command is used to allow the user to override the settings of specific variables without impact to any other variables. The user's control file is read up to the *override* command, all computations and analysis are done and reported, the rest of the control file is read to override specific settings, and finally the control register settings are written.

Table 7 describes the *pseudo\_fields*. The *Rcv* column indicates the type in receive mode. The *Xmt* column indicates the type in transmit mode. The *TYPE* column indicates if the variable is per channel or global. Names in the text in *italics* refer to *cmd5016* variable names described in the following tables.

**Table 7. Pseudo Fields in cmd5016**

Rcv	Xmt	NAME	TYPE	DEFAULT	DESCRIPTION
D	X	<i>agc_cf</i>	channel		Used for adjusting the agc crest factor, see AGC application note
D	X	<i>agc_mode</i>	channel	0	Selects the AGC mode, see AGC application note. (default is agc off)
D	X	<i>agc_tc</i>	channel		Calculates AGC time constant. See AGC application note.
M	M	<i>bits</i>	channel	0	Bits in each word of the output data in receive or input data in transmit. Must be either 4, 8, 12, 16, or 20. An interface with 8-bit real and 8-bit imaginary data would be programmed to 8.
D	D	<i>bypass_cic</i>	channel	0	Programs the CIC into bypass mode (1) or normal (0). It neither interpolates nor decimates. Gain is unity in transmit, 1/2 in receive. The data still goes through the CIC.
D	D	<i>bypass_fir</i>	channel	0	Programs the FIR filter to an impulse, with a minimum latency and unity gain (1) or normal.
D	D	<i>bypass_mix</i>	channel	0	Programs the mixers to be nearly unity gain $(2^{20}-1)/2^{20}$ . The sin mixer multipliers are programmed to multiply by zero. Also sets the frequency to be dc and phase to zero.
M	X	<i>cic_dec</i>	channel	1	CIC decimation amount (only in receive).
X	M	<i>cic_int</i>	channel	1	CIC interpolation amount (only in transmit).
M	X	<i>fir_coef</i>	channel		FIR filter coefficient filename, must be entered for configuration
M	X	<i>fir_dec</i>	channel	1	FIR decimation (only in receive). Values from 1 to 16.
D	D	<i>fir_diff</i>	channel	0	If set, allows multiple data streams in the filter to get different coefficients.
X	M	<i>fir_int</i>	channel	1	FIR interpolation amount (only in transmit) (1–16).
D	D	<i>fir_nchan</i>	channel	1	Specifies how many data streams in the filter (1–16). Almost always the default of 1 is correct.
D	D	<i>gain</i>	channel	1.0	ratio <i>gain_lsb</i> , and <i>gain_msb</i> adjustment – normally <i>overall_gain</i> is used
D	D	<i>Overall_gain</i>	global	1.0	Used for calculating the channel gain. . See Application notes.
M	M	<i>pins</i>	channel	0	Specifies how many pins are active in the output interface in receive or input interface in transmit. Must be either 4, 8, or 16.
D	X	<i>pwr_mtr_on</i>	channel	0	(1) automatically configure the power meter ( DDC mode only)
D	X	<i>rin_cmplx</i>	global	0	Receive input data is complex (1) or real (0).
D	X	<i>rin_rate</i>	global	1	Receive input data rate is half (0) for IQ time multiplexed, full (1), or double (2). If double, <i>splitiq</i> must also be set.
D	X	<i>routf_tdm</i>	global	0	Receive output data is TDM'd (1) onto port DO or normal (0).



Rcv	Xmt	NAME	TYPE	DEFAULT	DESCRIPTION
D	D	<i>splitiqAB</i>	channel pair	0	If set, channel A and B are splitIQ mode, I data is processed in ChA, the Q data is processed in ChB.
D	D	<i>splitiqCD</i>	channel pair	0	If set, channel C and D are splitIQ mode, I data is processed in ChC, the Q data is processed in ChD.
D	D	<i>splitiq</i>	global	0	If set, complex IQ data is split so the I data goes to one filter and Q data goes to another. This applies to both pairs of channels AB and CD.
D	D	<i>syncmode</i>	global	0	Setting to combine channel and global sync options, adds one shot startup sequence at end of file, if proper mode is selected
X	M	<i>tinf_cmplx</i>	channel	NA	Transmit input data is complex (1) or real (0). If <i>splitiq</i> is on <i>tinf_cmplx</i> must be real.
X	D	<i>tinf_fs_dly</i>	channel	3	Transmit input frame strobe delay. Delays internal strobe identifying the MSB from the output frame strobe. 4 bits
X	D	<i>tinf_tdm</i>	global	0	TDM'd transmit input data is expected on port AI(1), or normal (0).
X	D	<i>tout_cmplx</i>	global	1	Transmit output data is complex (1) or real (0).
X	D	<i>tout_nsig</i>	global	NA	Number of transmit output signals. Defines how channels are summed together. The number of input signals is derived from channels in transmit mode that are powered and whether they are in <i>splitiq</i> or not.
X	D	<i>tout_rate</i>	global	1	Transmit output rate is half (0) for IQ time multiplexed, full (1) or double (2). If double, <i>splitiq</i> must also be set.
X	D	<i>tout_res</i>	global	1	Transmit output resolution is normal (0) for 16 bits or less, high resolution (1) up to 22 bits, or complementary signaling (2).
X	D	<i>tout_sumin</i>	global	0	Sumin port active (1) or not (0).
M	M	<i>freq</i>	channel		Frequency. determines the fractional phase value with Fck, to be loaded into the 48bit frequency registers <i>freq_msb</i> , <i>freq_mid</i> , and <i>freq_lsb</i> .
M	M	<i>fck</i>	global		The chip clock rate. It is used to compute estimated power as well as to convert freq.

## 17.2 DDC Mode Pseudo-Fields

mode AB(CD) receive – identifies DDC mode

*rin\_rate*, *rin\_cmplx* – determines the Receive Input Formatter mode, double rate processing

*splitiq*, *splitiqAB*, *splitiqCD* – determine the 2channel or 4 channel mode

*freq*, *fck*, *bypass\_mix* – determine the complex mixer *freq\_msb*, *freq\_mid*, *freq\_lsb* settings

*bypass\_cic*, *cic\_dec* – determines the dual CIC filter decimation

*bypass\_fir*, *fir\_dec*, *fir\_diff*, *fir\_nchan*, *fir\_coef* – determine the PFIR mode, and filter taps

*gain*, *overall\_gain* – manual gain settings

*agc\_cf*, *agc\_mode*, *agc\_tc* – agc gain settings

*pwr\_mtr\_on* – setup of receive Power Meter

*routf\_tdm* – receive output format control for PortD TDM mode

### 17.3 DUC Mode Pseudo-Fields

mode AB(CD) transmit – identifies DUC mode

tinf\_cmplx, tinf\_tdm – identifies the Transmit Input Formatter mode

tinf\_fs\_dly – customer logic Transmit Input Formatter timing offset

splitiq, splitiqAB, splitiqCD – determine the 2channel or 4 channel mode

gain, overall\_gain – manual gain settings

bypass\_fir, fir\_int, fir\_diff, fir\_nchan, fir\_coef – determine the PFIR mode, and filter taps

bypass\_cic, cic\_int – determines the dual CIC filter decimation

freq, fck, bypass\_mix – determine the complex mixer freq\_msb, freq\_mid, freq\_lsb settings

tout\_sumin – determines if the COut and DOut are used as the sum input port, activates sum input mode

tout\_nsig – determines the two internal sum logic sets of A,B,C, and D channels

tout\_rate, tout\_cmplx, tout\_res – determines the DUC output modes, and signal to pin mapping

### 17.4 Control Registers

This section describes the control registers of the GC5016. The control register addressing is divided into two sections:

Page – the value of global address 2

Address – the hexadecimal value of the five address pins

The Global registers are accessed through addresses 0 through 0xF. The paged registers are accessed through addresses x10 through 0x1F.

Table 8 provides an overview of the page allocations. FirA–D, cicAB, and cicCD are hardware blocks that contain the signal processing blocks listed in Table 8.

The register values are not changed by the hardware-reset pin, software master reset, block reset, or clock loss. A global register 0 (internal reset and power down) is set at power up (but not by any reset action). Global register 3 (output enables) is cleared at power up.

**Table 8. Map of Control Pages**

BLOCK	PAGES	DESCRIPTION
FirA	00–1F	Transmit input formatter, gain, PFIR, AGC, power meter, receive output formatter for A
FirB	20–3F	Transmit input formatter, gain, PFIR, AGC, power meter, receive output formatter for B
FirC	40–5F	Transmit input formatter, gain, PFIR, AGC, power meter, receive output formatter for C
FirD	60–7F	Transmit input formatter, gain, PFIR, AGC, power meter, receive output formatter for D
cicAB	80–81	CIC, NCO, mixers for channels A and B, common transmit blocks
cicCD	a0–A1	CIC, NCO, mixers for channels C and D, common receive blocks

Table 9 lists the global registers in the chip.

**Table 9. Global Control Registers**

PAGE	ADDRESS	REGISTER DESCRIPTION
Global	0	Reset and clock control
Global	1	General sync
Global	2	Page and revision
Global	3	Output enables

Table 10 lists the 4 FIR & Control blocks. Table 11 lists the registers in FirA. FirB, FirC, and FirD have identical registers with page offsets of 20, 40, and 60 respectively.

**Table 10. FirA Control RAMs**

BLOCK	PAGES	DESCRIPTION
FirA	00–1F	Transmit input formatter, gain, PFIR, AGC, power meter, receive output formatter for A
FirB	20–3F	Transmit input formatter, gain, PFIR, AGC, power meter, receive output formatter for B
FirC	40–5F	Transmit input formatter, gain, PFIR, AGC, power meter, receive output formatter for C
FirD	60–7F	Transmit input formatter, gain, PFIR, AGC, power meter, receive output formatter for D

Table 11 lists the control registers for FirA.

**Table 11. FirA Control Registers**

PAGE	ADDRESS	REGISTER DESCRIPTION
0–F	10–1F	FIR coefficients
10	10–1F	Swap ram contents
11	10–1F	BE ram contents
12	10	Coefficient address generator
12	11	Common address generator
12	12	Forward read address generator
12	13	Forward write address generator
12	14	Backward read address generator
12	15	Backward write address generator
12	16	Backward end cell read address generator
12	17	Backward end cell write address generator
12	18	Forward write strobe
12	19	Backward write strobe
12	1a	Backward end cell read bypass
13	10	Transmit input formatter
13	11	Transmit frame strobe controls
13	12	Transmit frame counter
13	13	Gain 16 LSB's
13	14	Gain controls
13	15	AGC minimum adaptation limit
13	16	AGC maximum adaptation limit
13	17	AGC counts and threshold
13	18	AGC loop gains
13	19	AGC gain read back
13	1a	Power meter least significant 16 bits
13	1b	Power meter most significant 16 bits
13	1c	Power meter status
13	1d	Power meter Integration time
13	1e	Receive output formatter
13	1f	Receive checksum
14	10	FIR swap ram controls
14	11	FIR accumulator controls
14	12	FIR output control
14	13	FIR sync count
14	14	FIR clock
14	15	Channel syncs

Table 12 lists the control registers for cicAB.

**Table 12. Control Registers for cicAB**

PAGE	ADDRESS	REGISTER DESCRIPTION
80	10	A CIC mode
80	11	A phase
80	12	A frequency (LSB)
80	13	A frequency (mid)
80	14	A frequency (MSB)
80	15	A mixer
80	16	A NCO sync and dither control
80	17	A CIC count and sync
80	18	B CIC mode
80	19	B phase
80	1a	B frequency (LSB)
80	1b	B frequency (mid)
80	1c	B frequency (MSB)
80	1d	B mixer
80	1e	B NCO sync and dither control
80	1f	B CIC count and sync
81	10	Sum tree sum selection
81	11	Sum tree multiplexing
81	12	Receive sensitivity reduction path A
81	13	Receive sensitivity reduction path B
81	14	Receive sensitivity reduction path C
81	15	Receive sensitivity reduction path D

Table 13 lists the control registers for cicCD.

**Table 13. Control Registers for cicCD**

PAGE	ADDRESS	REGISTER DESCRIPTION
a0	10	C CIC mode
a0	11	C phase
a0	12	C frequency (LSB)
a0	13	C frequency (mid)
a0	14	C frequency (MSB)
a0	15	C mixer
a0	16	C NCO sync and dither control
a0	17	C CIC count and sync
a0	18	D CIC mode
a0	19	D phase
a0	1a	D frequency (LSB)
a0	1b	D frequency (mid)
a0	1c	D frequency (MSB)
a0	1d	D mixer
a0	1e	D NCO sync and dither control
a0	1f	D CIC count and sync
a1	10	Receive input formatter
a1	11	General timer
a1	12	Receive syncs
a1	13	Transmit output multiplexing
a1	14	Transmit output rounding and hold
a1	15	Transmit checksum

## 17.5 Global Registers

The following tables describe the various bit fields contained in each of the global control registers.

**Table 14. Global Register Reset and Clock Control Address 0x0 Bits 15.8 Set at Power Up**

Rcv	Tx	FIELD	BITS	Dflt	DESCRIPTION
–	–	<i>ck_loss_status</i>	1..0		
D	D	<i>en_ck_loss</i>	8	1	Enable clock loss detection. Highly recommended.
C	C	<i>pwr_dwn_fir_A</i>	9		Power down PFIR in A. Power down puts the GC5016 section in reset and disables the clock. It does not reset the control registers.
C	C	<i>pwr_dwn_fir_B</i>	10		Power down PFIR in B
C	C	<i>pwr_dwn_fir_C</i>	11		Power down PFIR in C
C	C	<i>pwr_dwn_fir_D</i>	12		Power down PFIR in D
C	C	<i>pwr_dwn_cic_AB</i>	13		Power down cic/mix for A and B
C	C	<i>pwr_dwn_cic_CD</i>	14		Power down cic/mix for C and D
C	C	<i>master_reset</i>	15		Power down all sections

**Table 15. General Sync Global Address 0x1**

RCV	TX	FIELD	BITS	Dflt	DESCRIPTION
D	D	<i>soB_sync</i>	2..0	2	Signal selection for <i>sync_out_B</i>
–	–	<i>one_shot</i>	4..3		One shot control. (=0) Armed issue one shot when LSB goes high; (=1) issues one shot on transition of LSB to high safe state to be left in; (=2) level output 0; (=3) level output 1

**Table 16. Page and Revision Global Address 0x2**

Rcv	Tx	FIELD	BITS	Dflt	DESCRIPTION
–	–	<i>page</i>	7..0		Page register
–	–	<i>chip_rev</i>	15..8		Chip revision. Read only. Currently 1.

**Table 17. Output Enables Global Address 0x3 Cleared at Power Up**

Rcv	Tx	FIELD	BITS	Dflt	DESCRIPTION
C	C	<i>en_AO</i>	0		Enable data output AO
C	C	<i>en_AFS</i>	1		Enable frame strobe and output clock for A
C	C	<i>en_BO</i>	2		Enable data output BO
C	C	<i>en_BFS</i>	3		Enable frame strobe and output clock for B
C	C	<i>en_CO</i>	4		Enable data output CO
C	C	<i>en_CFS</i>	5		Enable frame strobe and output clock for C
C	C	<i>en_DO</i>	6		Enable data output DO
C	C	<i>en_DFS</i>	7		Enable frame strobe and output clock for D
C	C	<i>en_soB</i>	8		Enable <i>sync_out_B</i> and iflag
D	D	<i>ckp_A</i>	9	0	Invert ACK
D	D	<i>ckp_B</i>	10	0	Invert BCK
D	D	<i>ckp_C</i>	11	0	Invert CCK
D	D	<i>ckp_D</i>	12	0	Invert DCK
X	D	<i>sumin_clr</i>	13	0	Force sumin port to zero

## 17.6 FIR Control RAMs

The programmable filter has three RAM's used to control its operation.

PAGE	ADDRESS	REGISTER DESCRIPTION
0–F	10–1F	FIR coefficients
10	10–1F	Swap ram address index
11	10–1F	BE ram Bit Map

The filter coefficients are stored in a 16-word (by 16 bit) RAM, in each of 16 filter cells. The coefficients are 16-bit two's complement. The coefficients can be read without interrupting normal operation. Changing the coefficients during normal operation can cause erroneous output should the hardware be reading a coefficient value simultaneously. The coefficients can be divided into banks to allow safe updating and synchronous changing to a new set. The coefficients are stored in addresses 0x10 to 0x1F on the FIR Control RAM pages:

- 0x0 to 0xF (for channel A),
- 0x20 to 0x2F (for channel B),
- 0x40 to 0x4F (for channel C),
- 0x60 to 0x6F (for channel D)

The configuration software takes the filter coefficients from a file and writes them to the appropriate RAM locations.

## 17.7 Swap RAMs

The Swap RAM can re-order the data for use by the forward delay line. The Swap RAM is divided into two halves. The PFIR reads from the last stored set of data, and the input is written to the other half. The programmed portion of the swap RAM, is the address of the new written data. A counter is used to read the address-pointer-value, and write the newly received data at the pointed address.

Normally, this RAM is programmed so the content of each location equals its address (effectively bypassing it). In the future, this RAM can be used to allow complex coefficients by allowing the same data to be read twice. The swap RAM is on page 0x10 addresses 0x10 to 0x1F. Table 46 has additional Swap RAM controls for the write and read address counters. The configuration software automatically writes this RAM. Currently there is no manual override within the configuration software.

## 17.8 Backend RAM

The backend RAM encodes several fields into a 16 word by 16-bit RAM. The backend RAM is used to control the 16<sup>th</sup> FIR cell. There is a generic address that is programmed for all 16 cells. The 16<sup>th</sup> fir-cell functions may be different from the other 15 cells, and may require different configuration. The bits are mapped as shown in Table 18.

The configuration software calculates the appropriate values for this RAM. There is no manual override option in the configuration software.

**Table 18. Backward End Cell Control RAM Bit Map**

BITS	DESCRIPTION
3..0	Backward end cell write address map for first iteration
7..4	Backward end cell write address map for second iteration
8	Backward end cell write enable
12..9	Backward end cell read address map
13	Blank feedback (end cell only) for odd symmetry first iteration
14	Blank feedback (end cell only) for odd symmetry second iteration
15	Unused

## 17.9 Programmable FIR, Gain, Transmit Input, and Receive Output Control Registers

The following tables detail the various control registers for a single PFIR filter. Note that the configuration software calculates these registers. The PFIR has several sets of memories that are synchronized to read the data to be filtered, and the coefficient memory. The Common Address Generator is used to read from the Forward and Reverse Delay memory in each cell. This represents the data to be filtered. Different filtering modes, can have I or Q data at different offset positions. The Coefficient Address generator is used to read the coefficient memory.

The Forward Read address and Forward Write address are used at the end of each computational cycle, to pass the Forward Delay data between the FIR cells. The Forward Write strobe indicates the times within the PFIR calculates that the data is written to the next cell.

The Backward Read address, Backward Write address, Backward End Cell Read address, Backward End Cell Write address, and Backward End Cell Read Bypass are used to develop the address to pass the reverse delay line data from the 16<sup>th</sup> FIR cell back towards the 1<sup>st</sup> FIR cell. The Backward Write strobe indicates the times within the PFIR calculates that the data is written to the next cell.

**Table 19. Coefficient Address Generator Page 0x12 Address 0x10**

Rcv	Tx	FIELD	BITS	Dflt	DESCRIPTION
E	E	<i>coef_ofsc</i>	3..0		FIR coefficient address offset
E	E	<i>coef_modc</i>	7..4		FIR coefficient modulo count
E	E	<i>coef_repc</i>	11..8		FIR coefficient repeat count
E	E	<i>coef_sym</i>	12		FIR hardware exploits symmetry (1) or not (0)
E	E	<i>coef_zerofr</i>	13		FIR zero forward read

**Table 20. Common Address Generator Page 0x12 Address 0x11**

Rcv	Tx	FIELD	BITS	Dflt	DESCRIPTION
E	E	<i>agen_recr</i>	3..0		FIR recirculate count
E	E	<i>agen_depd</i>	7..4		FIR depth count
E	E	<i>agen_modd</i>	11..8		FIR modulo count
E	E	<i>agen_togen</i>	12		FIR toggle enable for back end read and write

**Table 21. Forward Read Address Generator Page 0x12 Address 0x12**

Rcv	Tx	FIELD	BITS	Dflt	DESCRIPTION
E	E	<i>fragen_soff</i>	3..0		FIR forward read address generator offset
E	E	<i>fragen_srecr</i>	7..4		FIR forward read address generator recirculate count
E	E	<i>fragen_sdepd</i>	11..8		FIR forward read address generator depth count
E	E	<i>fragen_stepn</i>	15..12		FIR forward read address generator step

**Table 22. Forward Write Address Generator Page 0x12 Address 0x13**

Rcv	Tx	FIELD	BITS	Dflt	DESCRIPTION
E	E	<i>fwagen_soff</i>	3..0		FIR forward write address generator offset
E	E	<i>fwagen_srecr</i>	7..4		FIR forward write address generator recirculate count
E	E	<i>fwagen_sdepd</i>	11..8		FIR forward write address generator depth count
E	E	<i>fwagen_wrecl</i>	15..12		FIR forward write address generator step

**Table 23. Backward Read Address Generator Page 0x12 Address 0x14**

Rcv	Tx	FIELD	BITS	Dflt	DESCRIPTION
E	E	<i>bragen_soff</i>	3..0		FIR backward read address generator offset
E	E	<i>bragen_srecr</i>	7..4		FIR backward read address generator recirculate count
E	E	<i>bragen_sdepd</i>	11..8		FIR backward read address generator depth count
E	E	<i>bragen_stepn</i>	15..12		FIR backward read address generator step

**Table 24. Backward Write Address Generator Page 0x12 Address 0x15**

Rcv	Tx	FIELD	BITS	Dflt	DESCRIPTION
E	E	<i>bwagen_soff</i>	3..0		FIR backward write address generator offset
E	E	<i>bwagen_srecr</i>	7..4		FIR backward write address generator recirculate count
E	E	<i>bwagen_sdepd</i>	11..8		FIR backward write address generator depth count
E	E	<i>bwagen_wrecl</i>	15..12		FIR backward write address generator step

**Table 25. Backward End Cell Read Address Generator Page 0x12 Address 0x16**

Rcv	Tx	FIELD	BITS	Dflt	DESCRIPTION
E	E	<i>beragen_soff</i>	3..0		FIR backward end cell read address generator offset
E	E	<i>beragen_srecr</i>	7..4		FIR backward end cell read address generator recirculate count
E	E	<i>beragen_sdepd</i>	11..8		FIR backward end cell read address generator depth count
E	E	<i>beragen_stepn</i>	15..12		FIR backward end cell read address generator step

**Table 26. Backward End Cell Write Address Generator Page 0x12 Address 0x17**

Rcv	Tx	FIELD	BITS	Dflt	DESCRIPTION
E	E	<i>bewagen_soff</i>	3..0		FIR backward end cell write address generator offset
E	E	<i>bewagen_srecr</i>	7..4		FIR backward end cell write address generator recirculate count
E	E	<i>bewagen_sdepd</i>	11..8		FIR backward end cell write address generator depth count
E	E	<i>bewagen_wrecl</i>	15..12		FIR backward end cell write address generator step

**Table 27. Forward Write Strobe Page 0x12 Address 0x18**

Rcv	Tx	FIELD	BITS	Dflt	DESCRIPTION
E	E	<i>fwa_strobe</i>	15..0		FIR forward write strobe

**Table 28. Backward Write Strobe Page 0x12 Address 0x19**

Rcv	Tx	FIELD	BITS	Dflt	DESCRIPTION
E	E	<i>bwa_strobe</i>	15..0		FIR backward write strobe

**Table 29. Backward End Cell Read Bypass Page 0x12 Address 0x1A**

Rcv	Tx	FIELD	BITS	Dflt	DESCRIPTION
E	E	<i>beagen_rbypass</i>	15..0		FIR backward end cell read bypass



## 17.10 Transmit Input Formatter Controls

The Transmit Input Formatter section is used to set the mode of the Transmit Input logic, control the Frame Strobe timing in Transmit mode, and to control the time when the customer logic – Transmitter input(s) are sampled.

**Table 30. Transmit Input Formatter Page 0x13 Address 0x10**

Rcv	Tx	FIELD	BITS	Dflt	DESCRIPTION
X	C	<i>tinf_bits</i>	2..0		Bits per word 0 – quiet, else bits = 4 x <i>tinf_bits</i> . Values 6 and 7 are illegal.
X	C	<i>tinf_pins</i>	5..3		Active pins quiet (0), four pins (1), 8 pins (2), 16 pins (4), illegal (else)
X	C	<i>tinf_igmux</i>	6		IQ multiplexed (1) or real (0) inputs
X	C	<i>tinf_pariq</i>	7		IQ parallel (1) or not (0) I is bits 15..8 Q is bits 7..0
X	C	<i>tinf_src</i>	10..8		Source channel A normal (2), TDM (6), test (0); channels B–D normal (2), TDM (1), test (0)
C	C	<i>tinf_xmt</i>	11		Transmit (1) or receive (0)
C	C	<i>fso_sel</i>	13..12		Frame strobe output select quiet (0), xmt (1), receive (2), illegal (3)

**Table 31. Transmit Frame Strobe Page 0x13 Address 0x11**

Rcv	Tx	FIELD	BITS	Dflt	DESCRIPTION
X	E	<i>tinf_first</i>	3..0		Transmit input frame strobe load first word
X	E	<i>tinf_second</i>	7..4		Transmit input frame strobe load second word
D	D	<i>sck_div</i>	11..8	0	divided clock, develops channel clock as $sck\_period = (1 + sck\_div) * ck\_period$
X	C	<i>tinf_fso_dly</i>	14..12		Transmit input frame strobe output delay values from 1 to 7 divided clocks * ( <i>sck_div</i> +1)

**Table 32. Transmit Frame Counter Page 0x13 Address 0x12**

Rcv	Tx	FIELD	BITS	Dflt	DESCRIPTION
X	E	<i>tinf_fs_cnt</i>	11..0		Transmit frame strobe count distance between frame strobes in divided clocks
X	E	<i>tinf_nfs</i>	15..12		Transmit number of frame strobes between <i>fir_swap</i> toggles

## 17.11 Gain and AGC Controls

The Gain Controls, *gain\_lsb*, and *gain\_msb*, and *agc* controls set the scale of the Receive output, or Transmit input after formatting. The *agc* controls can be used in the receive mode. See the DUC Gain, DDC Gain, and AGC application notes.

**Table 33. *gain\_lsb* Page 0x13 Address 0x13**

Rcv	Tx	FIELD	BITS	Dflt	DESCRIPTION
C	C	<i>gain_lsb</i>	15..0		Lower 16 bits of gain (gain is scaled by 4096)

**Table 34. Gain Controls Page 0x13 Address 0x14**

Rcv	Tx	FIELD	BITS	Dflt	DESCRIPTION
C	C	<i>gain_msb</i>	2..0		Upper 3 bits of gain
D	D	<i>agc_freeze</i>	3	1	Freezes adaptive gain
C	C	<i>gain_rnd</i>	8..4		Rounds off bottom 0 to 16 bits of a 20-bit word
C	C	<i>gain_half</i>	9		Saturates gain output at 1/2. Used in xmt for symmetric filters
D	D	<i>agc_hold</i>	10	0	Gain tracks when low, holds when high for uP gain read back
D	D	<i>agc_gain_out</i>	11	0	Puts <i>agc</i> information into lower 8 bits of output data
D	D	<i>agc_zmag</i>	15..12	0	AGC mask for defining zero signal for faster AGC adaptation. Masks off bottom 0, 1, 2, 3, or 4 bits (0xF, E, C, 8, or 0)

**Table 35. AGC Minimum Adaptation Limit Page 0x13 Address 0x15**

Rcv	Tx	FIELD	BITS	Dflt	DESCRIPTION
D	D	<i>agc_min</i>	15..0	0	AGC minimum adaptation limit. Lower limit for adapted gain is <i>manual_gain</i> – <i>agc_min</i>

**Table 36. AGC Maximum Adaptation Limit Page 0x13 Address 0x16**

Rcv	Tx	FIELD	BITS	Dflt	DESCRIPTION
D	D	<i>agc_max</i>	15..0	0	AGC maximum adaptation limit. Upper limit for adapted gain is manual_gain + agc_max

**Table 37. AGC Counts and Threshold Page 0x13 Address 0x17**

Rcv	Tx	FIELD	BITS	Dflt	DESCRIPTION
D	D	<i>agc_zero_cnt</i>	3..0	0	Run of zeros before fast adaptation gain increase step Dzro is used
D	D	<i>agc_sat_cnt</i>	7..4	0	Run of saturated values before fast adaptation gain reduction step Dsat is used
D	D	<i>agc_thresh</i>	15..8	0	Threshold for AGC adaptation

**Table 38. AGC Loop Gains Page 0x13 Address 0x18**

Rcv	Tx	FIELD	BITS	Dflt	DESCRIPTION
D	D	<i>agc_Dblw</i>	3..0	0	Gain shift for below threshold
D	D	<i>agc_Dabv</i>	7..4	0	Gain shift for above threshold
D	D	<i>agc_Dzro</i>	11..8	0	Gain shift for zero data
D	D	<i>agc_Dsat</i>	15..12	0	Gain shift for saturated

**Table 39. AGC Gain Read Back Page 0x13 Address 0x19**

Rcv	Tx	FIELD	BITS	Dflt	DESCRIPTION
–	–	<i>gain_read</i>	15..0		Read back of top 16 of 19 bits, current gain setting (read only)

## 17.12 Power Meter

The Power Meter integrates the I squared and Q squared values, over the integration counts. Table 43 is the integration counts. Table 42 is the controller setup, Tables 40 and 41 are the 32bit accumulated value.

**Table 40. Power Meter (LSB) Page 0x13 Address 0x1A**

Rcv	Tx	FIELD	BITS	Dflt	DESCRIPTION
–	–	<i>pwr_meter_lsb</i>	15..0		Read back of power meter least significant 16 bits (read only)

**Table 41. Power Meter (MSB) Page 0x13 Address 0x1B**

Rcv	Tx	FIELD	BITS	Dflt	DESCRIPTION
–	–	<i>pwr_meter_msb</i>	15..0		Read back of power meter most significant 16 bits (read only)

**Table 42. Power Meter Status Page 0x13 Address 0x1C**

Rcv	Tx	FIELD	BITS	Dflt	DESCRIPTION
–	–	<i>ready</i>	15		1 means power sample ready to read, user must reset to 0
–	–	<i>missed</i>	14		Set if power sample missed; reset by user
–	–	<i>too_soon</i>	13		Set if power sample reads too soon; reset by user
			12		Factory test bit keep 0
–	–	<i>pwr_os</i>	11		Power Meter One shot control keep 0 if pwr_msr = 1, if pwr_msr = 0, then use to fire one shot. 0 = armed, 1 = triggered; be sure that there are 2 clocks between arming and triggering
D	D	<i>pwr_msr</i>	10	0	1 = use read of register (address 0x1B) to fire one shot; 0 = manually fire one shot
			9..8		Unused
–	–	<i>gain_sign</i>	7		Read only, sign bit from gain. Only useful if one collects statistics over time.
			6		Sticky bit, set if gain zero = 1, reset by user (See Table 2)
			5		Sticky bit, set if gain saturated = 1, reset by user (See Table 2)
			4..0		Unused

**Table 43. Power Meter Integration Time Page 0x13 Address 0x1D**

Rcv	Tx	FIELD	BITS	Dflt	DESCRIPTION
D	D	<i>pwr_mtr_integ</i>	15..0	0	Power meter integration time in words

### 17.13 DDC Receive Output Formatter Controls

The output modes TDM, interleavedIQ, parallel IQ, or embedded gain and IQ are controlled from table 44. Although these are channel controls, the setup between channels must be correct for TDM mode, which is setup for all DDC channels. The Transmit DUC diagnostic source is also in this table. Table 45 if the checksum value read in the diagnostic test for a specific channel.

**Table 44. Receive Output Formatter Page 0x13 Address 0x1E**

Rcv	Tx	FIELD	BITS	Dflt	DESCRIPTION
C	X	<i>routf_pins</i>	2..0		Receive output formatter active pins. Active pins are always the MSBs. Set to 1, 2, or 4 for 4, 8, or 16 active pins.
C	X	<i>routf_bits</i>	7..3		Receive output formatter bits in a word. Set to 1, 2, 4, 8, 16, or 32 to get a word size of 4, 8, 12, 16, or 20.
C	X	<i>routf_iqmux</i>	8		Receive output complex (1) or real (0) per port. Note that when <i>splitiq</i> is active, <i>routf_iqmux</i> should be set to real.
C	C	<i>routf_pwrdown</i>	9		Power down receive output formatter block.
C	X	<i>routf_ctdm</i>	11		Activate TDM receive output.
D	D	<i>pwr_test</i>	12	0	Test mode for power meter. 0 for normal operation
D	D	<i>tx_pat_gen</i>	14..13	0	Transmit pattern generator enable and source selection off (0), random (1), constant 0x4000 (2), random with bit 14 inverted (3).

**Table 45. Receive Checksum Page 0x13 Address 0x1F**

Rcv	Tx	FIELD	BITS	Dflt	DESCRIPTION
–	–	<i>Rcv_checksum</i>	15..0	–	Checksum results for receive (read only).

### 17.14 Additional FIR Filter Controls

The Swap RAM controls are for the counters that write and read data from the FIR input to the Forward Delay Line. This register is calculated through the cmd5016 software. The FIR Accumulator controls adds the partial sums from the FIR cells, and controls the local FIR accumulator memory.

The FIR Output page, determines the FIR output format, provides scaling and rounding. The FIR Sync Count is used to maintain the internal FIR cycle count. The FIR sync is used at the beginning of each new FIR cycle.

The FIR Clock Control is used to determine the number of active clocks within the FIR cycle count. Reducing the FIR clocks within a cycle is used to lower the average Core power.

**Table 46. FIR Swap Ram Controls Page 0x14 Address 0x10**

Rcv	Tx	FIELD	BITS	Dflt	DESCRIPTION
E	E	<i>swap_wa_cnt</i>	3..0		FIR swap write address down count
E	E	<i>swap_ra_cnt</i>	7..4		FIR swap read address down count
E	E	<i>swap_xmt</i>	8		FIR swap RAM in transmit (1) or receive (0)
E	E	<i>swap_cmplx</i>	9		FIR swap expects complex from CIC (1) or real (0)
E	E	<i>fir_fb</i>	10		FIR forward broadcast (1) or not (0)
E	E	<i>swap_fb</i>	11		FIR swap RAM in forward broadcast (1) or not (0)
E	E	<i>swap_rcv_tdly</i>	12		FIR swap RAM. Reduces cic to FIR data valid delay by 1 when cic is bypassed – helps with data alignment in certain cases. Calculated by software.

**Table 47. FIR Accumulator Controls Page 0x14 Address 0x11**

Rcv	Tx	FIELD	BITS	Dflt	DESCRIPTION
E	E	<i>acc_dly</i>	3..0		FIR accumulator delay minus 1
E	E	<i>acc_cnt</i>	7..4		FIR number of partial products to accumulate
E	E	<i>acc_dly0</i>	8		FIR no accumulator delay (1) or not (0)
E	E	<i>acc_bypass</i>	9		FIR accumulator bypass (1) or normal (0). Must also set <i>acc_cnt</i> to zero for bypass.
E	E	<i>acc_enram</i>	10		FIR enable accumulate ram (1) normal. Set to 0 when <i>acc_dly0</i> is 1.

**Table 48. FIR Output Page 0x14 Address 0x12**

Rcv	Tx	FIELD	BITS	Dflt	DESCRIPTION
C	C	<i>fir_shift</i>	2..0		FIR shift up. Increase filter gain
C	C	<i>fir_xenq</i>	3		FIR transmit enable q. Set for transmit and complex filtering.
C	C	<i>fir_xeni</i>	4		FIR transmit enable i. Set for transmit, clear in receive.
C	C	<i>fir_half</i>	5		FIR half scale. Set to 0.
C	C	<i>fir_rnd20</i>	6		FIR round For receive, set to 1 for 20 bits to gain. In transmit, set to 0 for 18 bits to CIC.
C	C	<i>fir_cmplx</i>	7		FIR outputs complex data. Normally set, clear for <i>splitiq</i> or some bypass modes.

**Table 49. FIR Sync Count Page 0x14 Address 0x13**

Rcv	Tx	FIELD	BITS	Dflt	DESCRIPTION
E	E	<i>fir_sync_cnt</i>	15..0		FIR internal sync count to periodically resync various FIR counters

**Table 50. FIR Clock Page 0x14 Address 0x14**

Rcv	Tx	FIELD	Bits	Dflt	Description
E	E	<i>fir_clk_cnt</i>	7..0		Number of FIR clocks per CIC input (xmt) or output (rcv) minus 1
E	E	<i>fir_clk_cnt_en</i>	8		1 for normal operation; set to 0 and <i>fir_clk_cnt</i> +1 for FIR clock always on
E	E	<i>fir_test</i>	9		Set to 0 for normal operation
E	E	<i>fir_en_sync_cnt</i>	10		Enable fir sync counter (1)
D	D	<i>cksum_sync_back</i>	14..12	7	Receive checksum sync and transmit pattern generator sync

## 17.15 FIR, Gain, Power Meter, and Channel Clock Synchronization

The channel synchronization is programmed through the *sync\_mode* command, or register value commands. It is recommended that the *cic\_sync*, *fir\_sync*, and *sck\_sync* are selected to the same synchronization source. In normal use the *gain\_sync* value is set to always. The *pwr\_mtr\_sync*, and *coef\_sync* can be synchronized to the manual or one shot sources.

**Table 51. Channel Syncs Page 0x14 Address 0x15**

Rcv	Tx	FIELD	BITS	Dflt	DESCRIPTION
D	D	<i>fir_sync</i>	2..0	2	Sync source selection for FIR
D	D	<i>coef_sync</i>	5..3	6	Sync source selection for coefficient swapping. Used with multiple coefficient sets.
D	D	<i>gain_sync</i>	8..6	6	Sync source selection for gain updates
D	D	<i>pwr_mtr_sync</i>	11..9	7	Sync source selection for starting power meter
D	D	<i>sck_sync</i>	14..12	4	Sync source selection for slow clock divider

## 17.16 CIC and MIXER Control Registers

There are two cicmix blocks. The blocks are arranged as channel AB and channel CD:

page 0x80, addresses 0x10–0x17	channel A,
page 0x80, addresses 0x18 to 0x1F	channel B,
page 0xA0, addresses 0x10–0x17	channel C,
page 0xA0, addresses 0x18 to 0x1F	channel D.

Table 52 and 59 lists the CIC controls. The *cic\_shift*, *cic\_rshift*, *cic\_rcv\_full*, are the cic gain controls. The *cic\_rcv*, *cic\_xmt\_5stg*, *cic\_2x*, *cic\_xmt\_d6stg*, and *cic\_bypass* are the mode controls. The *cic\_rcv\_cross* is used to select the DDC input for the dual CIC in channels B and D.

Table 53, 54, 55, and 56 set the frequency register (delta phase) and phase (initial phase) values.

Table 57 is the mixer configuration, this sets the I and Q data source, and the cosine and sine multiplier selections. Table 58 is the mixer synchronization register.

**Table 52. CIC Mode Page 0x80 Address 0x10**

Rcv	Tx	FIELD	BITS	Dflt	DESCRIPTION
C	C	<i>cic_shift</i>	5..0		CIC is followed by a shifter by a shifter to compensate for CIC gain. $0 \leq \text{cic\_shift} \leq 39$ .
C	C	<i>cic_rcv</i>	7..6		CIC mode is quiet (0), receive (1), transmit (2), or illegal (3)
X	C	<i>cic_xmt_5stg</i>	8		CIC transmits five stages (1), rather than the normal six stages (0)
C	X	<i>cic_rshift</i>	9		Upshift 1 bit in receive mode after CIC filtering before rounding
C	C	<i>cic_2x</i>	10		Operate the CIC in double rate mode
X	C	<i>cic_xmt_d6stg</i>	11		Must be set for CIC in double rate and six stage, else clear
C	X	<i>cic_rcv_cross</i>	12		Use cross-strapped CIC inputs in receive. Set for <i>splitiq</i> mode
C	X	<i>cic_rcv_full</i>	13		Saturate CIC output at full scale (1) for nonsymmetrical FIR or half scale (0) for symmetric FIR. Only affects receive outputs.
C	C	<i>cic_bypass</i>	14		Bypass CIC in transmit (1), must also set <i>cic_shift</i> (39) and <i>ncic</i> (0). Clear in receive.
–	–	<i>cic_fl_status</i>	15		CIC flush status sticky bit. Chip sets if autoflushed. User must clear.

**Table 53. Phase Page 0x80 Address 0x11**

Rcv	Tx	FIELD	BITS	Dflt	DESCRIPTION
D	D	<i>phase</i>	15..0	0	Phase is $\text{phase}/2^{16}$ Hz

**Table 54. Frequency (LSB) Page 0x80 Address 0x12**

Rcv	Tx	FIELD	BITS	Dflt	DESCRIPTION
D	D	<i>freq_lsb</i>	15..0	0	Bottom 16 bits of frequency

**Table 55. Frequency (mid) Page 0x80 Address 0x13**

Rcv	Tx	FIELD	BITS	Dflt	DESCRIPTION
D	D	<i>freq_mid</i>	15..0	0	Middle 16 bits of frequency

**Table 56. Frequency (MSB) Page 0x80 Address 0x14**

Rcv	Tx	FIELD	BITS	Dflt	DESCRIPTION
M	M	<i>freq_msb</i>	15..0		Top 16 bits of frequency. Values in Table 54 through Table 56 may be set using the pseudo field <i>freq</i> .

**Table 57. Mixer Page 0x80 Address 0x15**

Rcv	Tx	FIELD	BITS	Dflt	DESCRIPTION
M	X	<i>mix_rcv_sel</i>	1..0		Mixer input selection in receive (paths a, b, c, or d for 0, 1, 2, or 3 respectively).
C	X	<i>mix_rcv_cmplx</i>	2		Set for receive complex input at full rate or double rate.
C	C	<i>mix_inv_qsin</i>	4		Invert the output of Qdata by sin in the mixer.
C	C	<i>mix_qsin</i>	6..5		Select data input to qsin multiplier as zero (0), receive (1), transmit cross-strapped (2), or transmit (3). Transmit cross-strapped is for transmit in <i>splitiq</i> or double rate modes.
C	C	<i>mix_inv_qcos</i>	7		Invert the output of Qdata by cos in the mixer.
C	C	<i>mix_qcos</i>	9..8		Select data input to qcos multiplier as zero (0), receive (1), transmit cross-strapped (2), or transmit (3). Transmit cross-strapped is for transmit in <i>splitiq</i> or double rate modes.
C	C	<i>mix_inv_isin</i>	10		Invert the output of Idata by sin in the mixer.
C	C	<i>mix_isin</i>	12..11		Select data input to isin multiplier as zero (0), receive (1), transmit cross-strapped (2), or transmit (3). Transmit cross-strapped is for transmit in <i>splitiq</i> or double rate modes.
C	C	<i>mix_inv_icos</i>	13		Invert the output of Idata by cos in the mixer.
C	C	<i>mix_icos</i>	15..14		Select data input to icos multiplier as zero (0), receive (1), transmit cross-strapped (2), or transmit (3). Transmit cross-strapped is for transmit in <i>splitiq</i> or double rate modes.

**Table 58. NCO Syncs Page 0x80 Address 0x16**

Rcv	Tx	FIELD	BITS	Dflt	DESCRIPTION
D	D	<i>freq_sync</i>	2..0	6	Sync source for frequency word update
D	D	<i>phase_sync</i>	5..3	6	Sync source for phase word update
D	D	<i>dith_sync</i>	8..6	0	Sync source for dither update. Typically set to never. Set to always to disable.
D	D	<i>nco_sync</i>	11..9	0	Sync source for nco word update. Disrupts signal processing when sync occurs
D	D	<i>flush_sync</i>	14..12	0	Sync source for cic flush. Disrupts signal processing when sync occurs.
D	D	<i>dith_test</i>	15	0	Experimental dither mode, set to 0.

**Table 59. CIC Count and Sync Page 0x80 Address 0x17**

Rcv	Tx	FIELD	BITS	Dflt	DESCRIPTION
C	C	<i>ncic</i>	11..0		CIC decimation / interpolation count minus one
D	D	<i>cic_sync</i>	14..12	2	Sync source for cic counter. suggested value matches the fir_sync setting

## 17.17 Transmit Sum Tree Registers

The Table 60 register variables select the sum tree logic selection. See Table 4, and figures 24 through 26.

**Table 60. Sum Tree Sum Selection Page 0x81 Address 0x10**

Rcv	Tx	FIELD	BITS	Dflt	DESCRIPTION
X	C	<i>sum_selI</i>	7..0		Selects inputs for I sum both A and B paths.
X	C	<i>sum_selQ</i>	15..8		Selects inputs for Q sum both A and B paths.

**Table 61. Sum Tree Multiplexing Page 0x81 Address 0x11**

Rcv	Tx	FIELD	BITS	Dflt	DESCRIPTION
X	C	<i>sum_shift</i>	2..0		Upshifts sum before output (0–7).
X	C	<i>sum_ia</i>	4..3		Summing mode off (0), 22 bit sumin (1), bypass (2), 16 bit sumin (3)
X	C	<i>sum_ib</i>	6..5		Summing mode off (0), 22 bit sumin (1), bypass (2), 16 bit sumin (3)
X	C	<i>sum_qa</i>	8..7		Summing mode off (0), 22 bit sumin (1), bypass (2), 16 bit sumin (3)
X	C	<i>sum_qb</i>	9		Summing mode normal (0), quiet (1)
X	C	<i>sum_in</i>	11..10		Sum in mode off (0), IQ multiplexed (1), 16 bit (2), 22 bit (3)
–	–	<i>sum_of_la</i>	12		Sum tree overflow sticky status bit for Ia
–	–	<i>sum_of_lb</i>	13		Sum tree overflow sticky status bit for Ib
–	–	<i>sum_of_Qa</i>	14		Sum tree overflow sticky status bit for Qa
–	–	<i>sum_of_Qb</i>	15		Sum tree overflow sticky status bit for Qb

## 17.18 Receive Sensitivity Registers

The Tables 62, 63, 64, and 65 are used to add bit-wise controlled noise to the DDC input path. Normally these bits are 0, setting a bit to '1' adds the Receive LFSR noise generator data to the DDC input data bit.

**Table 62. Receive Sensitivity Reduction Path A Page 0x81 Address 0x12**

Rcv	Tx	FIELD	BITS	Dflt	DESCRIPTION
D	X	<i>rcv_noise_A</i>	15..0	0	Adds noise to input A to desensitize the digital down converters. Must also release pn generator sync and set test mode to random.

**Table 63. Receive Sensitivity Reduction Path B Page 0x81 Address 0x13**

Rcv	Tx	FIELD	BITS	Dflt	DESCRIPTION
D	X	<i>rcv_noise_B</i>	15..0	0	Adds noise to input B to desensitize the digital down converters. Must also release pn generator sync and set test mode to random.

**Table 64. Receive Sensitivity Reduction Path C Page 0x81 Address 0x14**

Rcv	Tx	FIELD	BITS	Dflt	DESCRIPTION
D	X	<i>rcv_noise_C</i>	15..0	0	Adds noise to input C to desensitize the digital down converters. Must also release pn generator sync and set test mode to random.

**Table 65. Receive Sensitivity Reduction Path D Page 0x81 Address 0x15**

Rcv	Tx	FIELD	BITS	Dflt	DESCRIPTION
D	X	<i>rcv_noise_D</i>	15..0	0	Adds noise to input D to desensitize the digital down converters. Must also release pn generator sync and set test mode to random.

## 17.19 Receive Input Formatter

The Table 66 values select the complex output bus for each of the 4 DDC channels.

**Table 66. Receive Input Formatter Page 0xa1 Address 0x10**

Rcv	Tx	FIELD	BITS	Dflt	DESCRIPTION
C	X	<i>rinf_sel_A</i>	3..0		Receive input formatting. Normal usage quiet (0), Q part of nonmultiplexed complex (1), IQ multiplexed (3), real or real portion of nonmultiplexed complex (4), and test (8). Detailed settings are quiet (0), input to Q (1), input delayed by 1 to I (2), input to I (4), and test to both I and Q (8).
C	X	<i>rinf_sel_B</i>	7..4		Same as above, but for path B
C	X	<i>rinf_sel_C</i>	11..8		Same as above, but for path C
C	X	<i>rinf_sel_D</i>	15..12		Same as above, but for path D

## 17.20 General Timer

**Table 67. General Timer Page 0xA1 Address 0x11**

Rcv	Tx	FIELD	BITS	Dflt	DESCRIPTION
D	D	<i>gen_timer</i>	15..0	65535	General-purpose timer. A 24-bit counter. The bottom eight bits of the count value are normally assumed to be zero. Timer counts down from 256 x ( <i>gen_timer</i> + 1) to zero, then repeats. The timer starts over with every sync, provides ramp data for receive testing, and outputs a pulse at restart plus five clocks.

**Table 68. Receive Syncs Page 0xA1 Address 0x12**

Rcv	Tx	FIELD	BITS	Dflt	DESCRIPTION
D	X	<i>rinf_zpad</i>	3..0	0	Receive input formatter zero pad count. Effectively interpolates by ( <i>rinf_zpad</i> +1) up to the CK rate.
D	X	<i>rinf_diag</i>	5..4	0	Receive diagnostic test pattern ramp (0), 0 (1), random (2), constant 0x4000 (3).
D	D	<i>gen_timer_test</i>	6	0	Shorten <i>gen_timer</i> for test (1) (bottom 8 bits are forced high). Normally 0.
D	D	<i>gen_timer_sync</i>	9..7	7	Sync control for general timer
D	D	<i>cksum_sync_front</i>	12..10	7	Sync control for receive input pattern generator and transmit check sum.
D	X	<i>rinf_zpad_sync</i>	15..13	7	Sync control for receive zero padding

## 17.21 Transmit Output

**Table 69. Transmit Output Multiplexing Page 0xA1 Address 0x13**

Rcv	Tx	FIELD	Bits	Dflt	Description
X	D	<i>toutf_hold_sync</i>	2..0	7	Sync control for transmit output hold
X	C	<i>toutf_do</i>	8..4		Transmit output format control for DO. quiet (0), id (1), qb (2), ib LSB's (4), qa LSB's (8), CO complement (16). Others illegal.
X	C	<i>toutf_co</i>	11..9		Transmit output format control for CO. quiet (0), ic (1), ib (2), qa (4).
X	C	<i>toutf_bo</i>	15..12		Transmit output format control for BO. quiet (0), ib (1), qa (2), LSB of ia (4), or AO complement (8).

**Table 70. Transmit Output Round and Hold Page 0xA1 Address 0x14**

Rcv	Tx	FIELD	BITS	Dflt	DESCRIPTION
X	C	<i>toutf_rnd_AB</i>	1..0		Round transmit outputs AO, and BO to 16 (1), 14 (2), 12 (3) bits, or no round (0).
X	D	<i>toutf_offsetbin</i>	3	0	Offset binary format (1) or two's complement (0). Common to all transmit outputs.
X	C	<i>toutf_halfcmplx_AB</i>	4		Time multiplex IQ data by decimating by two at output.
X	D	<i>toutf_hold</i>	7..5	0	Hold output for <i>toutf_hold</i> +1 clocks – effectively decimating the signal.
X	C	<i>toutf_rnd_CD</i>	9..8		Round transmit outputs for CO and DO to 16 (1), 14 (2), 12 (3), bits or no round (0).
X	C	<i>toutf_quiet_CD</i>	10		Quiet CD path (1) when unused.
X	C	<i>toutf_halfcmplx_CD</i>	11		Time multiplex IQ for channels C and D.
E	C	<i>toutf_xmt_CD</i>	12		Channels C and D setup in transmit (1) or receive (0).
X	C	<i>toutf_sumin</i>	13		CO and DO setup as inputs for <i>sumin</i> (1), or outputs (0).
E	C	<i>toutf_xmt_AB</i>	14		Channels A and B setup in transmit (1) or receive (0).

**Table 71. Transmit Checksum Page 0xA1 Address 0x15**

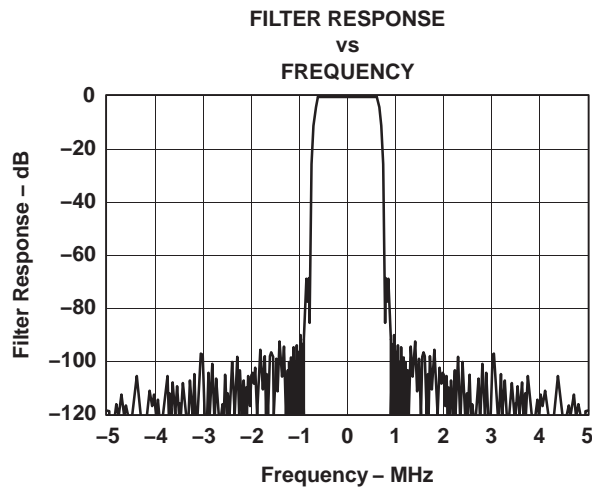
Rcv	Tx	FIELD	BITS	Dflt	DESCRIPTION
–	–	<i>transmit_cksum</i>	15..0		Checksum results for transmit (read only)



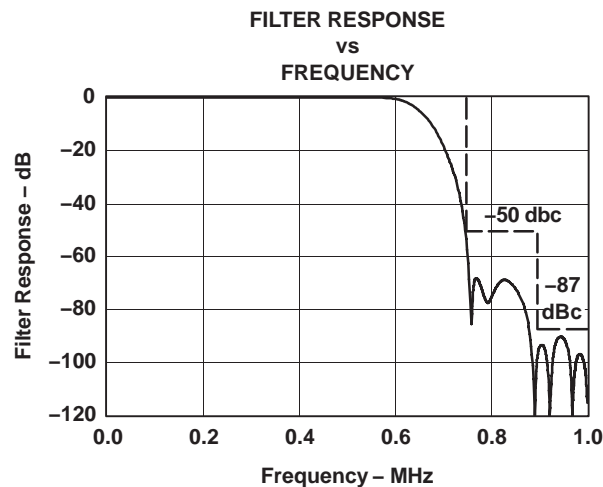
## 18 5016 – CONFIGURATION SOFTWARE

### 18.1 CDMA2000

This section describes an example of the down-conversion filter response for CDMA2000 1X. The GC5016 configuration values were input sample rate of 78.643 MSPS, CIC decimation of eight, and PFIR decimation of four for an overall decimation of 32, output rate of 2.4576 MSPS (2x chip rate), and 255 PFIR taps. The overall filter response, including both the CIC and PFIR filters, is shown in Figure 33 and Figure 34. As seen in Figure 34 of the transition region, the filter response meets the CDMA2000 1X stop-band rejection requirements of  $-50$  dB at 750 kHz and  $-87$  dB at 900 kHz.



**Figure 33. CDMA2000 1X Filter Response**

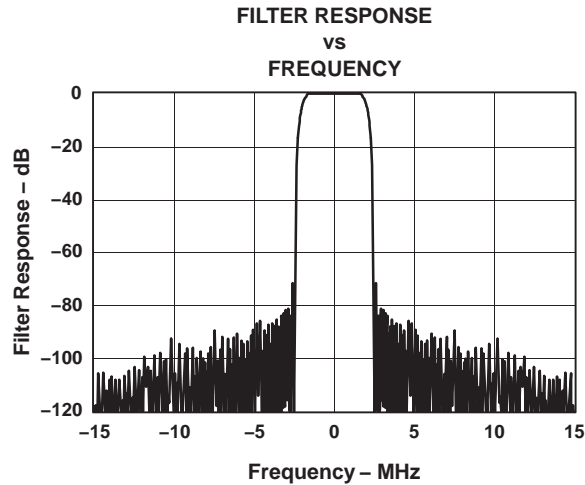


**Figure 34. CDMA2000 1X Filter Response Transition Region with Spectral Mask**

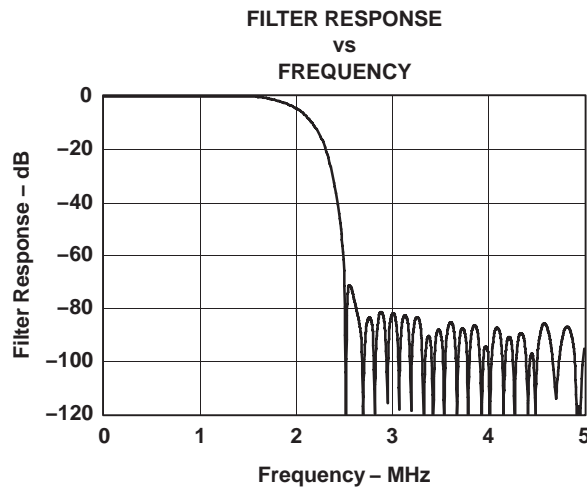
In transmit the input is presumed to operate at one sample per chip (1.2288 MHz), the PFIR interpolates by four and uses a 192 tap filter that applies the phase predistortion, pulse shaping, adjacent channel rejection, and CIC roll-off compensation. This is followed by a six stage CIC filter. The cmd5016 configuration file and filter taps are available on the web.

## 18.2 WCDMA (UMTS)

This section describes an example of the down-conversion filter response for WCDMA. The GC5016 configuration values were input sample rate of 122.88 MHz, a CIC and PFIR decimation of four each for an overall decimation of 16, output rate of 7.68 MSPS, and 255 PFIR taps. The overall filter response filter, including both the CIC and PFIR filters, an optimized raised cosine filter with  $\alpha = 0.22$ , is shown in Figure 35 and Figure 36. The stop-band attenuation is better than  $-80$  dBc for frequencies more than 2.5 MHz from the band center.



**Figure 35. UMTS Filter Response**



**Figure 36. UMTS Filter Response Transition Region**

The cmd5016 configuration file and filter taps are available on the web.

**APPLICATION INFORMATION**

**19 BOARD BRING-UP PROCEDURE**

This section describes a recommended procedure for checkout of a board using the GC5016. The various test files are available on the website.

**19.1 JTAG**

The 1.8-Vdc VCore and 3.3-Vdc VPad should be within nominal values before using the JTAG or the Control Bus. The TRST JTAG signal is a logic '1' for JTAG testing. The TRST JTAG signal is a logic '0' for nominal operation. The TRST signal forces the JTAG Tap Controller to be in an idle state when the signal is logic '0'.

If JTAG is not used, the TRST signal should be tied to GND.

**19.1.1 Basic Control Path**

Write reset value (0xFFFF) to register 0. Read back to see 0xFFFF[C–F]. The bottom two bits are status bits and can be any value. Write and read the page register (address 0x2). The lower byte should be just what you write in. The upper byte should read back the revision (currently 1), regardless of what was written. If possible, use a scope to capture the event so you can confirm setup/hold, output delay, strobe pulse width, voltage levels, and signal integrity.

**19.1.2 Thorough Control Path Test**

Use the control\_check.gc101 script to read and write every control register and coefficient RAM in the chip with all 0's, 1's, 5's and A's and it then tests to see that the proper results are returned. Two commands are used (dwr16 and dcm16) as shown in the following table:

dwr16 address data	Write to the chip (both address and data are in hex)
dcm16 address mask <i>expected_data</i>	Reads from the chip, masks the results, and checks against the expected data.

The user software should accumulate errors as miscompared values. The control path test should have no errors.

The files are contained in the GC5016 *Diagnostic Configuration File* on the TI Web site at www.ti.com.

**19.1.3 Built-in Self-test**

These built-in self-tests provide the chip with input data using an internal pattern generator, an internal sync using the general timer in the chip, and analyzes the output using a checksum generator. These tests depend on the board to provide a solid control path, good clock, and good power. They generally work by setting the chip into a particular mode, then running the patterns (typically for at least four million clocks), then reading out the checksum result. Four checksum configurations are provided to provide good coverage of chip internals. If possible, use a scope to check the quality of the clock, power, and ground. Table 72 provides the addresses to find the resultant checksums.

**Table 72. Checksum Addresses**

	Transmit	Receive Channel A	Receive Channel B	Receive Channel C	Receive Channel D
Page	0xA1	0x13	0x33	0x53	0x73
Address	0x15	0x1F	0x1F	0x1F	0x1F

The user should configure the chip as specified in the configuration file, wait the recommended time, and then read the checksum results and compare them to the expected results shown in Table 73.

**Table 73. Expected Checksum Results**

Configuration Name	Wait Time (in clocks)	Expected Results				
		Transmit	Chan A	Chan B	Chan C	Chan D
TCK10R0.GC101	4,000,000	0x121D	–	–	–	–
TCK100R0.GC101	4,000,000	0x61EF	–	–	–	–
RCK100R0.GC101	4,000,000	–	0x64CF	0x4747	0x7BD9	0x4747
TRCK100R0.GC101	4,000,000	0x15C8	–	–	0x7BD9	0xE1CB

The files are contained in the GC5016 *Diagnostic Configuration File* on the TI Web site at [www.ti.com](http://www.ti.com).

#### 19.1.4 Output Test Configuration

In these tests the chip is setup using the internal pattern generator to provide a simple sin wave output regardless of the input. There is a transmit configuration (tsin\_r0) and a receive configuration (rsin\_r0). The transmit configuration outputs a single real tone on each of the four output ports (AO, BO, CO, and DO) at a rate of one new sample for each clock. The frequencies are 0.0633, 0.0711, 0.1297, and 0.1378 respectively. The receive configuration outputs one complex tone on each port as I followed by Q followed by 14 zeros. The four frequencies are 0.0249, 0.0498, 0.0996, and 0.1992 (of F<sub>sout</sub>). In both cases, SO can be used to synchronize the capture of the output if desired - its period is 2<sup>20</sup> clocks. The frequencies have been chosen so that the output is also periodic in 2<sup>20</sup> to avoid glitches at the repetition point. While the output is periodic in a general sense, it is not digitally precise periodic due to dithering of the NCO. Use a scope to check that output data from GC5016 provides sufficient setup and hold and signal integrity for the receiving device.

The files rsin\_r0 and tsin\_r0 are contained in the GC5016 *Diagnostic Configuration File* on the TI Web site at [www.ti.com](http://www.ti.com).

#### 19.1.5 Input Test Configuration

In this configuration (rby\_r0), the chip output is the same as the chip input, only delayed by 50 cycles. This test can be used to be sure that the input is read properly by the GC5016. Use a scope to check that input setup and hold times are met and that the signal doesn't have excessive ringing.

**PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
GC5016-PB	ACTIVE	BGA	GDJ	252	90	TBD	Call TI	Level-3-220C-168 HR
GC5016-PBZ	ACTIVE	BGA	ZDJ	252	90	Pb-Free (RoHS)	SNAGCU	Level-3-260C-168 HR

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSELETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

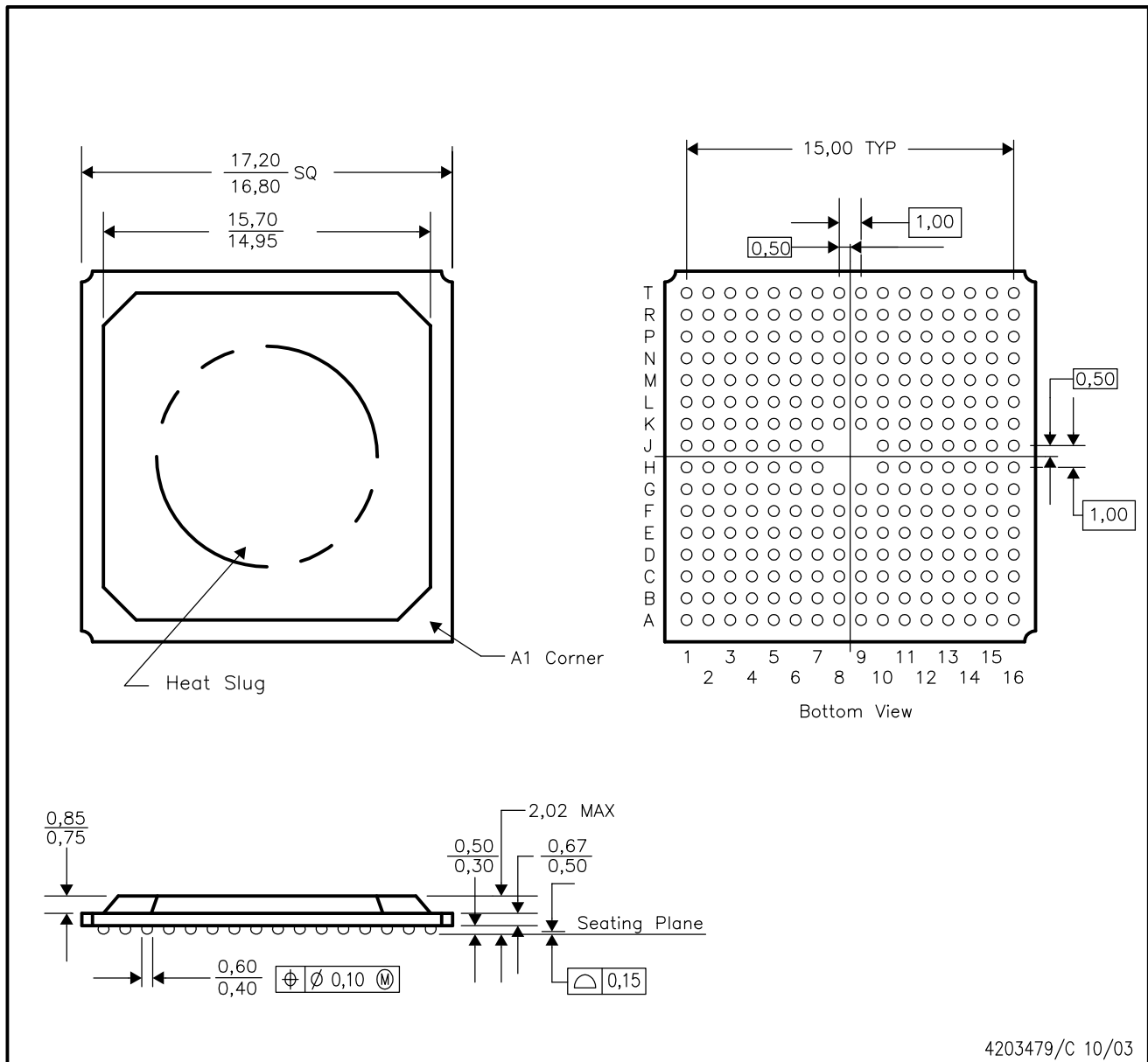
<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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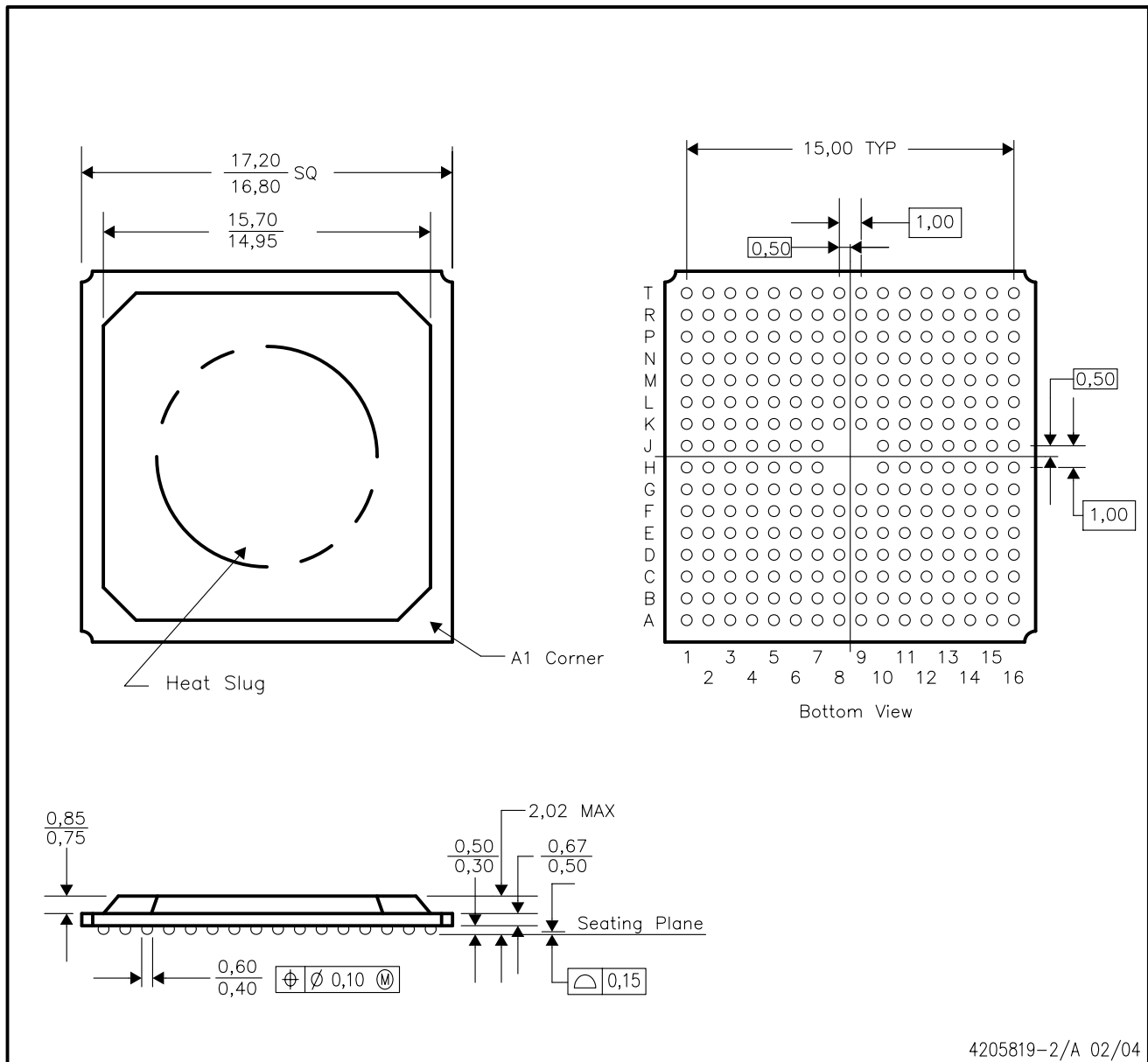
GDJ (S-PBGA-N252)

PLASTIC BALL GRID ARRAY



ZDJ (S-PBGA-N252)

PLASTIC BALL GRID ARRAY



4205819-2/A 02/04

- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Thermally enhanced plastic package with heat slug (HSL).
  - D. This package is lead-free.

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